# Latitude3000 Schematic Haswell-ULT

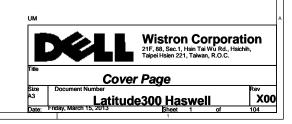
2013-3-15

**REV: X00** 

DY : None Installed

UMA: UMA only installed

OPS: DISCRTE OPTIMUS installed



Project code: 91.46001.001

PCB P/N : 13221-SA

Revision: X00

## Latitude3000 Block Diagram

CHARGER BQ24717

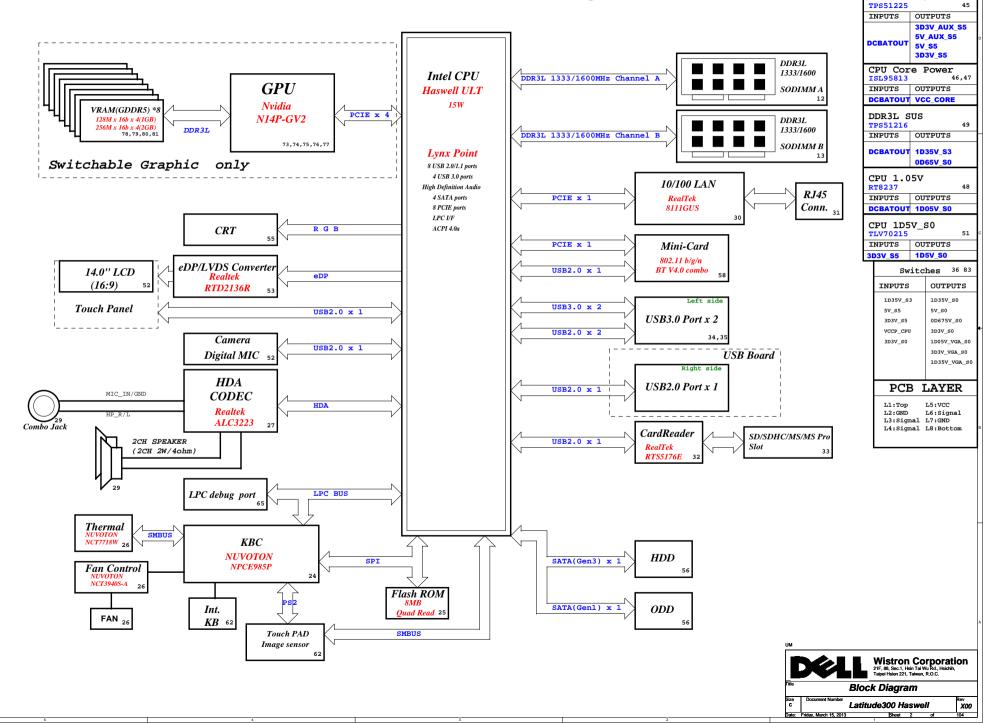
SYSTEM DC/DC

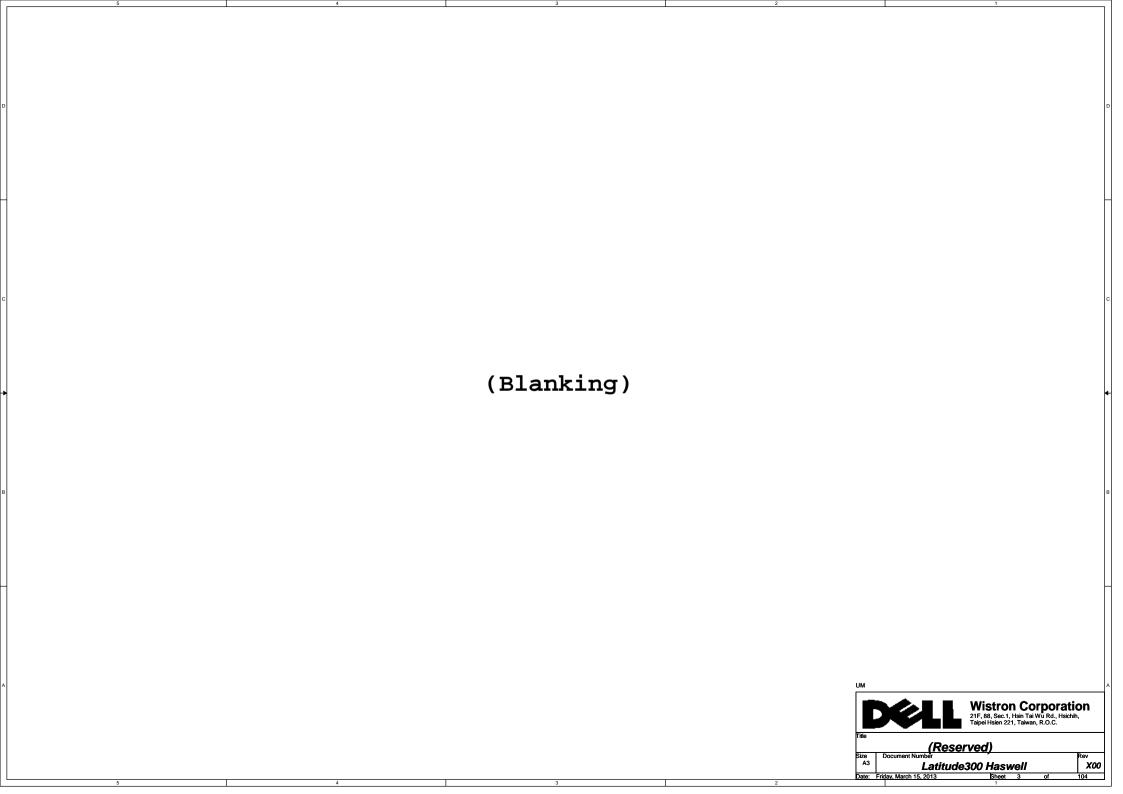
INPUTS

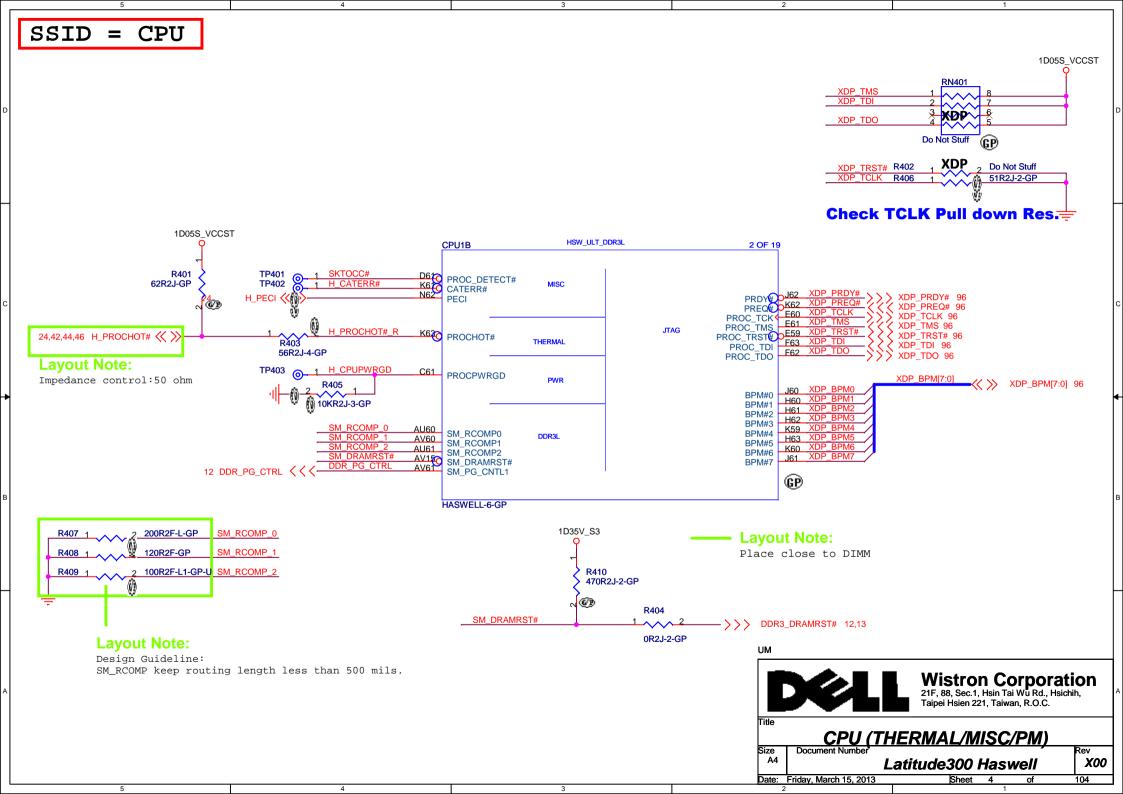
RT+

OUTPUTS

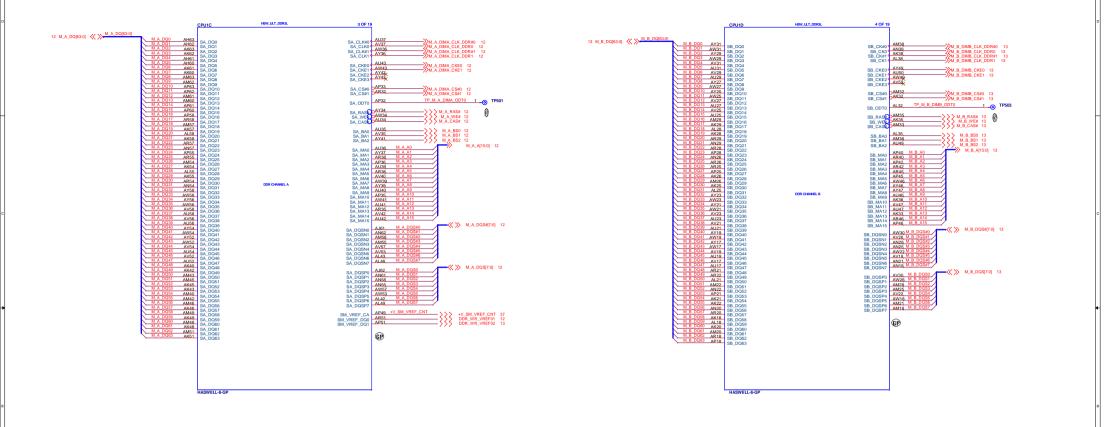
**DCBATOUT** 



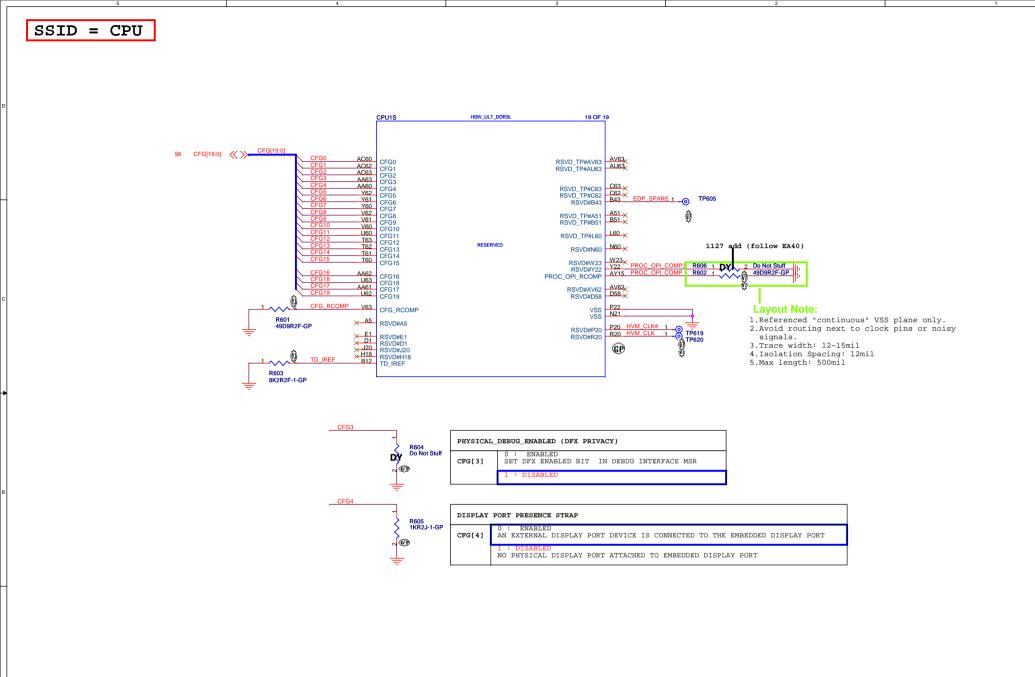


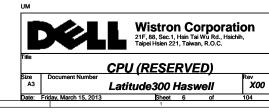


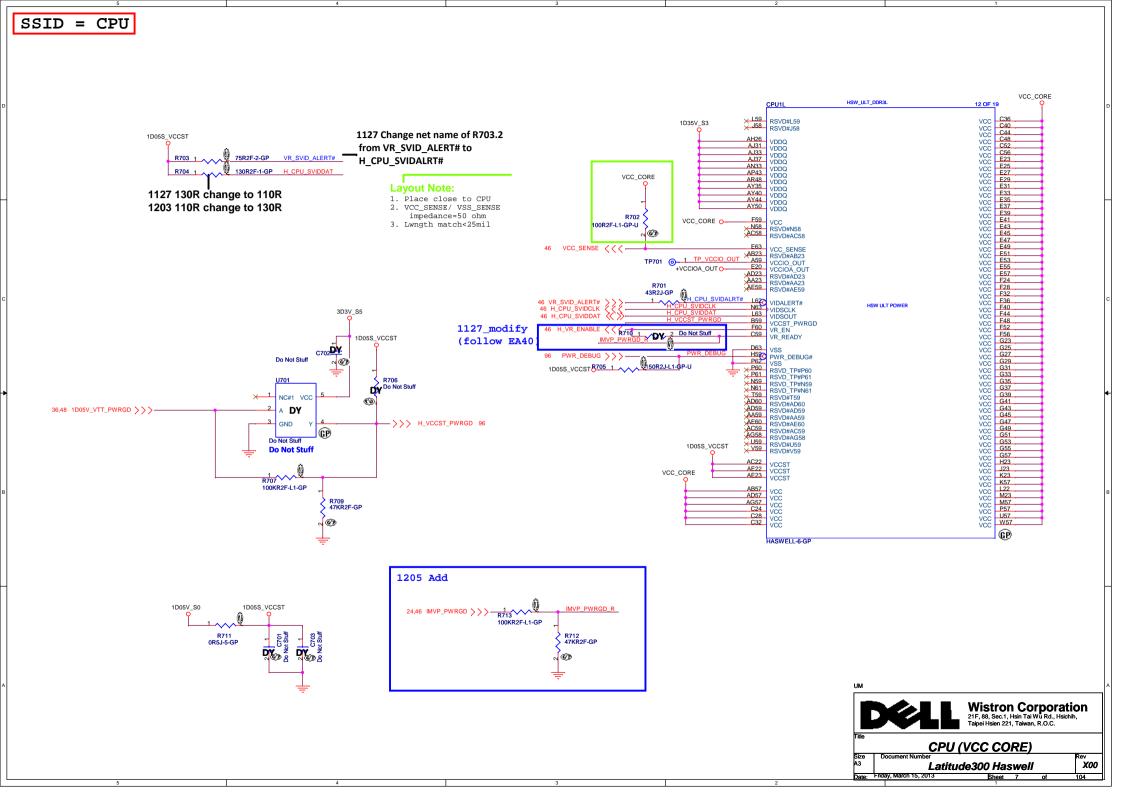
SSID = CPU

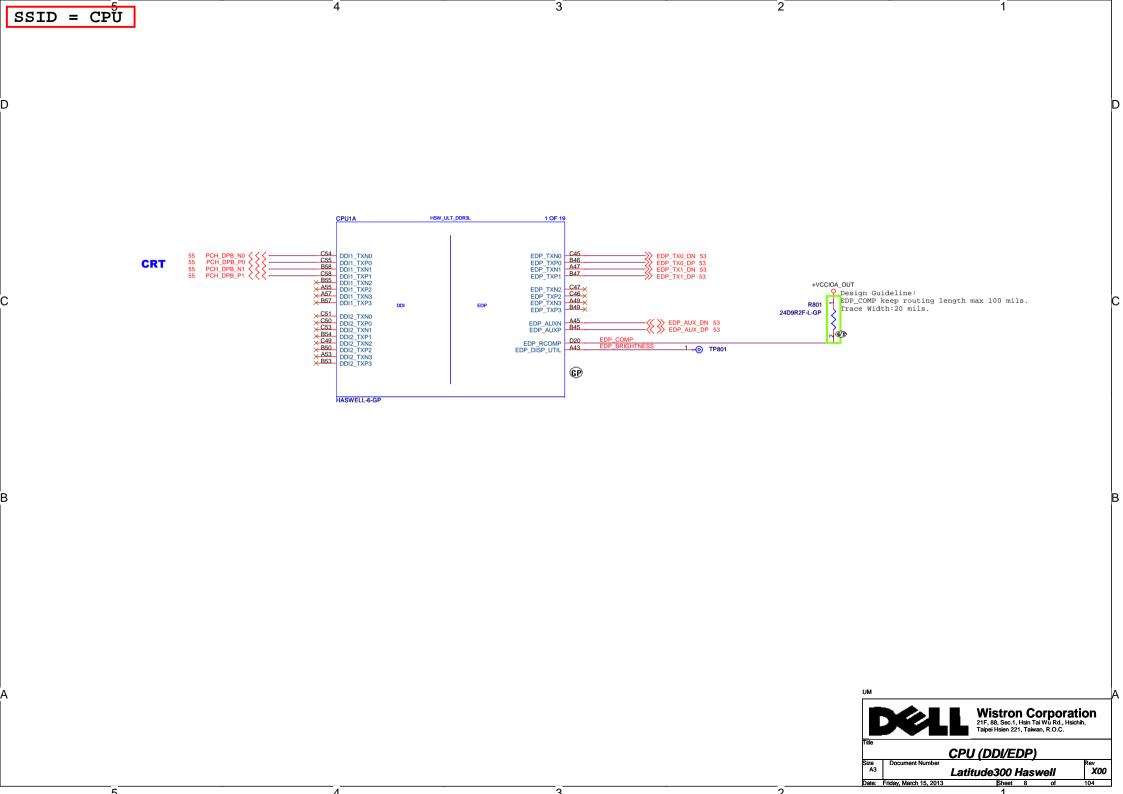


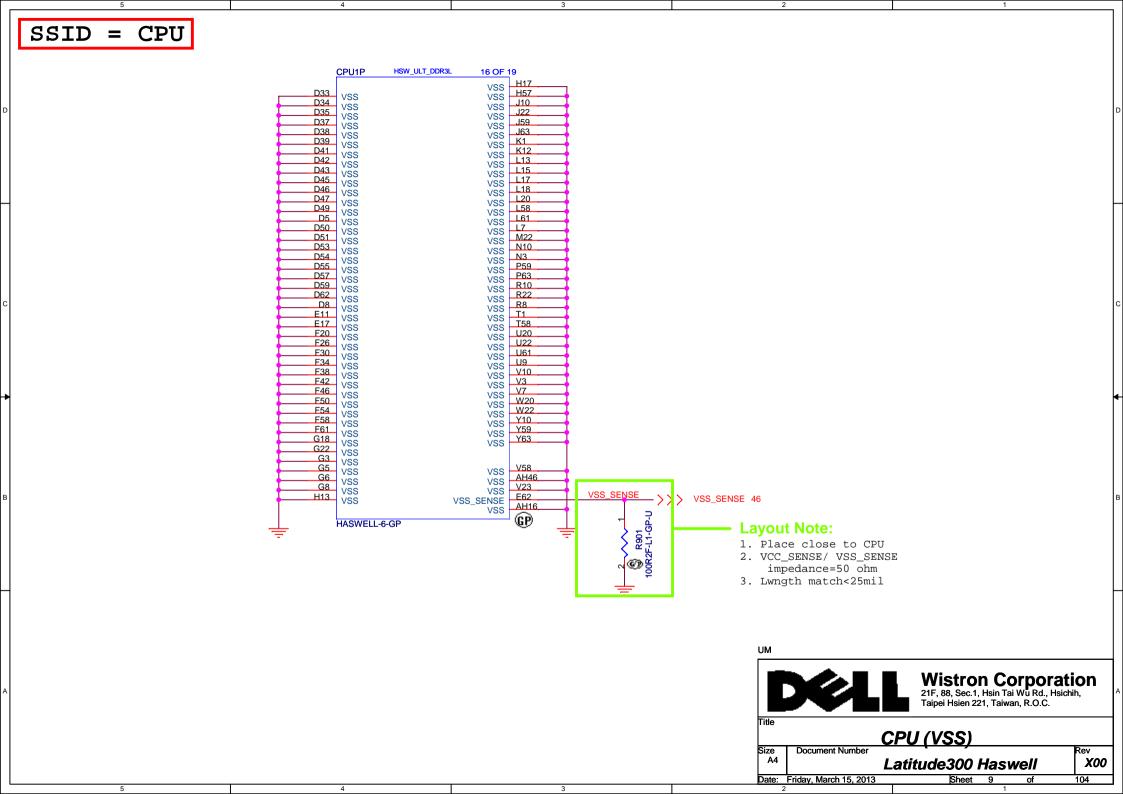


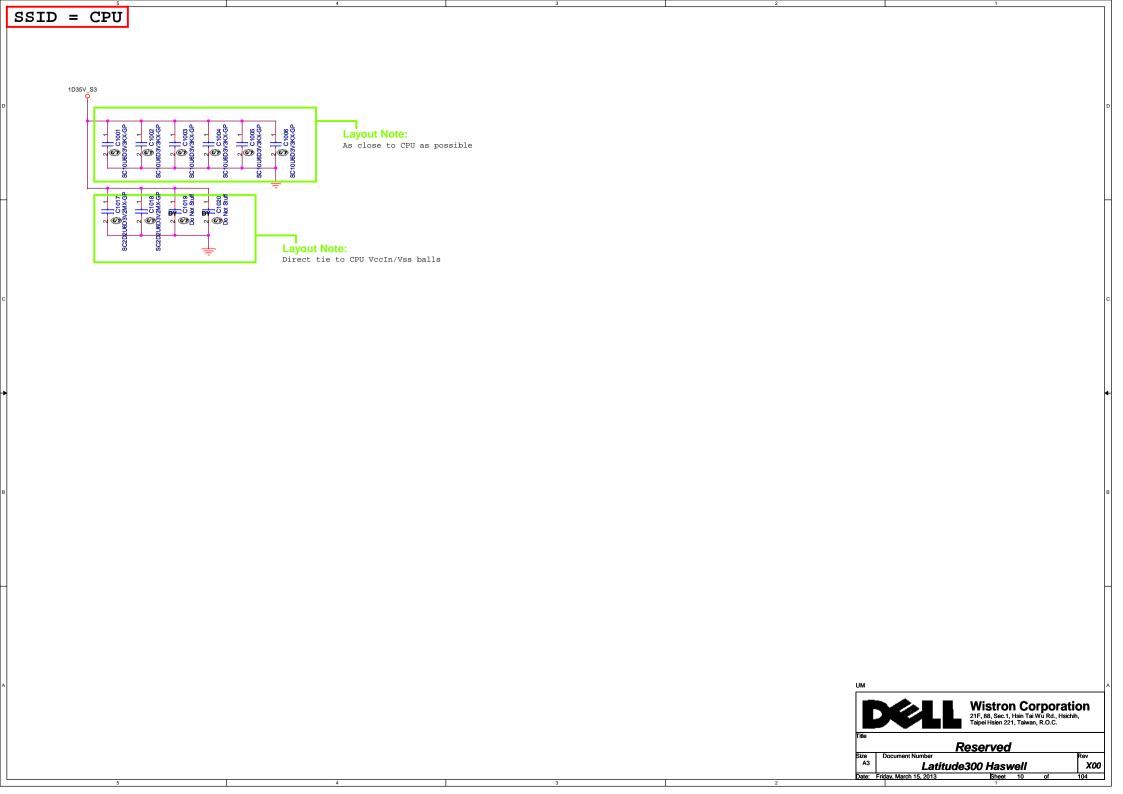


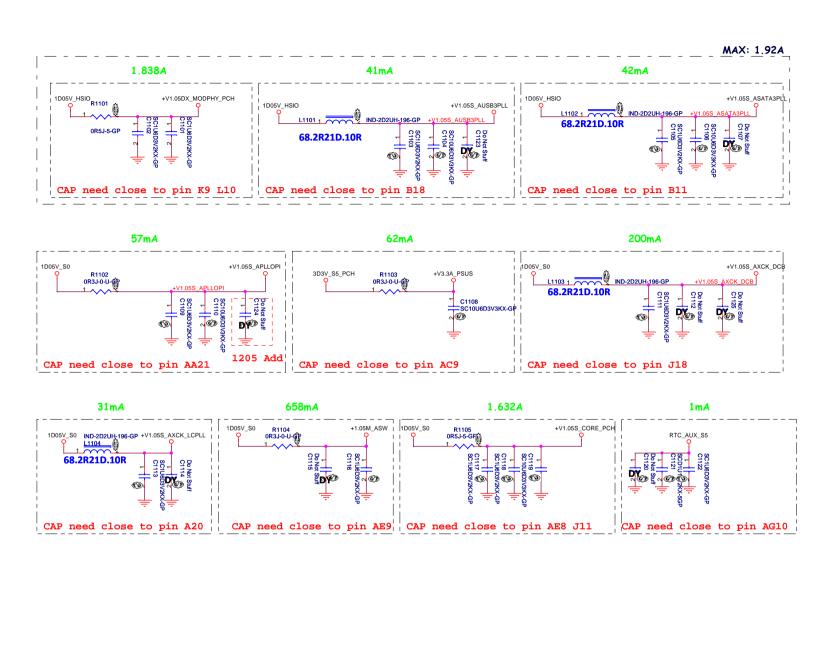


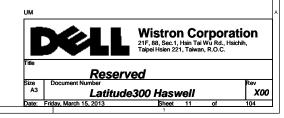


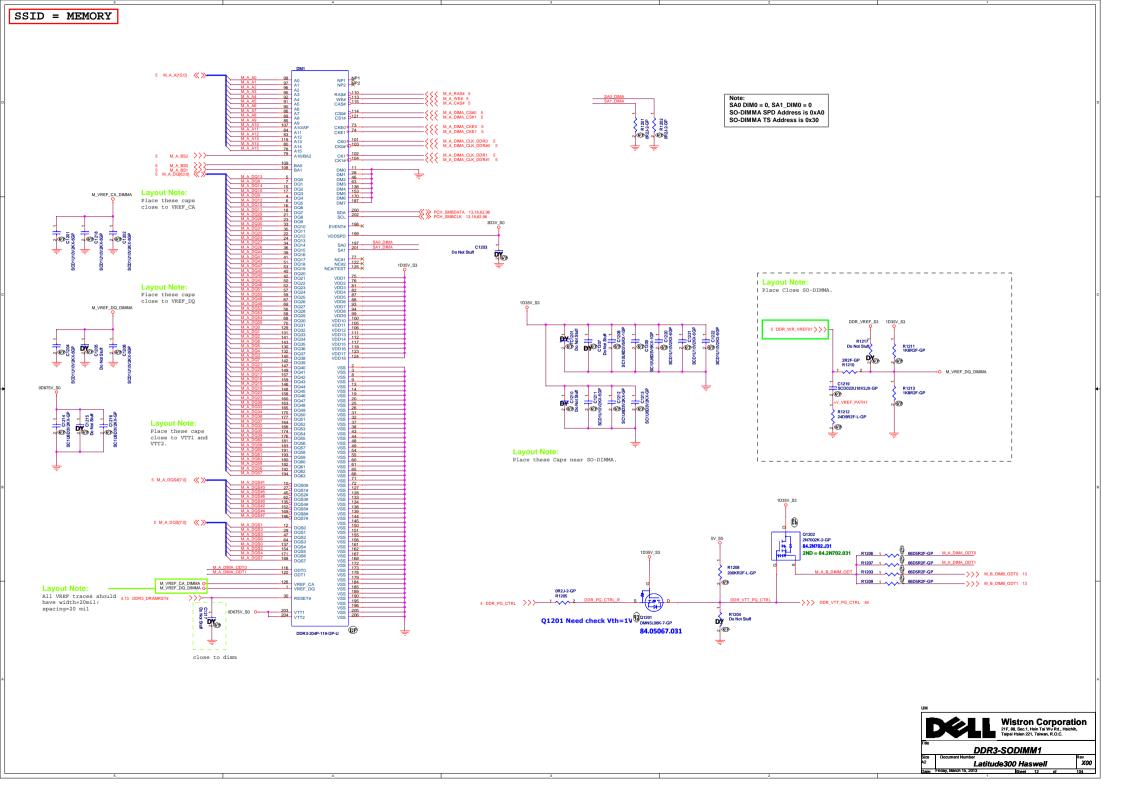


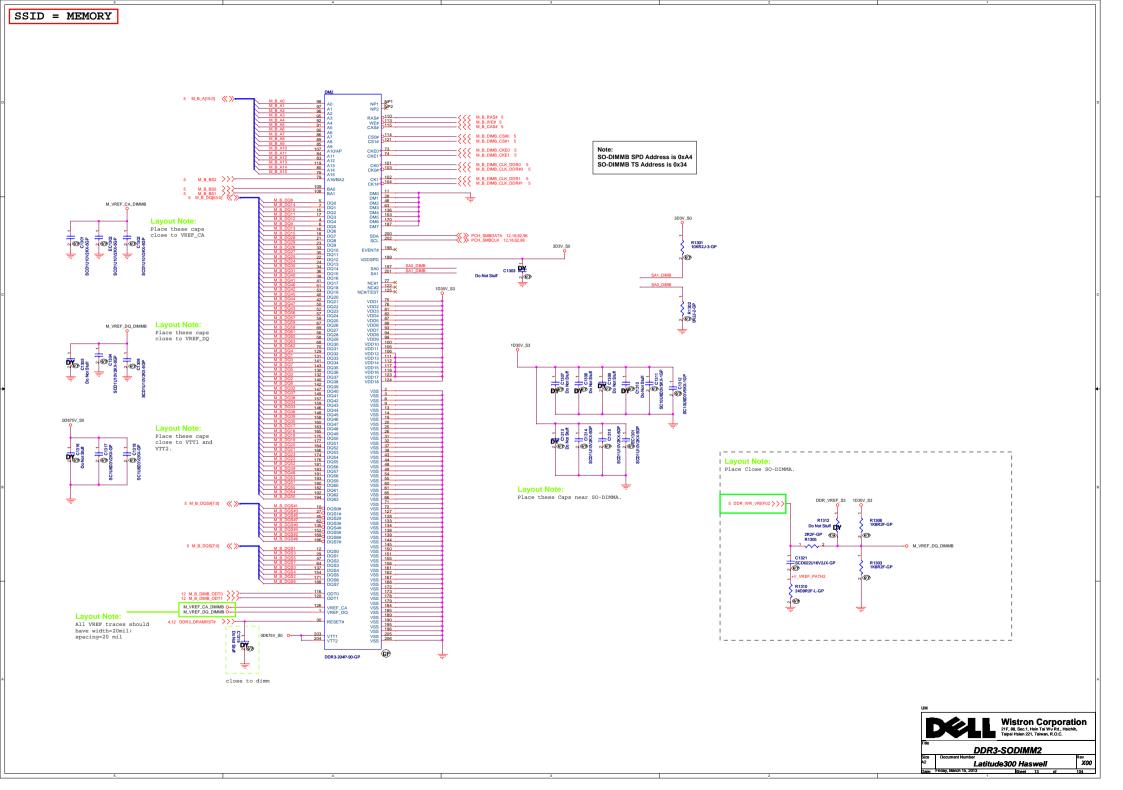


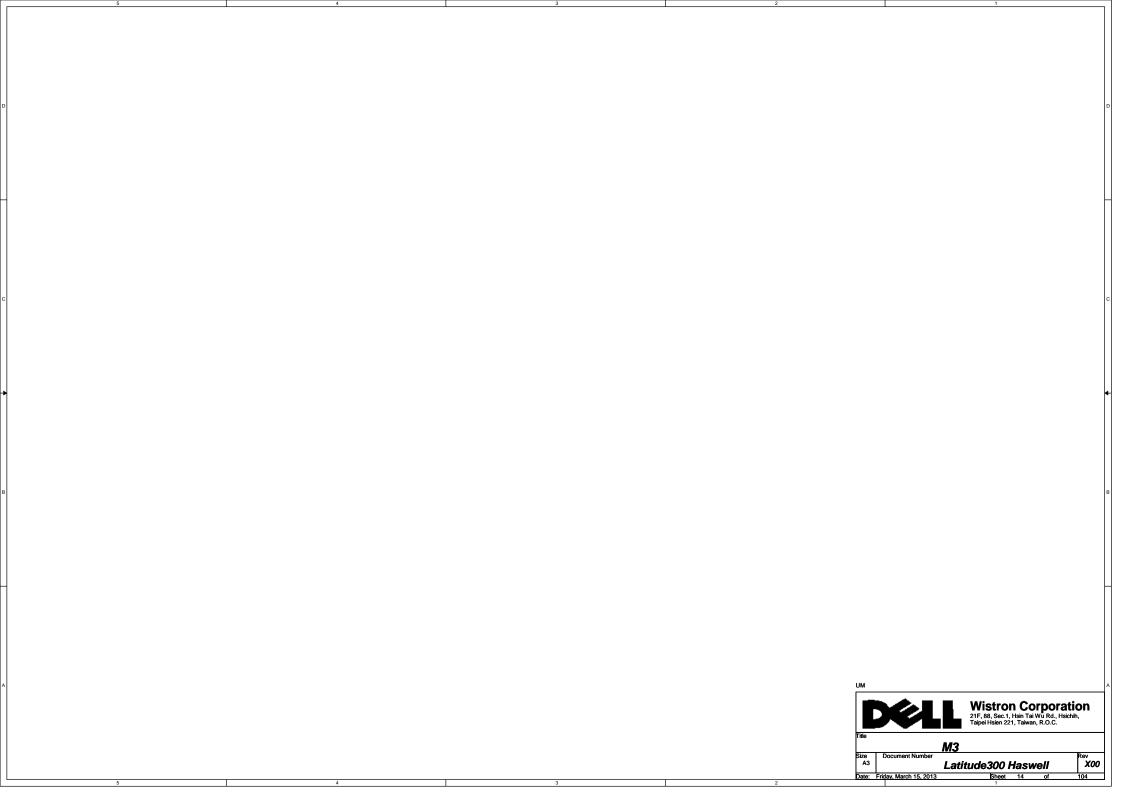


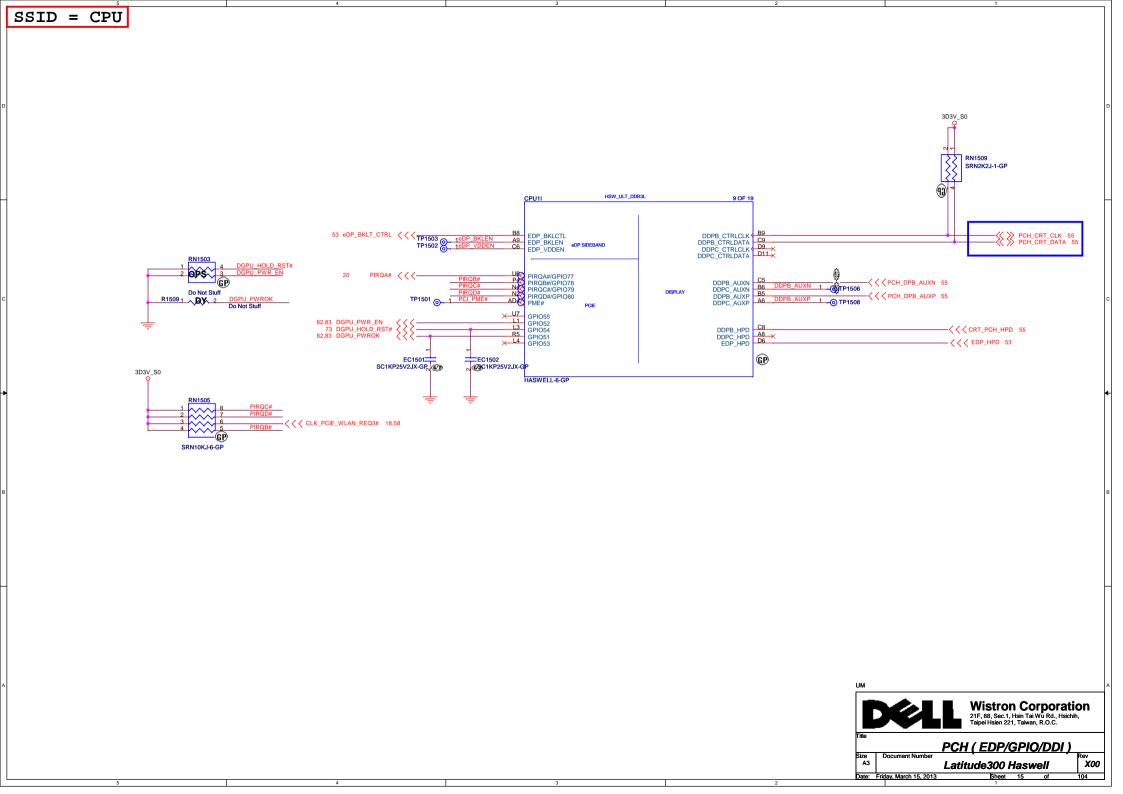












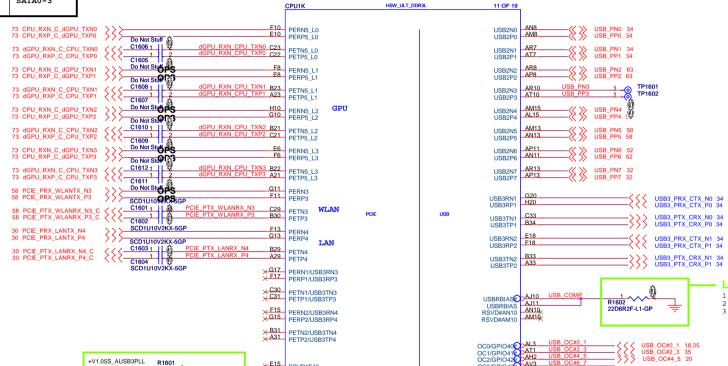
# SSID = PCH

#### **PCIE Table**

Port	Device	Share BUS
1	TBD	USB3.0_3
2	TBD	USB3.0_4
3	WLAN	
4	LAN	
5(41ane)	GPU	
6(4lane)	TBD	SATA0~3

#### **USB 2.0 Table**

002 2.0 1000		
Pair	Device	
0	USB3.0 port1	
1	USB3.0 Port2	
2	USB2.0 Port3	
3	TBD	
4	CAMERA	
5	WLAN	
6	Touch Panel	
7	Card Reader	



OC3/GPIO43#

(GP)

- 1. USB\_COMP using 50 ohm single-ended impedance
- 2. Isolation Spacing :15mil
- 3. Total trace length<500mil

**Layout Note:** 

1. PCIE\_RCOMP/ PCIE\_IREF trace width=12~15mil

PCIE\_RCOMP

A27 PCIE\_RCOMP PCIE\_IREF

HASWELL-6-GP

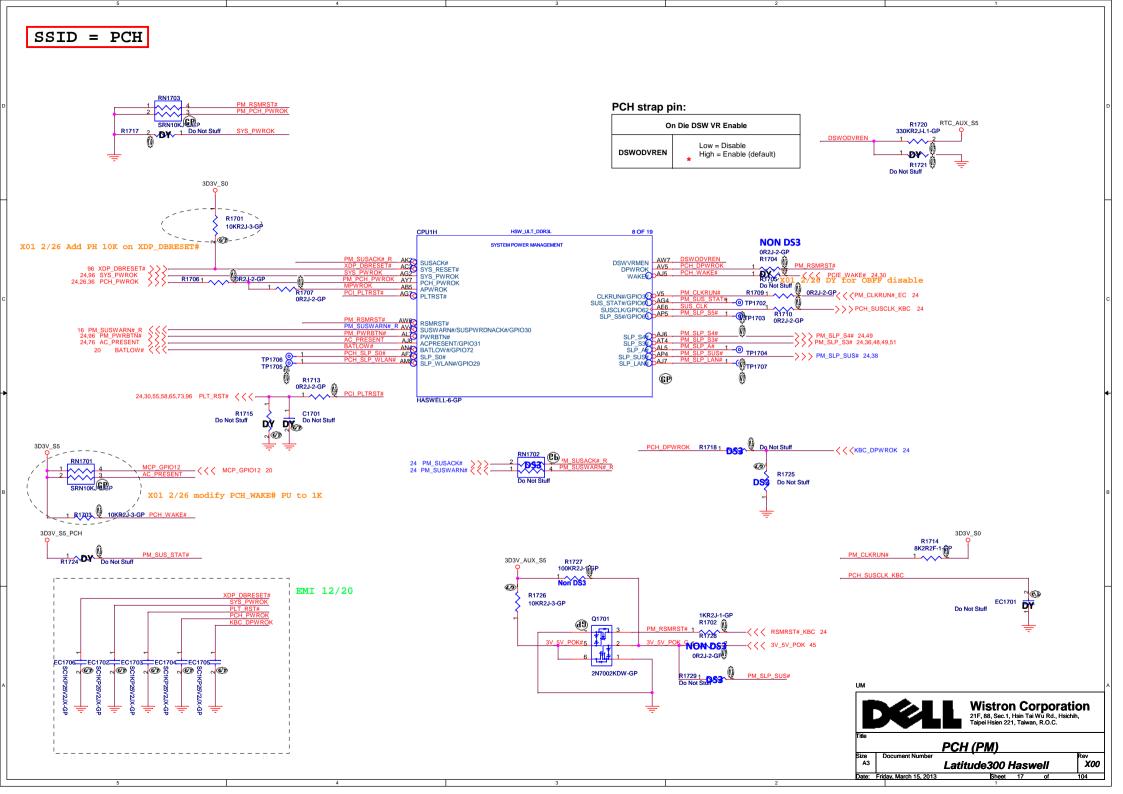
2. Isolation Spacing: 12mil

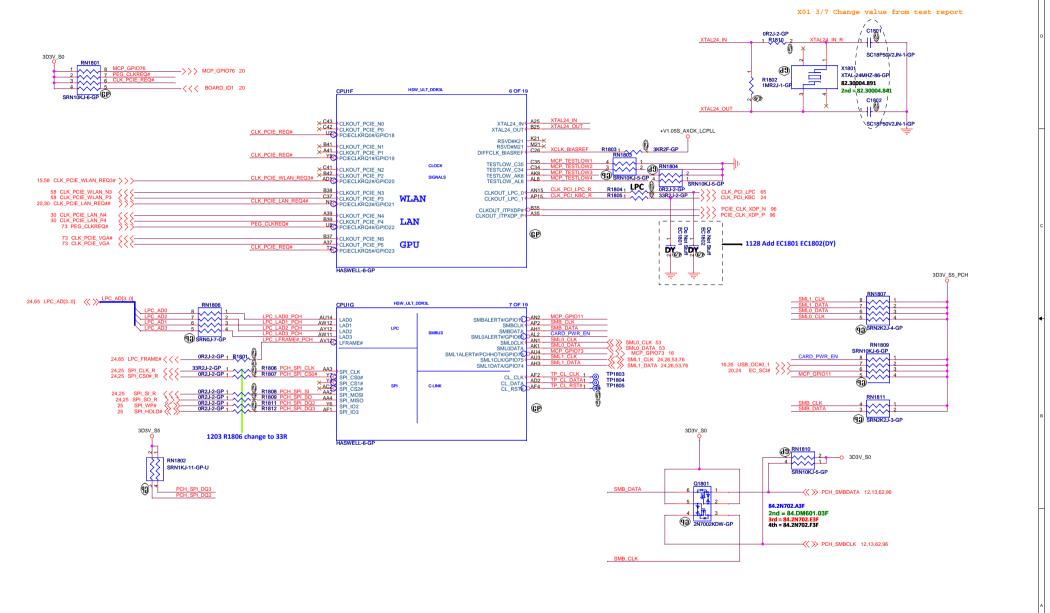
3KR2F-GP

3. Total trace length<500mil

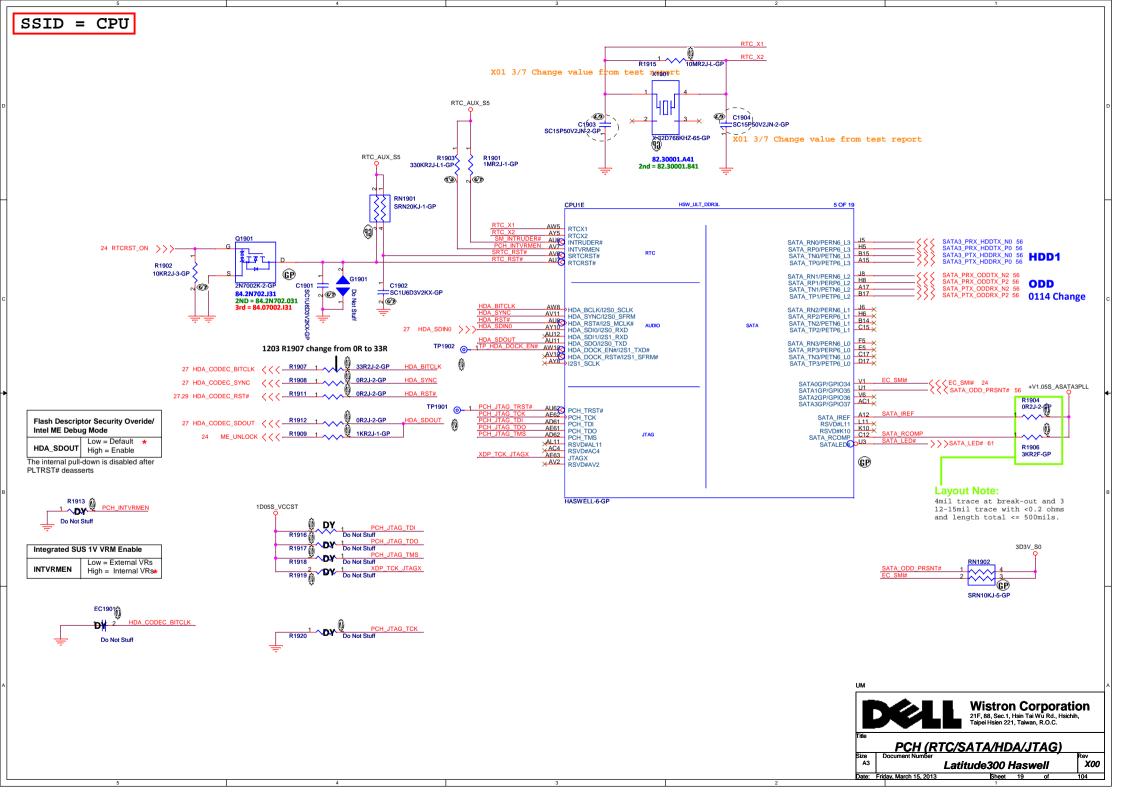


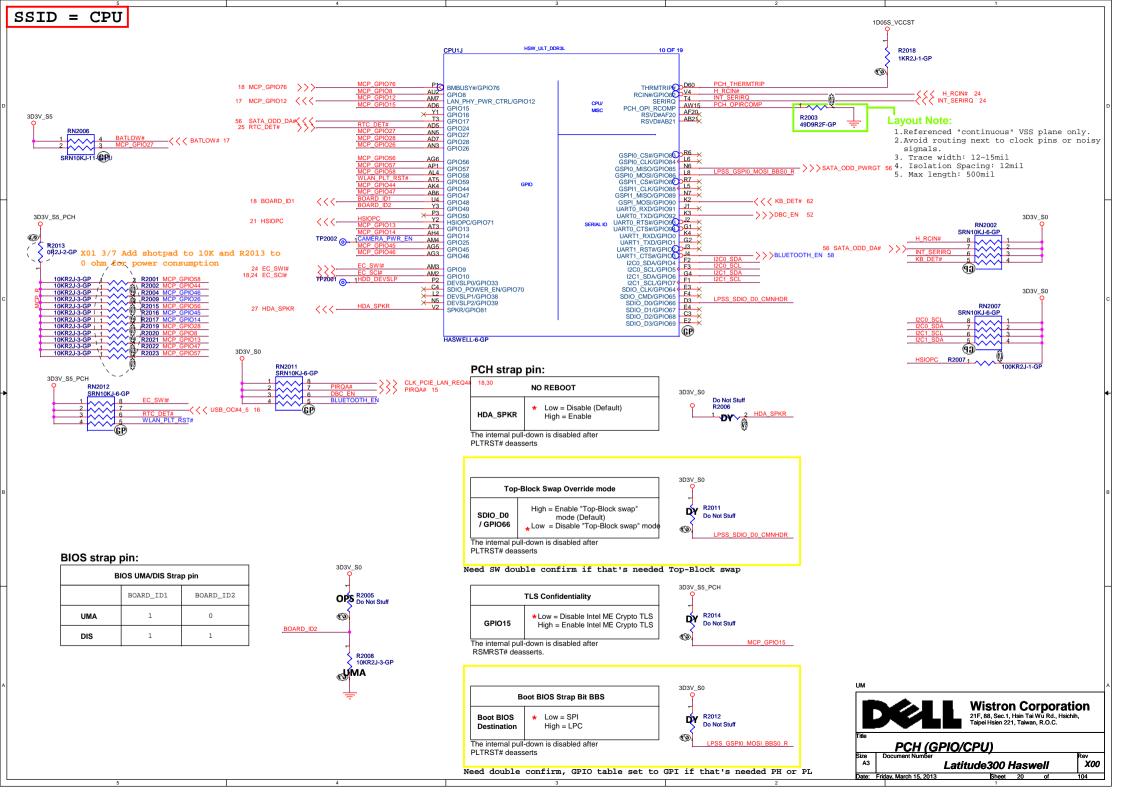


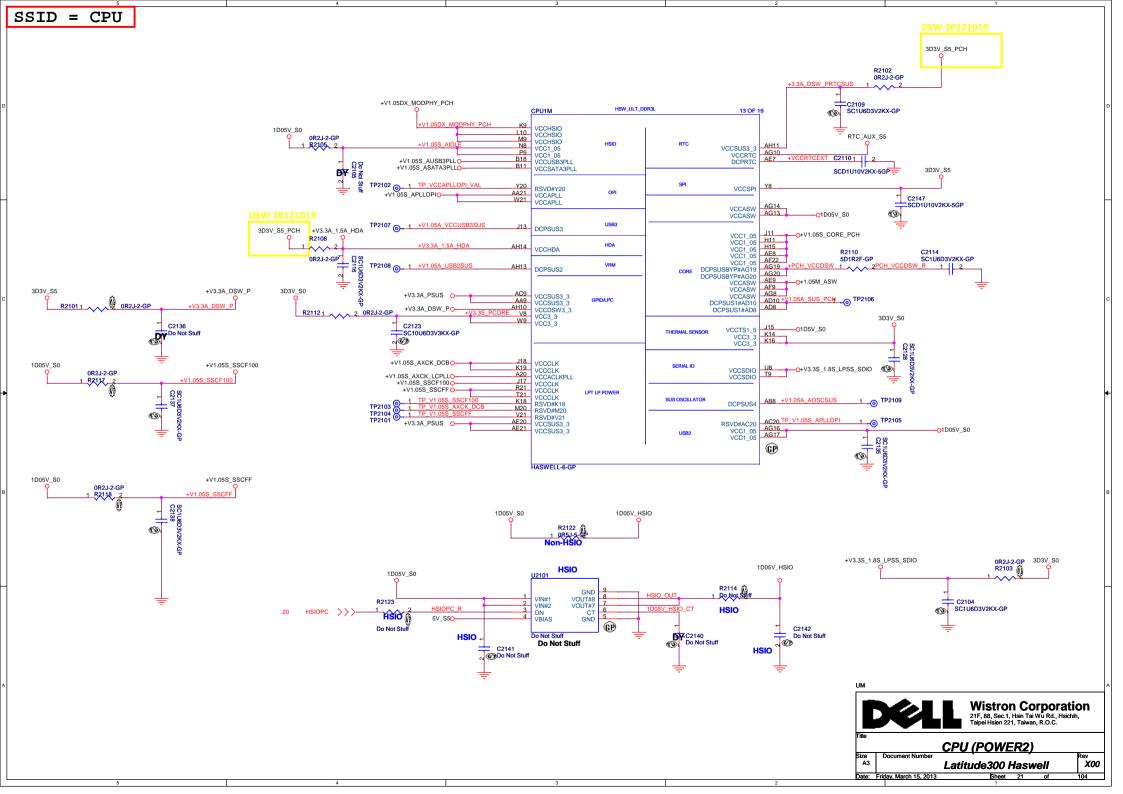


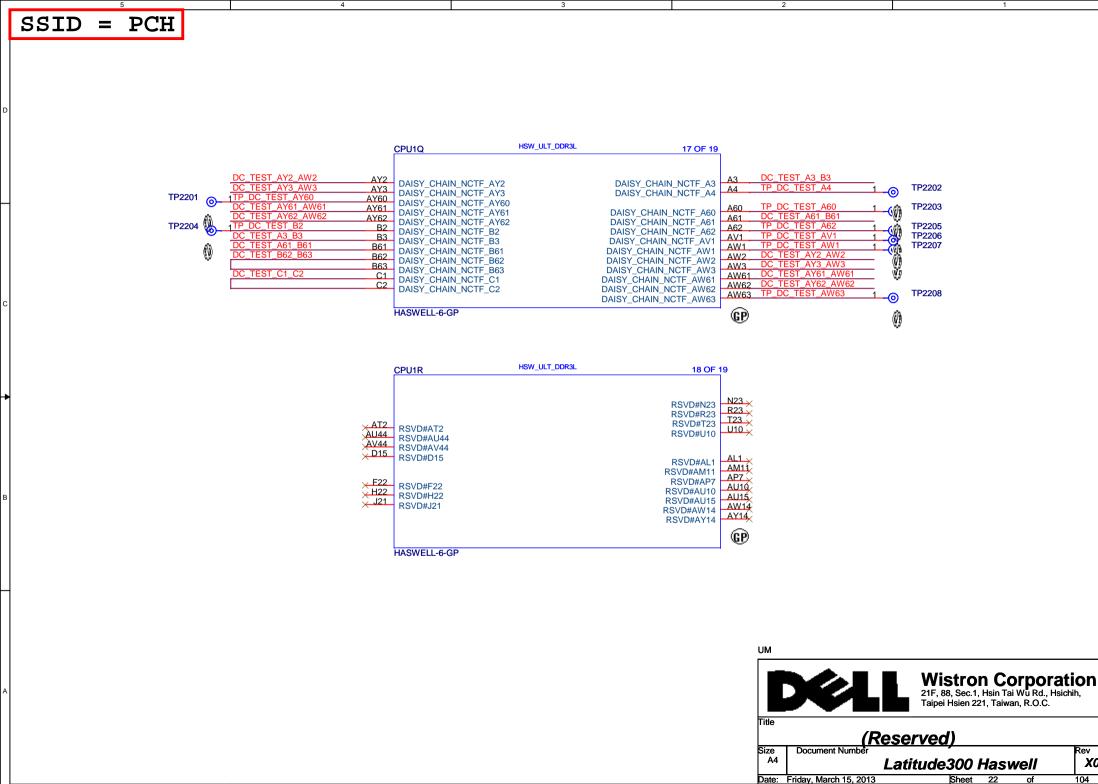












Rev

104

X00

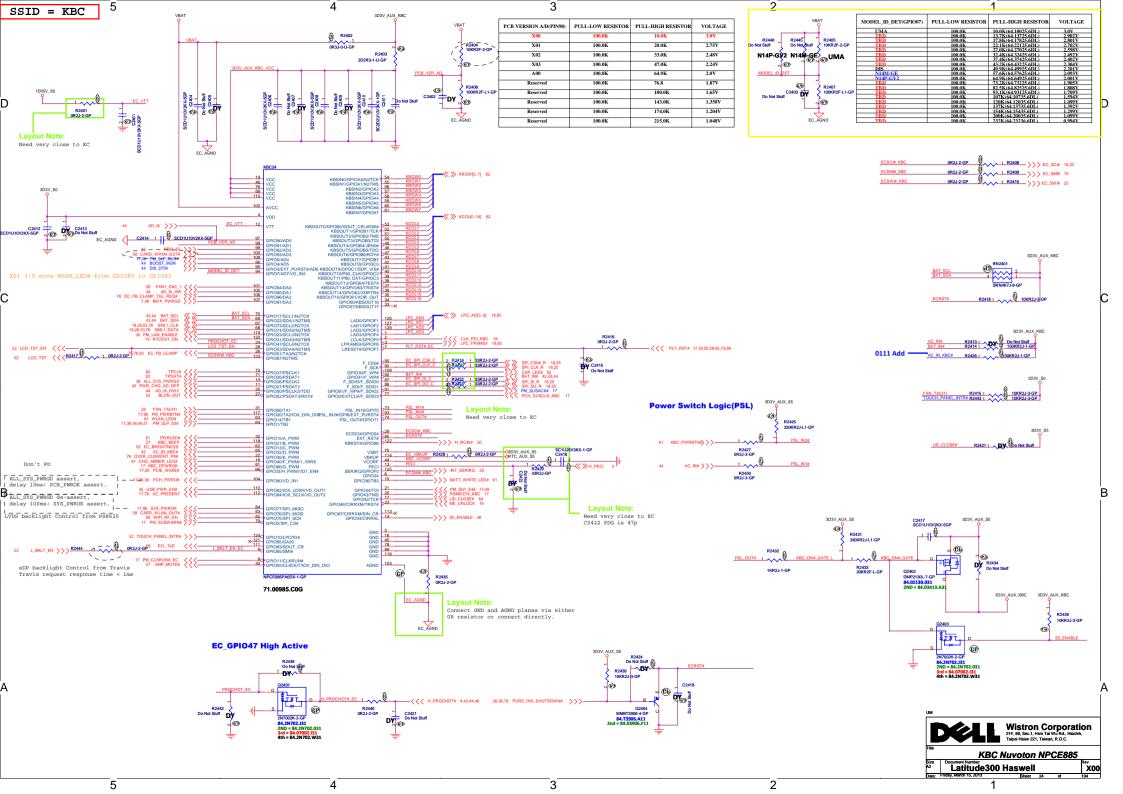
SSID = PCH

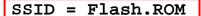
	CPU1N	HSW_ULT_DDR3L	14 OF 1	9
A11				AJ35
A14	VSS		VSS	AJ39
A18	VSS		VSS	AJ41
A24	VSS		VSS	AJ43
A28	VSS		VSS	AJ45
A32	VSS		VSS	AJ47
A36	VSS		VSS	AJ50
A40	VSS		VSS	AJ52
A44	VSS		VSS	AJ54
A48	VSS		VSS	AJ56
A52	VSS		VSS	AJ58
A56	VSS VSS		VSS VSS	AJ60
AA1	VSS		VSS	AJ63
AA58	VSS		VSS	AK23
AB10	VSS		VSS	AK3
AB20	VSS		VSS	AK52
AB22	VSS		VSS	AL10.
AB7	VSS		VSS	AL13
AC61	VSS		VSS	AL17
AD21	VSS		VSS	AL20
AD3	VSS		VSS	AL22
AD63	VSS		VSS	AL23
AE10	VSS		VSS	AL26
AE5	VSS		VSS	AL29
AE58	VSS		VSS	AL31
AF11	VSS		VSS	AL33
AF12	VSS		VSS	AL36
AL 14	VSS		VSS	AL39
	VSS		VSS	AL40
AF17	VSS		VSS	AL45
AF18	VSS		VSS	AL46 AL51
AG1 AG11	VSS		VSS	AL51 AL52
	VSS		VSS	AL52 AL54
AG21 AG23	VSS		VSS	AL54 AL57
AG60	VSS		VSS	AL60
AG61	VSS		VSS	AL61
AG62	VSS		VSS	AM1
AG63	VSS		VSS	AM17
AH17	VSS		VSS	AM23
AH19	VSS		VSS	AM31
AH20	VSS VSS		VSS VSS	AM52
AH22	VSS		VSS	AN17
AH24	VSS		VSS	AN23
AH28	VSS		VSS	AN31
AH30	VSS		VSS	AN32
AH32	VSS		VSS	AN35
AH34	VSS		VSS	AN36
AH36	VSS		VSS	AN39,
AH38	VSS		VSS	AN40
AH40	VSS		VSS	AN42
AH42	VSS		VSS	AN43
AH44	VSS		VSS	AN45
AD49	VSS		VSS	AN46.
ALIST	VSS		VSS	AN48
ALIJ3	VSS		VSS	AN49
	VSS		VSS	AN51
AH57 AJ13	VSS		VSS	AN52 AN60
AJ13 AJ14	VSS		VSS	AN63
AJ14 AJ23	VSS		VSS	AN7
AJ25	VSS		VSS	AP10
AJ27	VSS		VSS	AP17
AJ29	VSS		VSS	AP20
1	VSS		VSS	
L				<u></u>
<del>-</del>				GP) →
	HASWEL	L-6-GP		

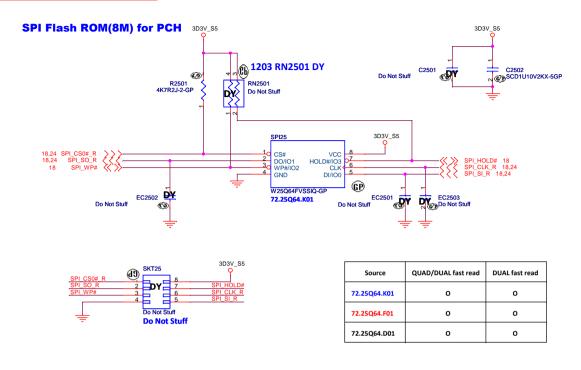
AP22	VSS	VSS	AV59
AP23		VSS	AV8
AP26		VSS	AW16
AP29		VSS	AW24
AP3		VSS	AW33
AP31		VSS	AW35
AP38		VSS	AW37
AP39		VSS	AW4
AP48		VSS	AW40
AP52	VSS	VSS	AW42
AP54	VSS	VSS	AW44
AP57	VSS	VSS	AW47
AR11 AR15	VSS	VSS	AW50 AW51
AR15 AR17		VSS	AW51 AW59
AR23		VSS	AW60
AR31		VSS	AY11.
AR33		VSS	AY16
AR39		VSS	AY18
AR43		VSS	AY22
AR49		VSS	AY24
AR5		VSS	AY26
AR52		VSS	AY30
AT13		VSS	AY33
AT35		VSS	AY4
AT37	VSS VSS	VSS VSS	AY51
AT40			AY53
AT42		VSS VSS	AY57
AT43		VSS	AY59
AT46		VSS	AY6
AT49		VSS	B20
AT61		VSS	B24
AT62		VSS	B26
AT63		VSS	B28
AU1		VSS	B32
AU16		VSS	B36
AU18		VSS	B4
AU20	VSS	VSS	B40
AU22		VSS	B44
AU24	VSS	VSS	B48
AU26	VSS	VSS	B52
AU28		VSS	B56 B60
AU30 AU33		VSS	C11
AU51		VSS	C14
AU53	VSS	VSS	C14 C18
AU55		VSS	C20
AU55 AU57		VSS	C25
AU59		VSS	C27
AV14		VSS	C38
AV16		VSS	C39
AV20		VSS	C57
AV24		VSS	D12
AV28		VSS VSS	D14
AV33		VSS	D18
AV34		VSS	D2
AV36		VSS	D21
AV39		VSS	D23
AV41		VSS	D25
AV43		VSS	D26
AV46		VSS	D27
AV49		VSS	D29
AV51		VSS	D30
AV55		VSS	D31
	HASWELL-6-GP		(GP)
<del>=</del>	I MOWELL-O-OF		~ +
Ŧ			=

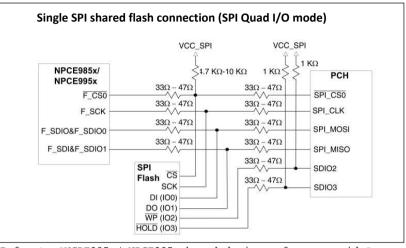
CPU10 HSW\_ULT\_DDR3L 15 OF 19





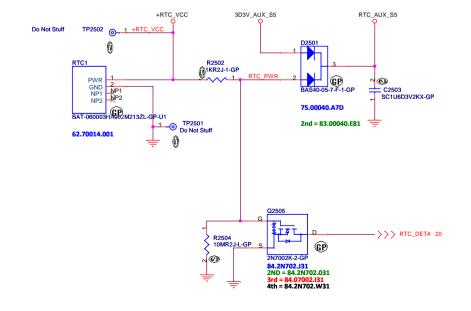




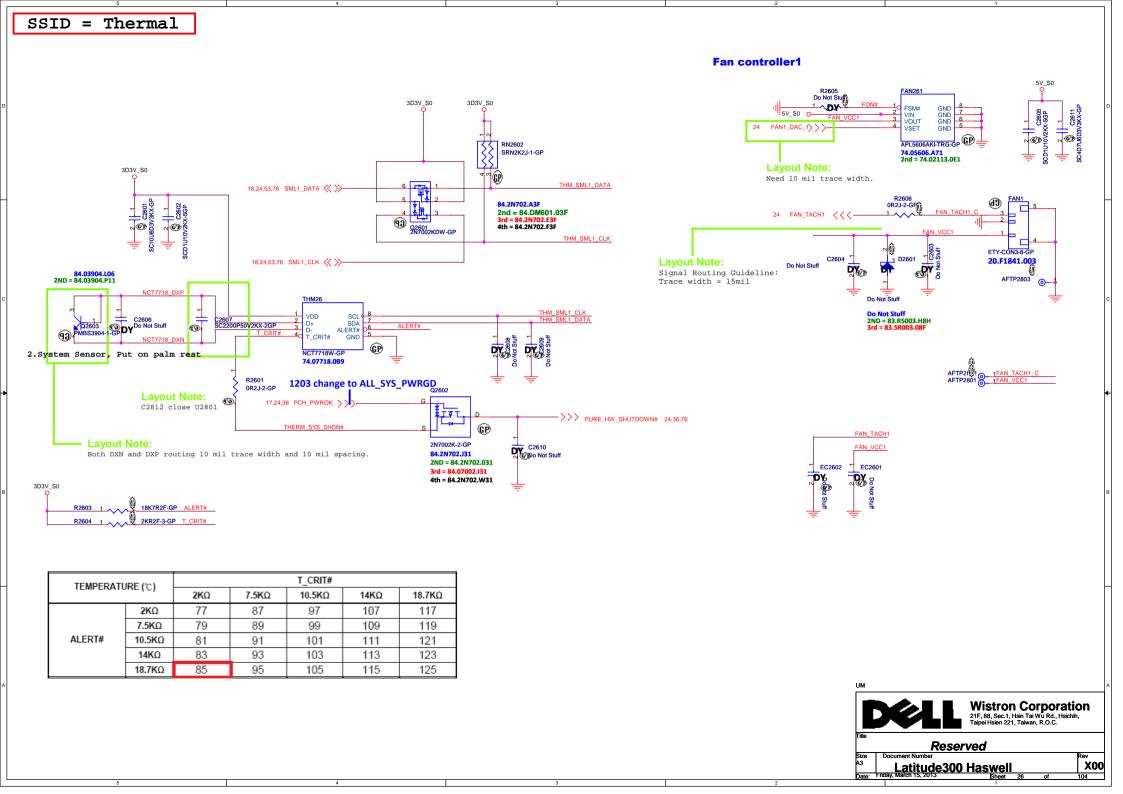


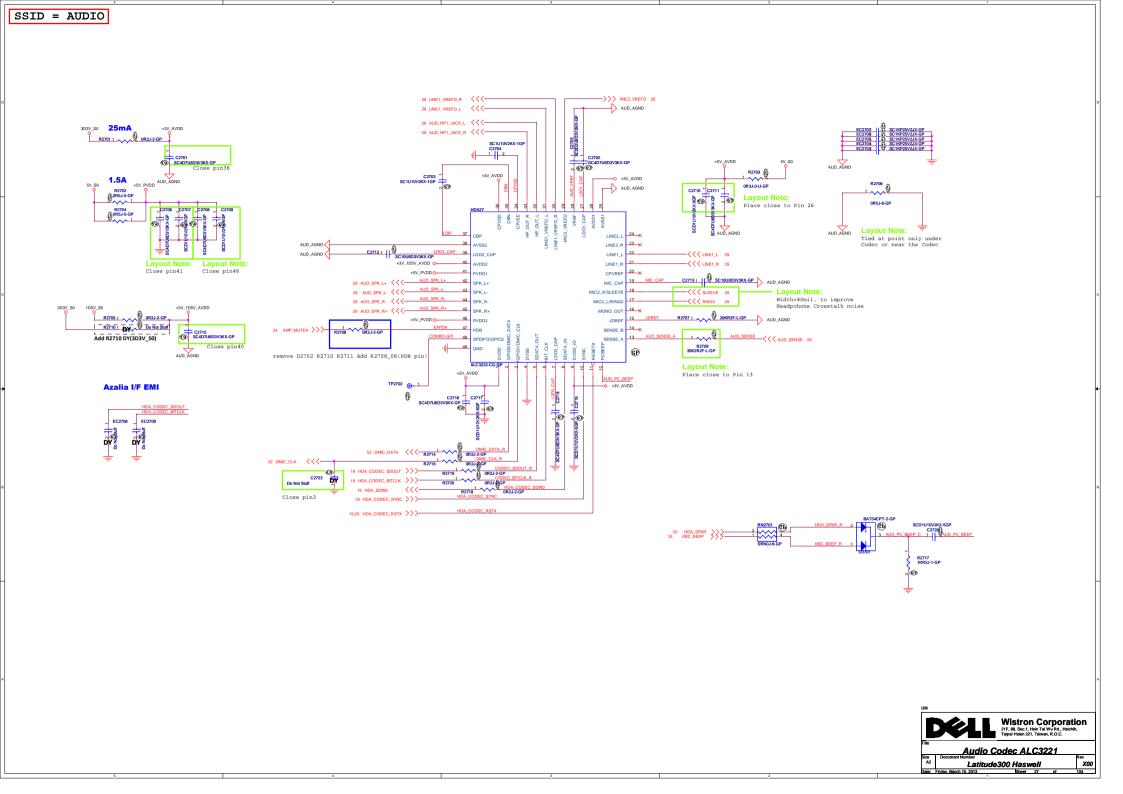
Refer to "NCPE985x/ NPCE995x board design reference guide"

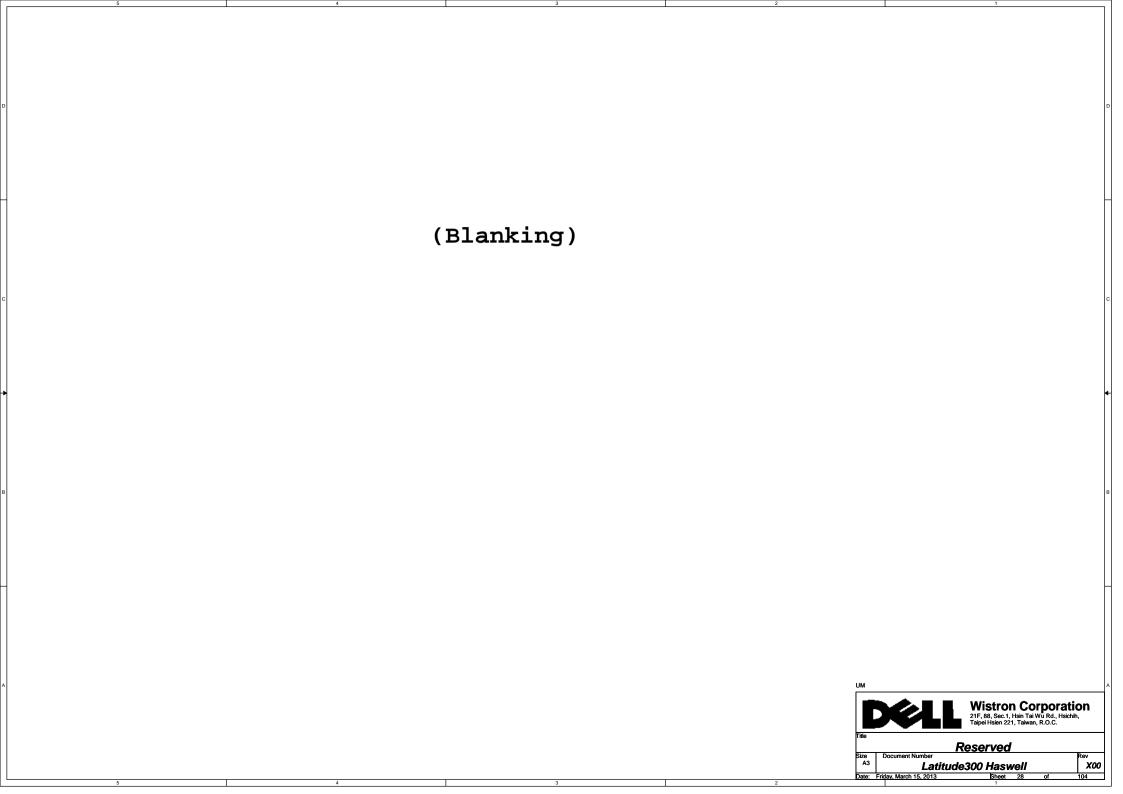
#### SSID = RBATT

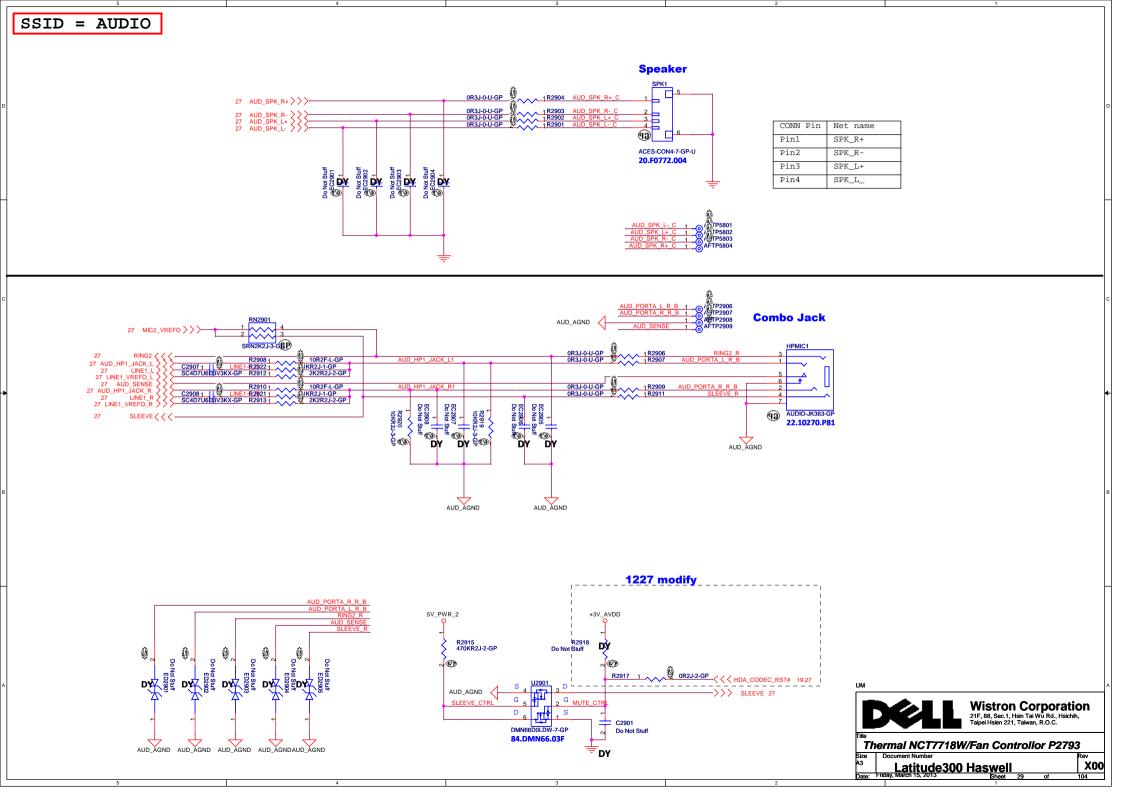


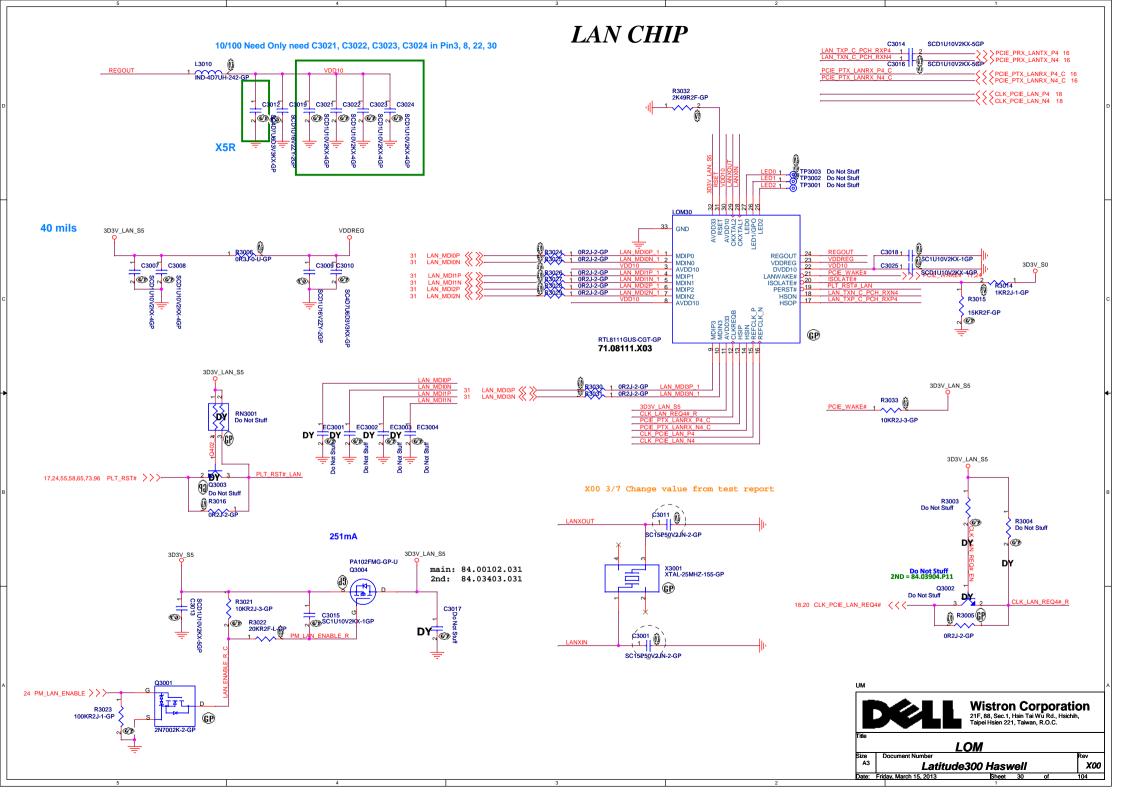


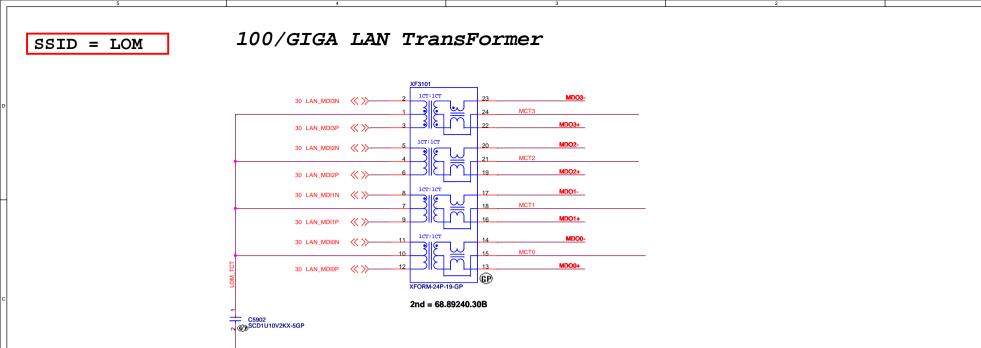


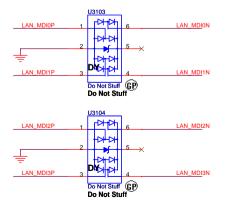




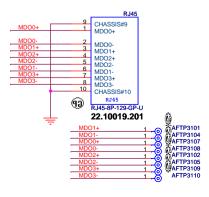


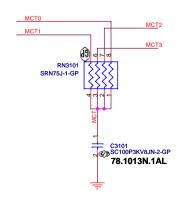




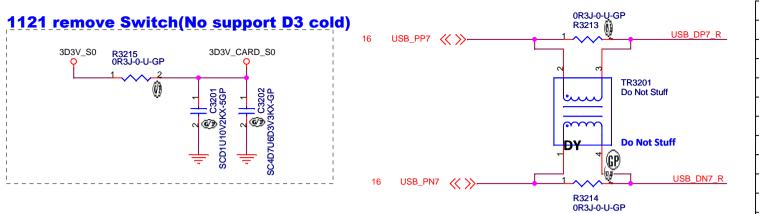


### RJ45 CONN

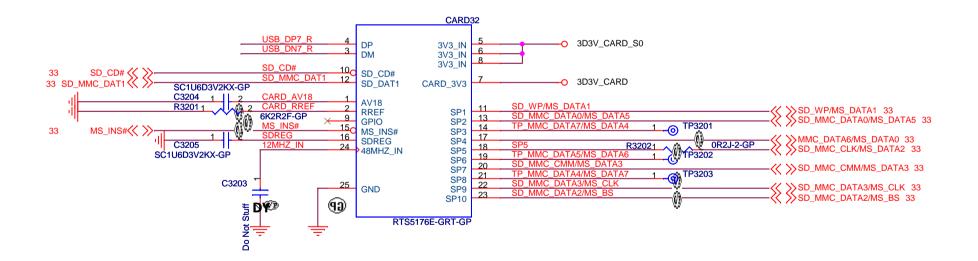








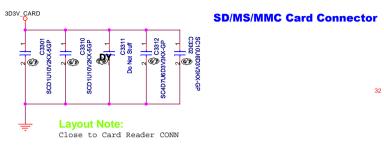
Pin name	Net name
SD_DAT1	SD_MMC_DAT1
SP1	SD_WP/MS_DATA1
SP2	SD_MMC_DATA0/MS_DATA5
SP3	MMC_DATA7/MS_DATA4
SP4	MMC_DATA6/MS_DATA0
SP5	SD_MMC_CLK/MS_DATA2
SP6	MMC_DATA5/MS_DATA6
SP7	SD_MMC Command/MS_DATA3
SP8	MMC_DATA4/MS_DATA7
SP9	SD_MMC_DATA3/MS_CLK
SP10	SD_MMC_DATA2/MS_BS

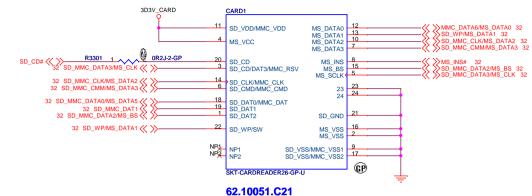


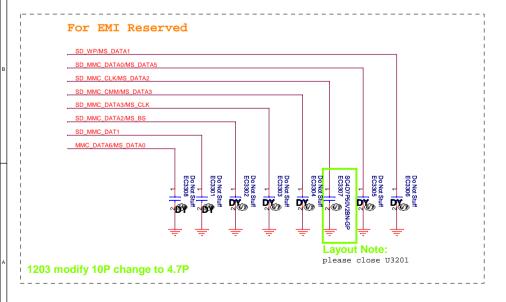


pate. 1 Triday, March 10, 2010 Sheet 32

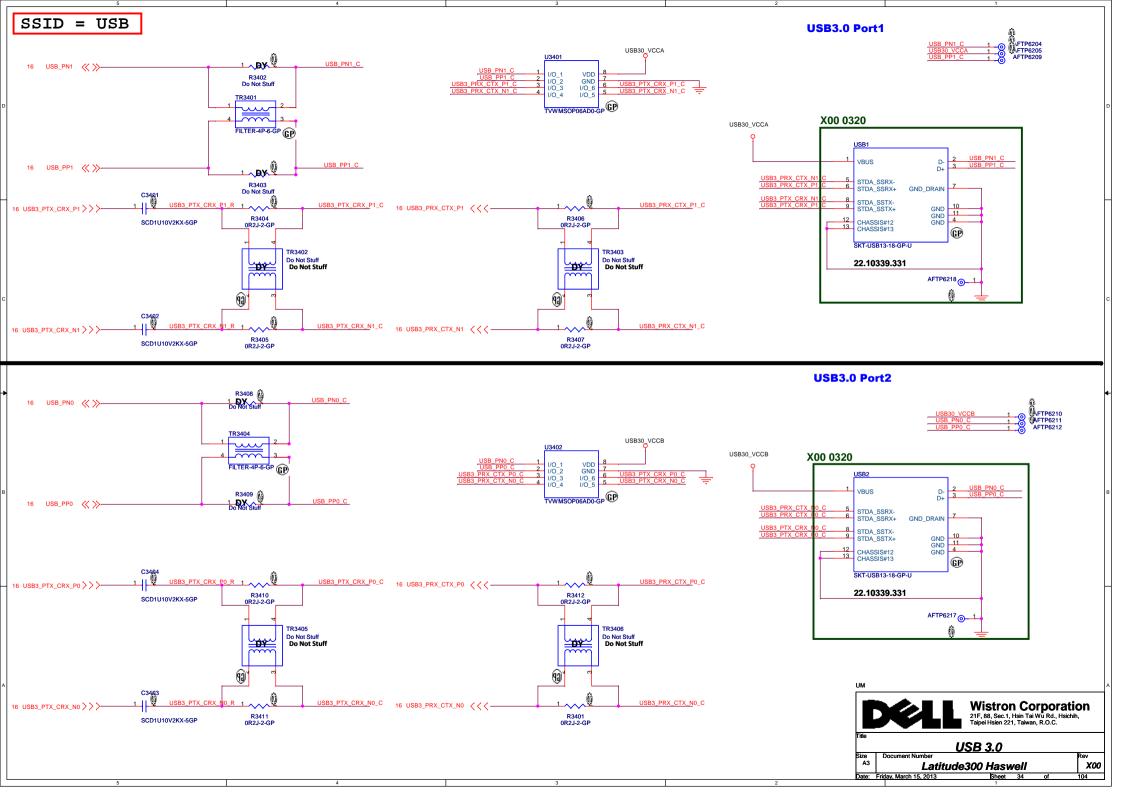


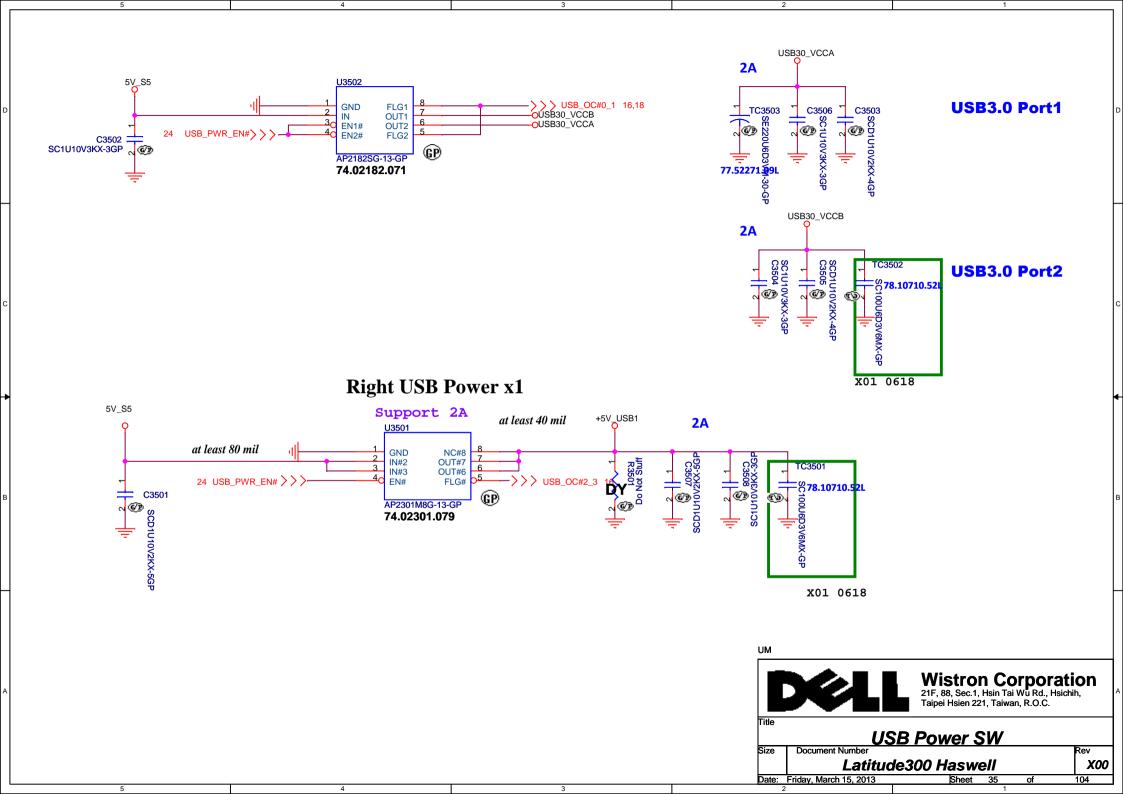


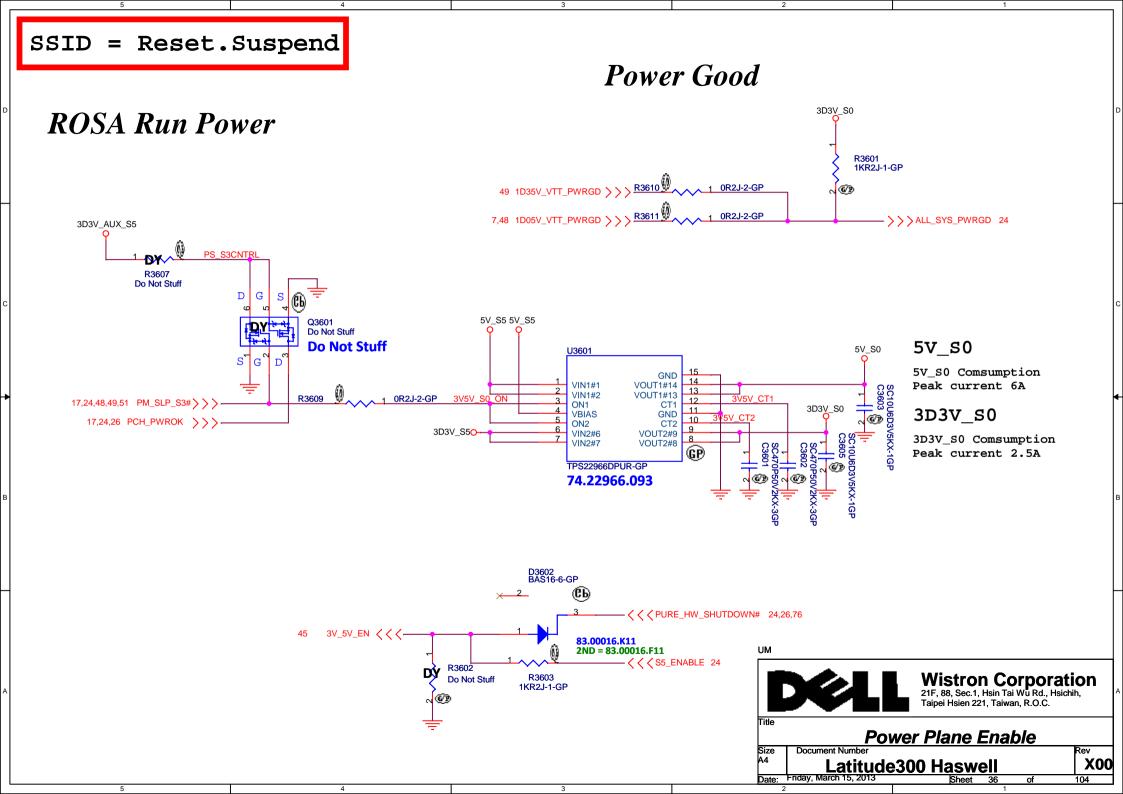


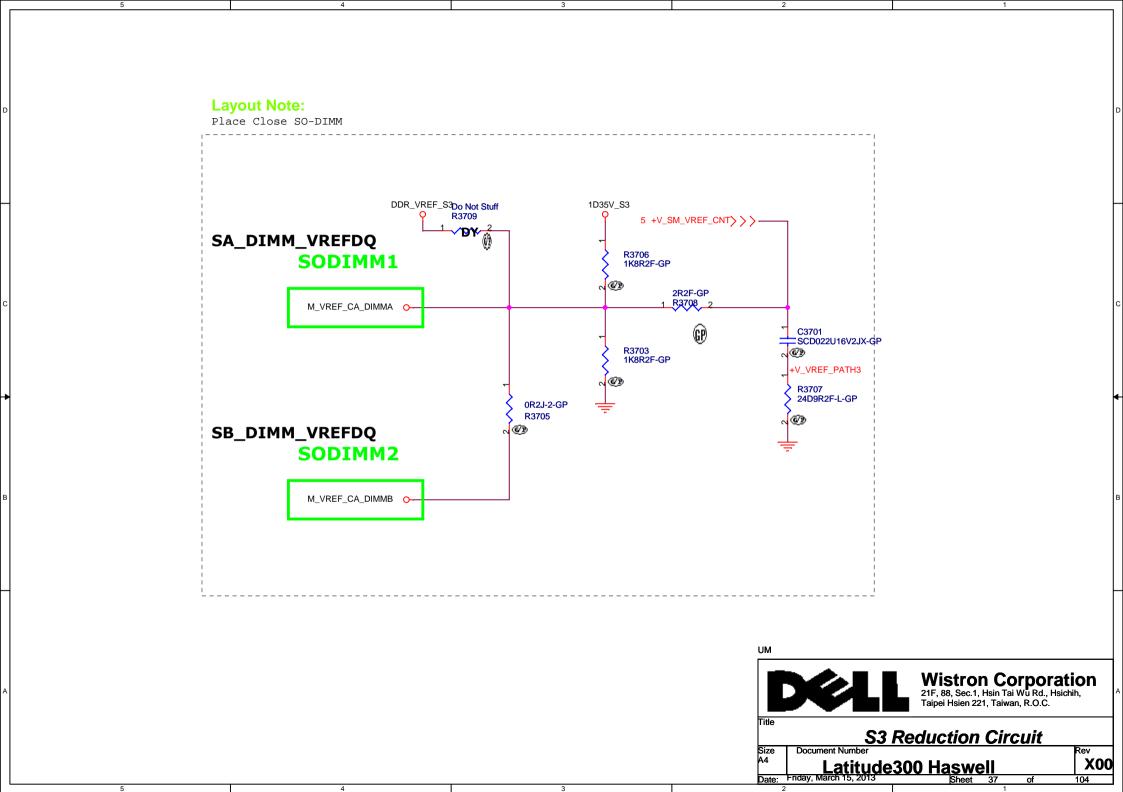




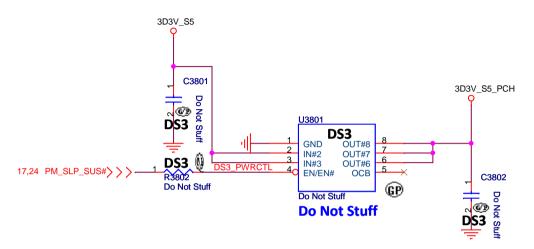








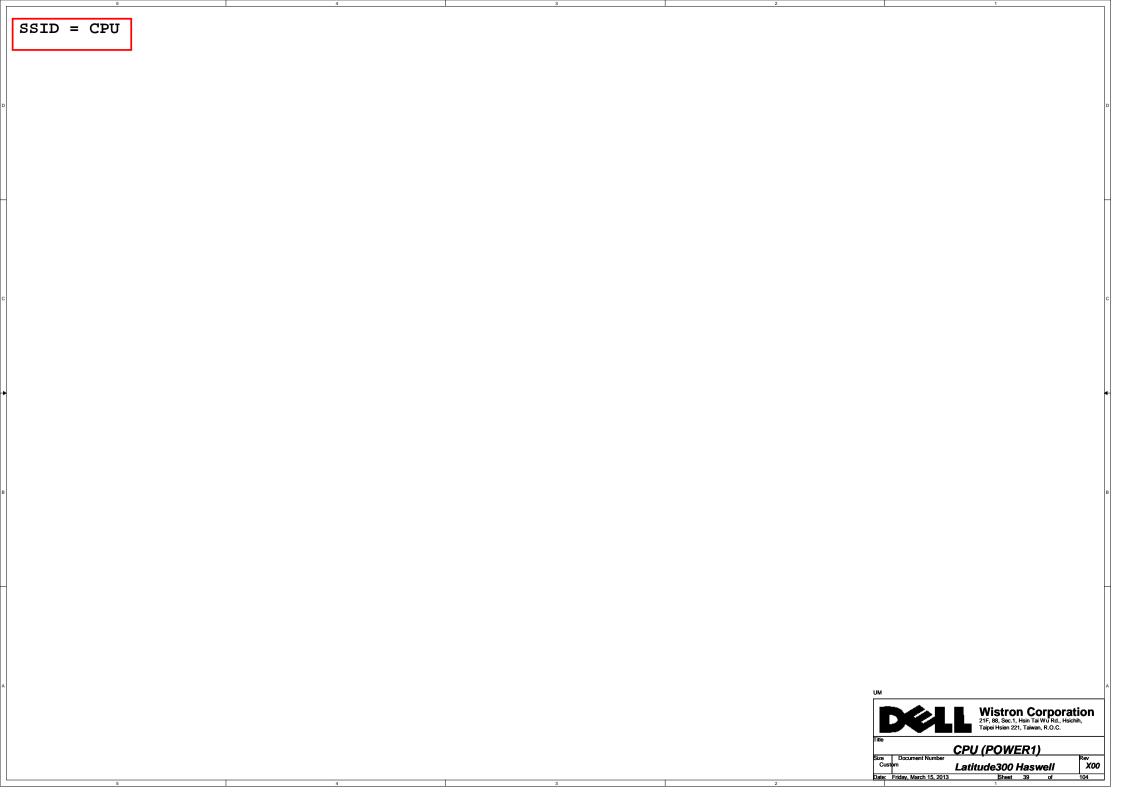




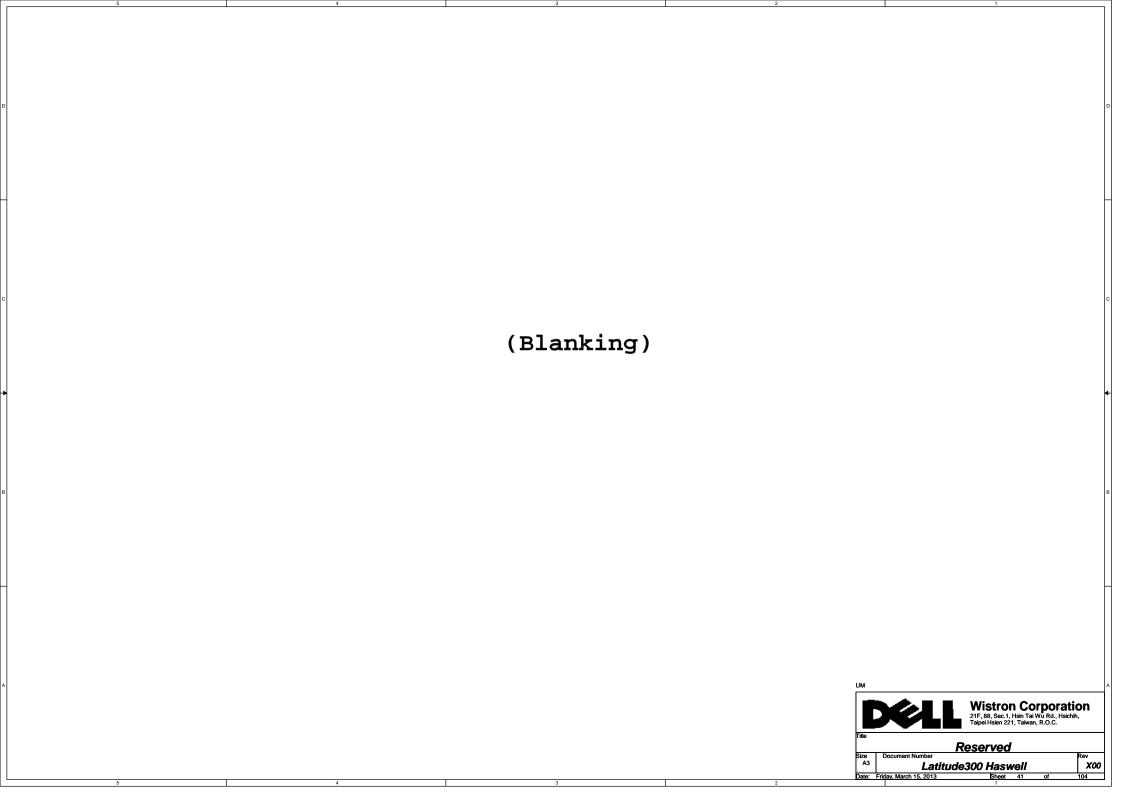
1210 change power switch (RdsON:100m ohm)

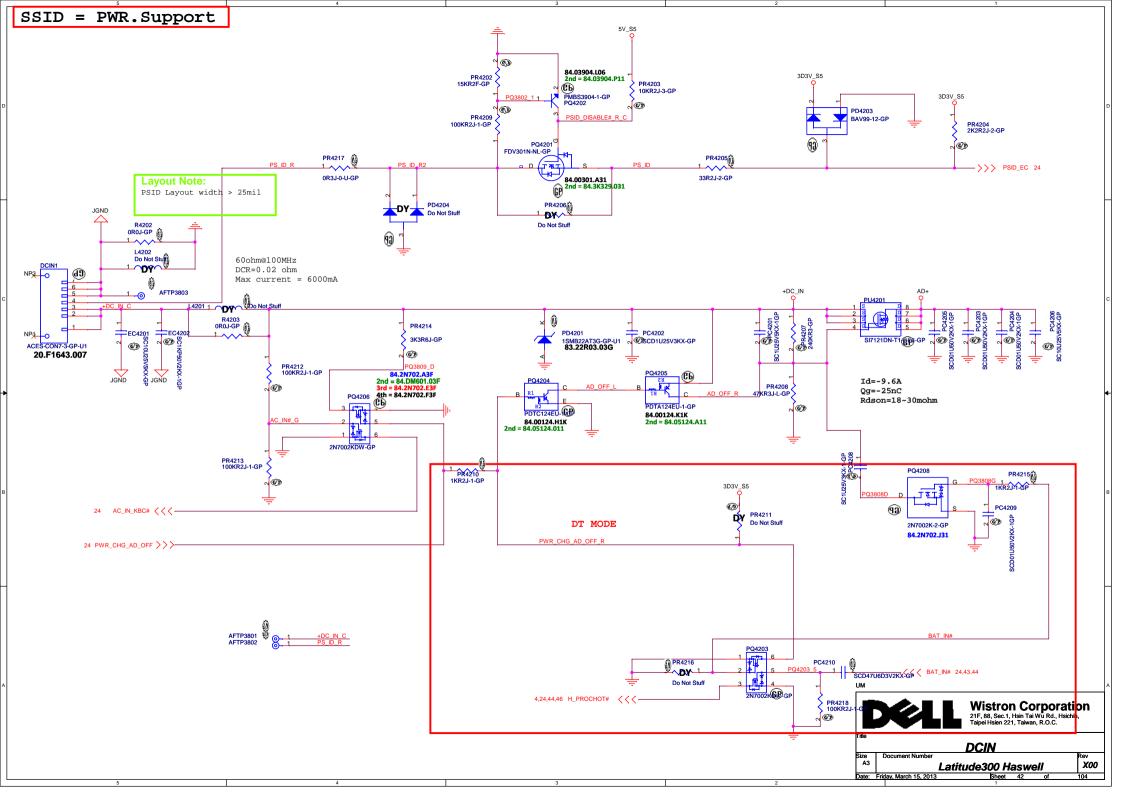


Date: Friday, March 15, 2013

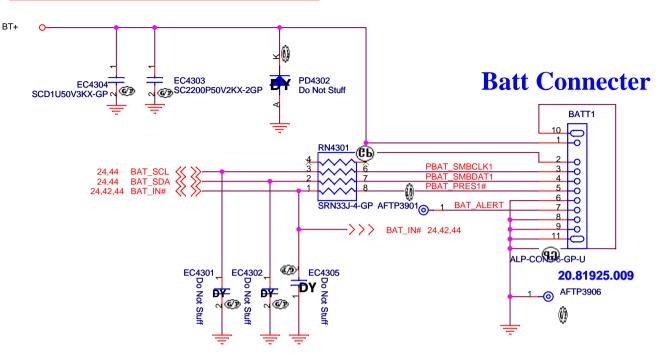




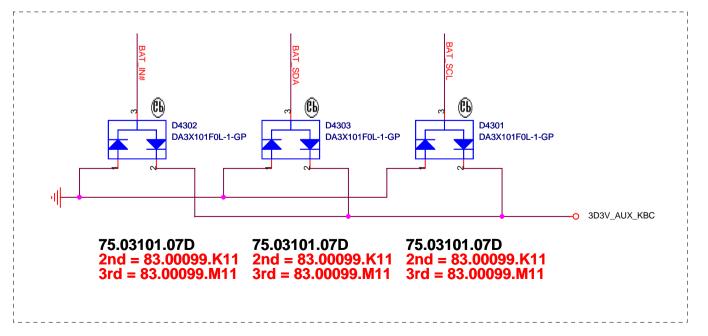






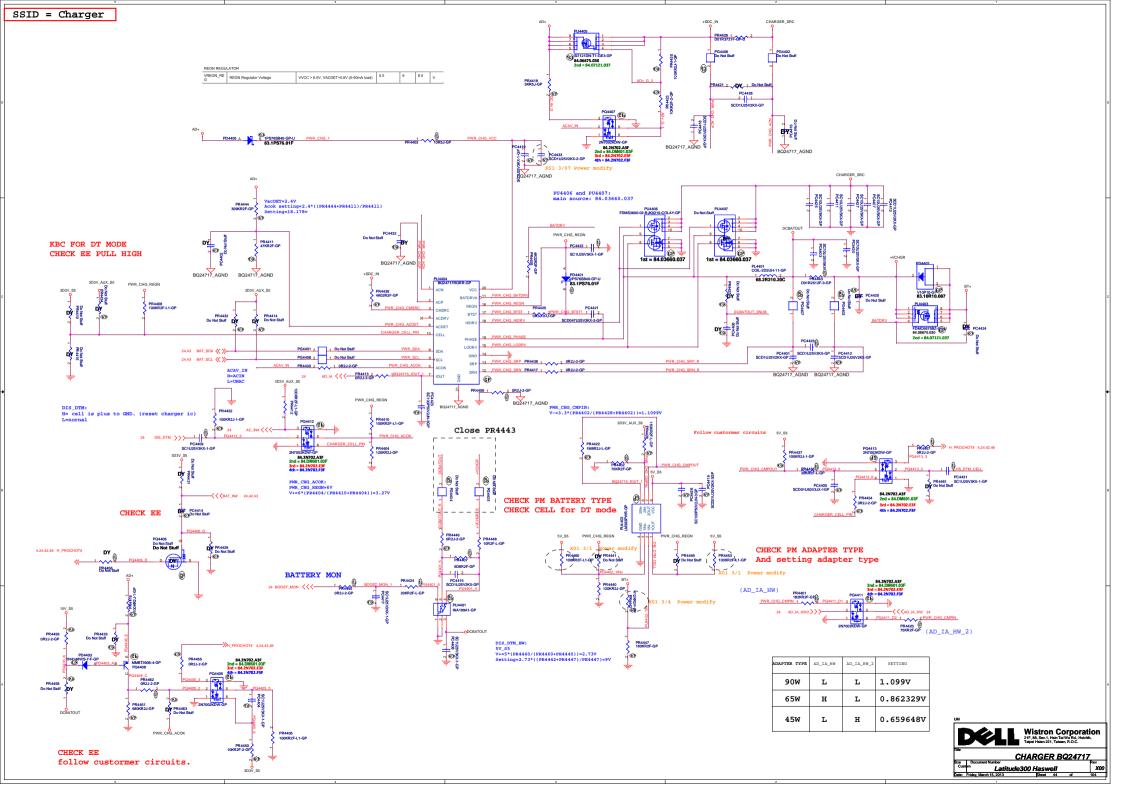


Placement: Close to Batt Connector









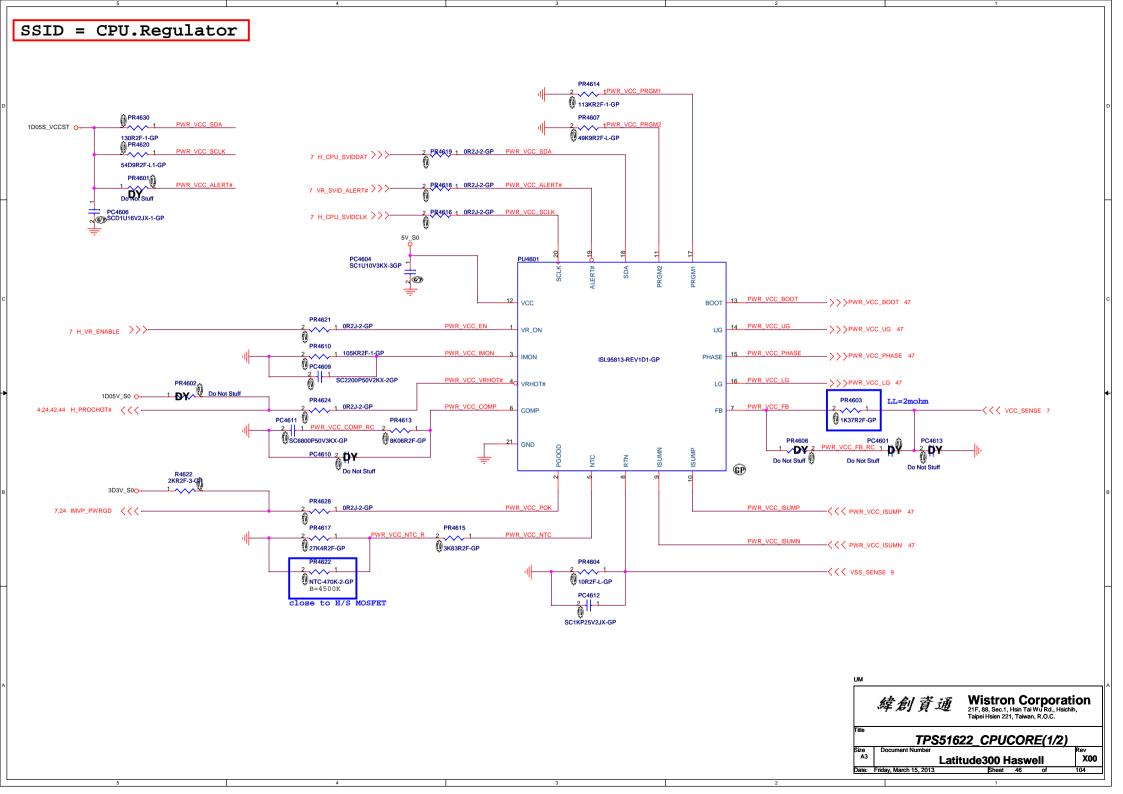
## SSID = PWR.Plane.Regulator 5v3p3v 3D3V AUX S5 PWR\_DCBATOUT\_5V 2nd = 83.00054.Y81 3rd - 93 RAT54 D91 Do Not Stuff 0R2J-2-GP 75.00054.C7D PR4515 0R2J-2-GP PWR DCBATOUT 3D3V 3rd = 83.BAT54.P81<sub>5V St</sub> 75.00054±C7D 36 3V\_5V\_EN >>> (P) (Q) 0R2J-2-GP PC4515 PC4534 SCD1U25V3KX-GP SCD1U25V3KX-GP PWR\_DCBATOUT\_5V Design Current=3.3A 5.17A<OCP>6.11A C4535 PR4528 PWR 3D3V VBST2 1 D8R3 GP PWR 3D3V VBST2 SCD1U25V3KX-GP 1D8R3 GP Design Current=8.3A 12.98A<OCP>15.34A 2nd = 68.3R31B.10U 68.3R310.20A PL4503 MI PWR\_3D3V\_DRVL2 11 15 PWR 5V DRVL1 IND-2D2UH-46-GP-U DB/// 2 DRVI 1 **4 9** PWR\_3D3V\_EN2 20 PWR\_5V\_EN1 PR4531 137KR2F-1-GP GP) PR4534 Dy Do Not Stuf Do Not Stuff PC4522 PY PC4526 SC4D7U6D3V3KX-GP ~ ഈ 17 3V\_5V\_POK <<<< Close to VFB Pin (pin2) PR4532 Close to VFB Pin (pin5) TPS51225 & TPS51285 Co-lay

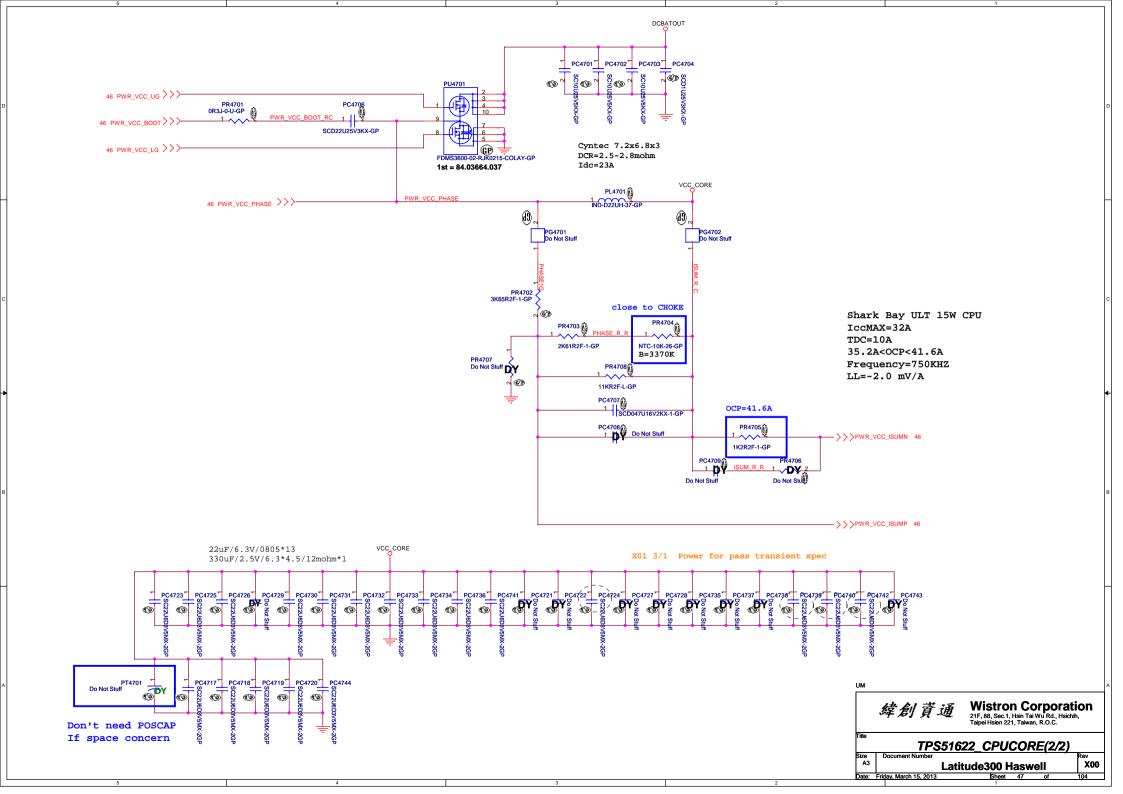
I/P cap: CHIP CAP C 10U 25V K0805 X5R/ 78.10622.51L
Inductor: CHIP IND 3.3UH PCMC063T-3R3MN Cyntec 28mohm/30mohm Isat =13.5Arms 68.3R310.20A
O/P cap: CHIP CAP POL 220U 6.3V M 6.3\*4.5 / Matsuki/ 17mohm / 77.52271.09L
H/S:S18412 / 24mohm/30mohme4.5Vgs / 84.00412.037
L/S:S18740 / 14.5mohm/17.5mohme4.5Vgs / 84.00412.037

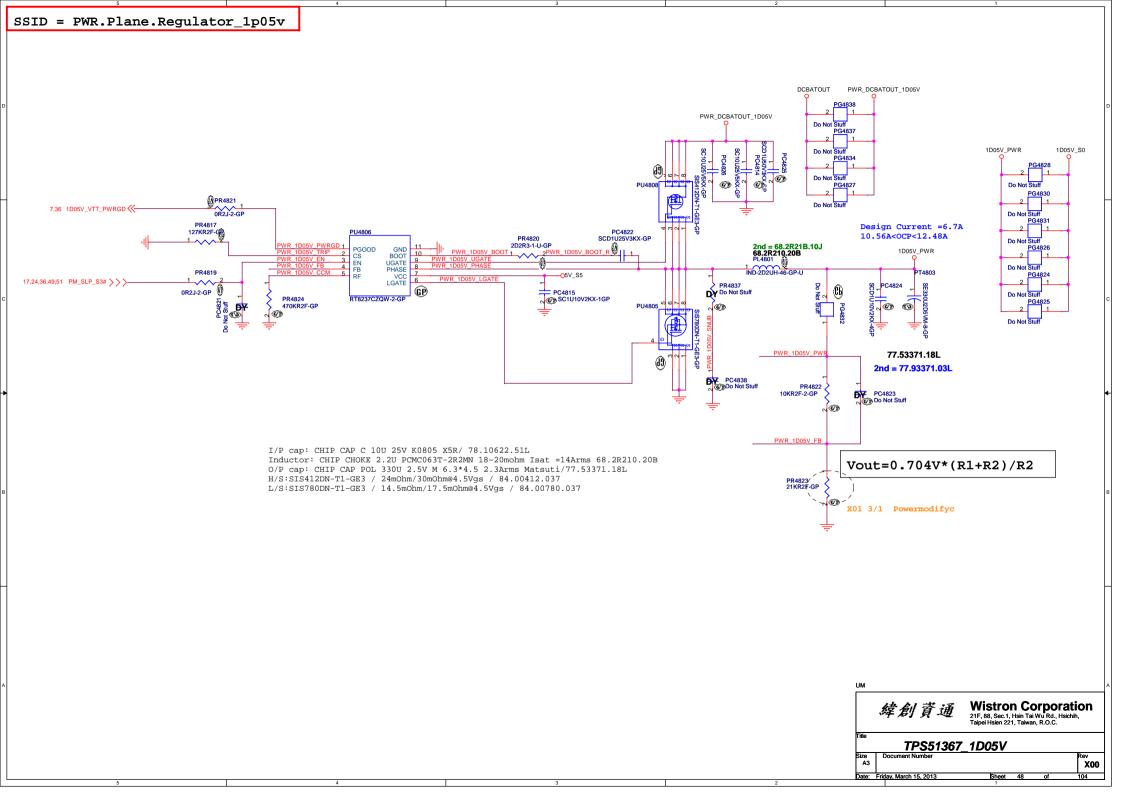
	TPS51225	TPS51285
PR4510	45.3KK	9.09K
PR4511	110K	22.1K

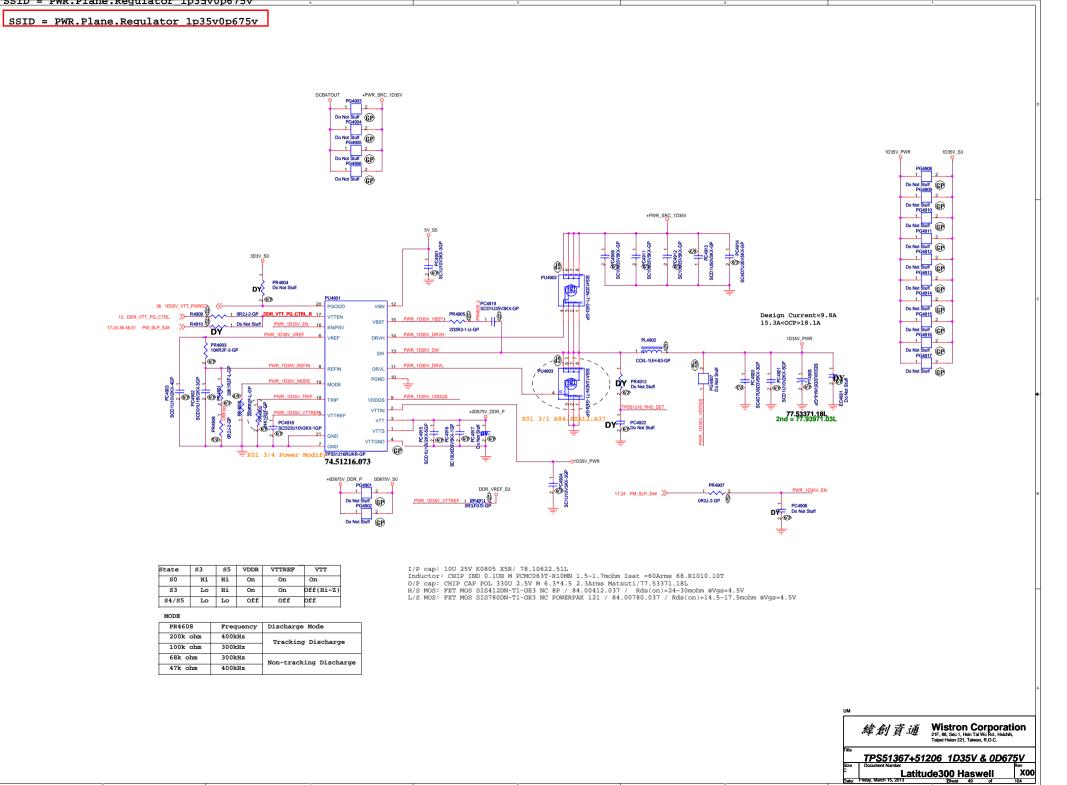
I/P cap: CHIP CAP C 101 25V K0805 XSR/ 78.10622.51L
I/P cap: CHIP CHOKE 2.2U PCMC063T-2R2MN 18mohm/20mohm Isat =14Arms 68.2R210.20B
O/P cap: CHIP CAP POL 220U 6.3V M 6.3\*4.5 [Matsukl/ 17mohm / 77.52271.09L
H/S:SIS412 / 24mohm/3/mohm41.5Vgs / 84.00f80.037
L/S:SIS780 / 14.5mohm/17.5mohme4.5Vgs / 84.00f80.037

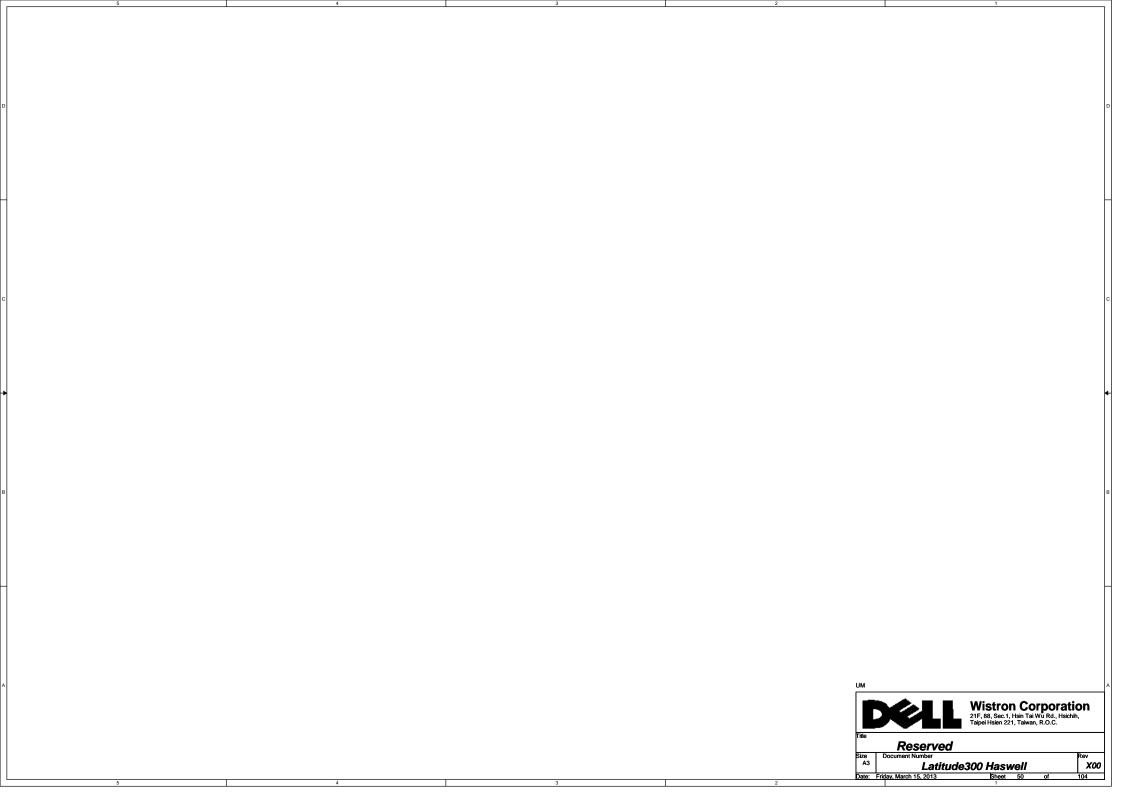


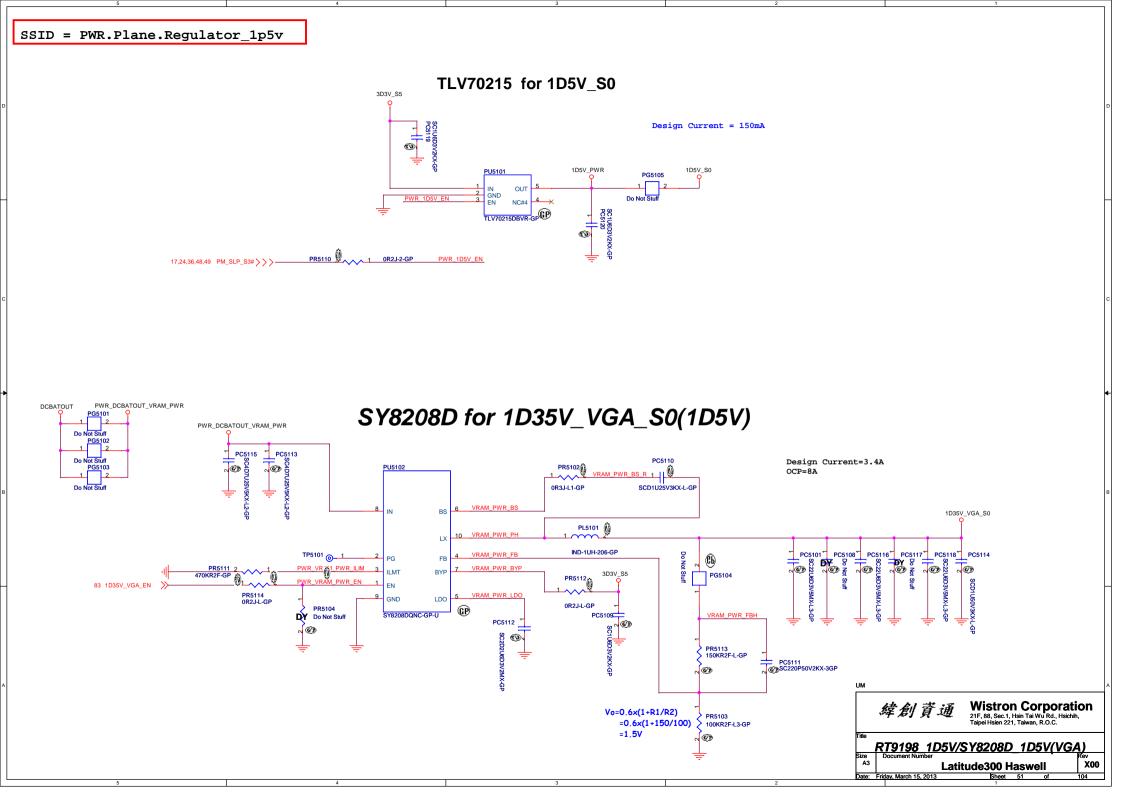


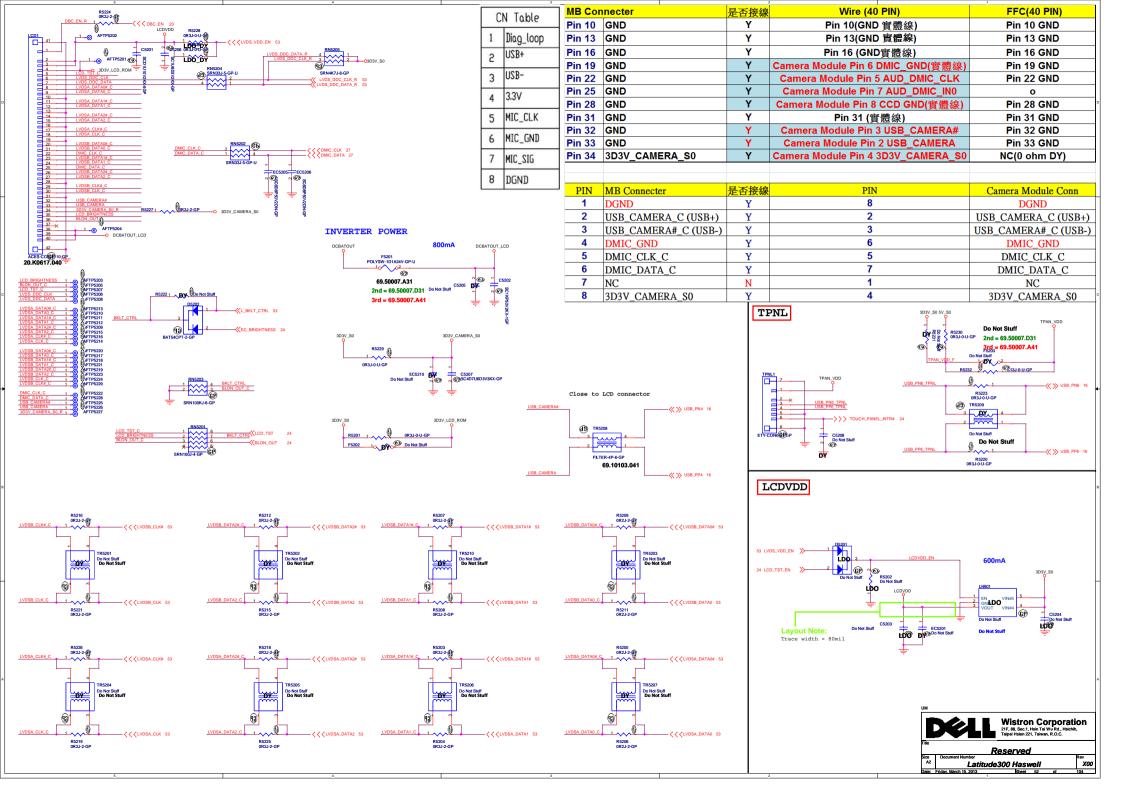


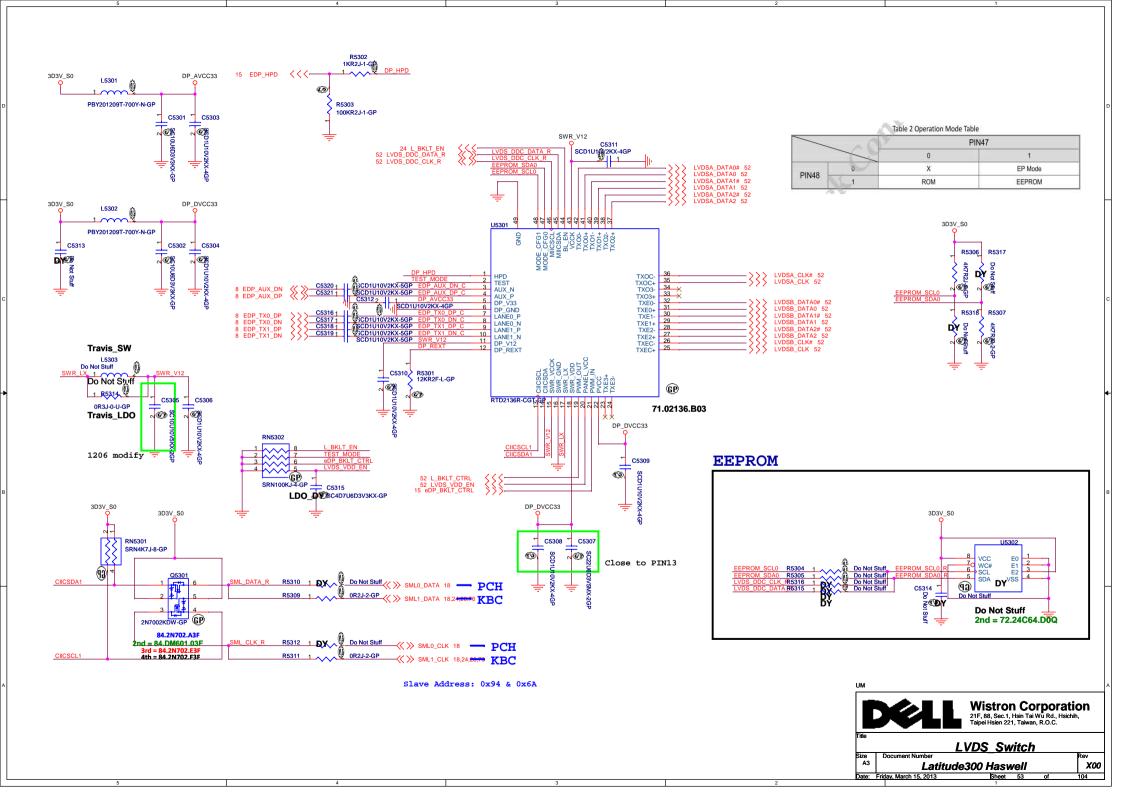


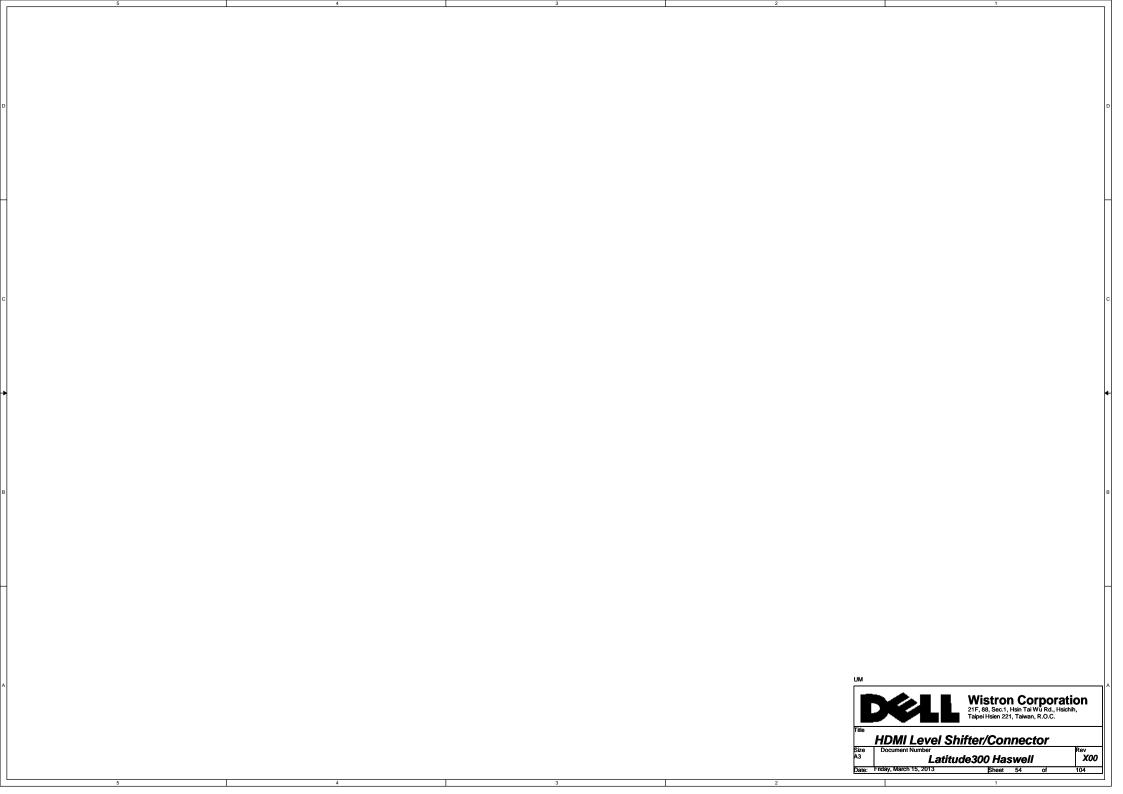


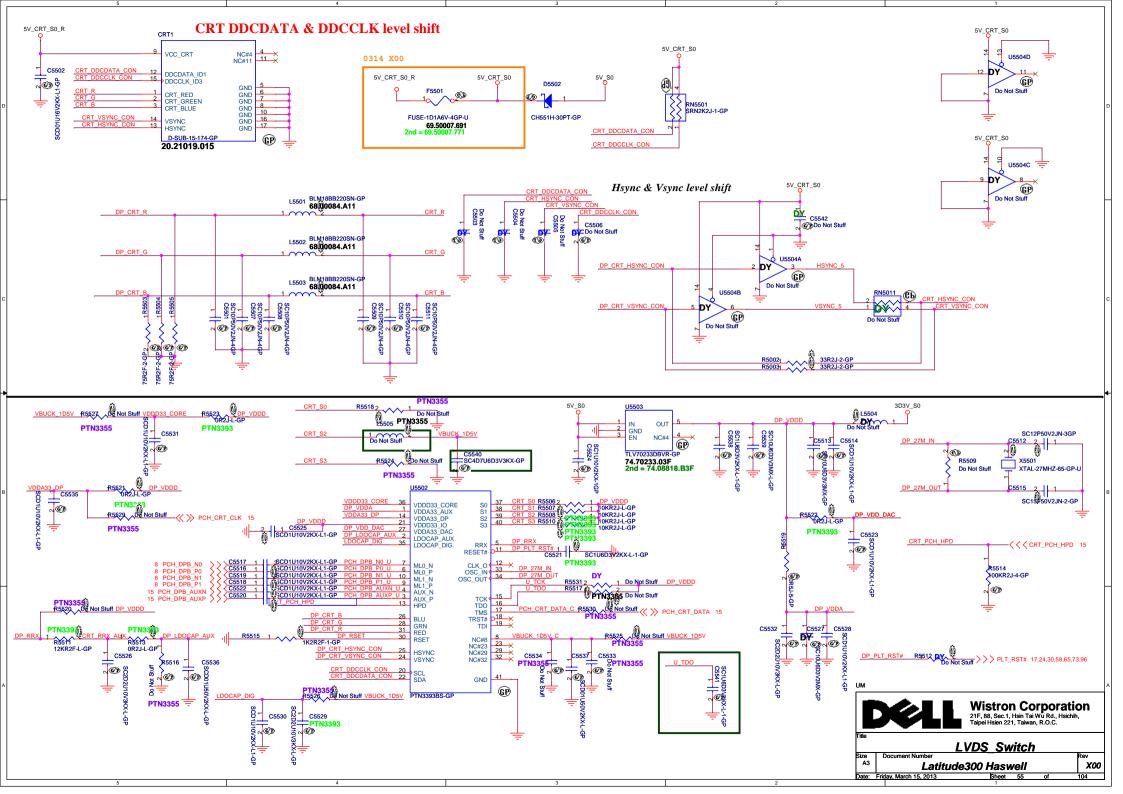






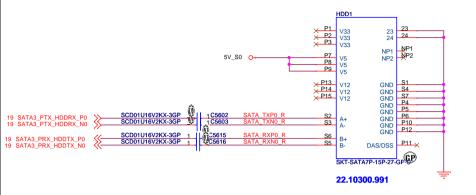


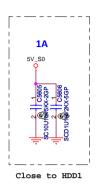




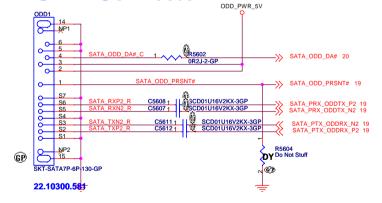
SSID = SATA

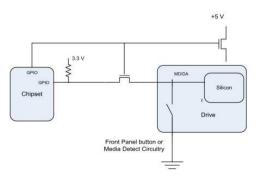
## **SATA HDD Connector**



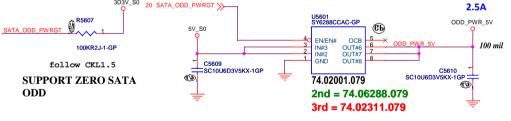








## SATA Zero Power ODD



Current limit Active High typ =>2.5A

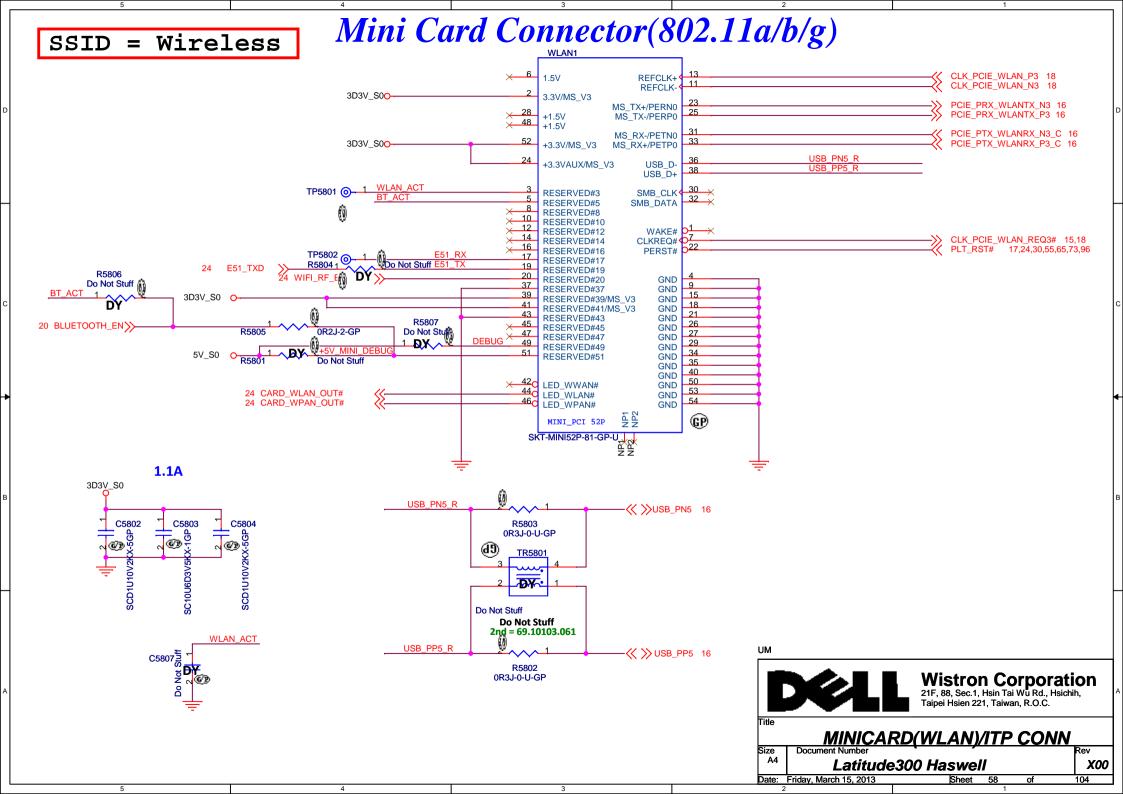


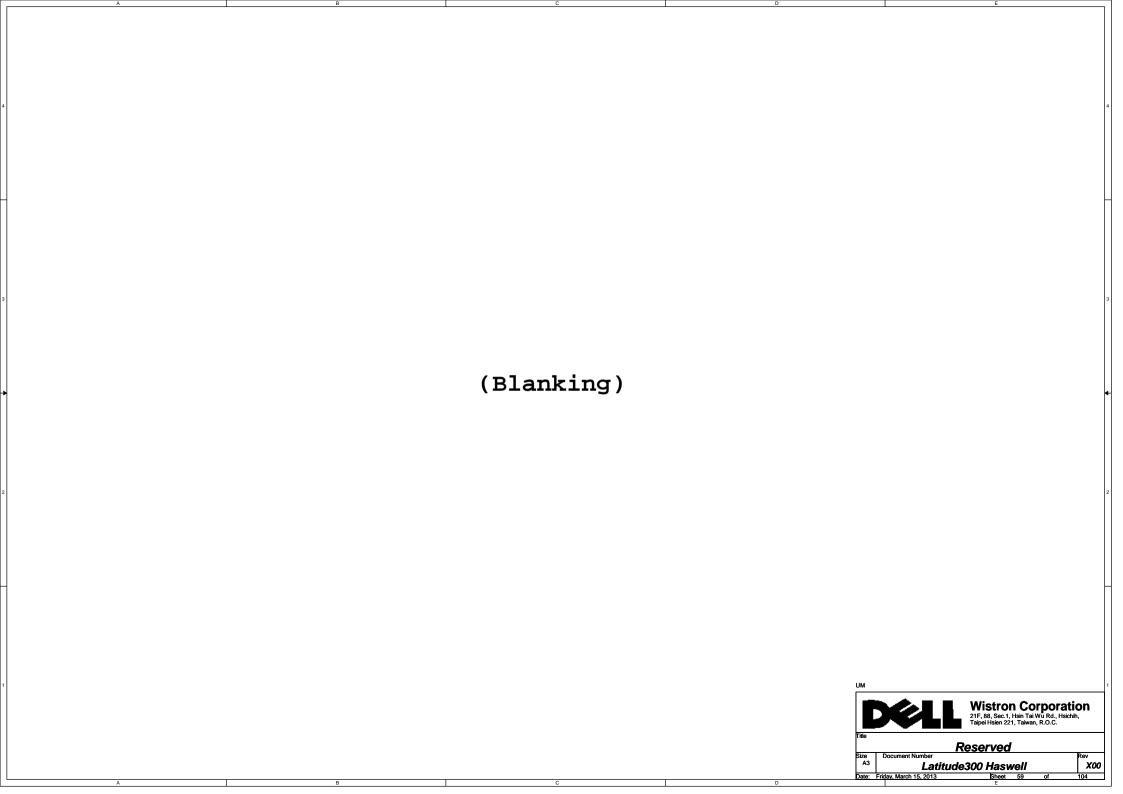
HDD/ODD

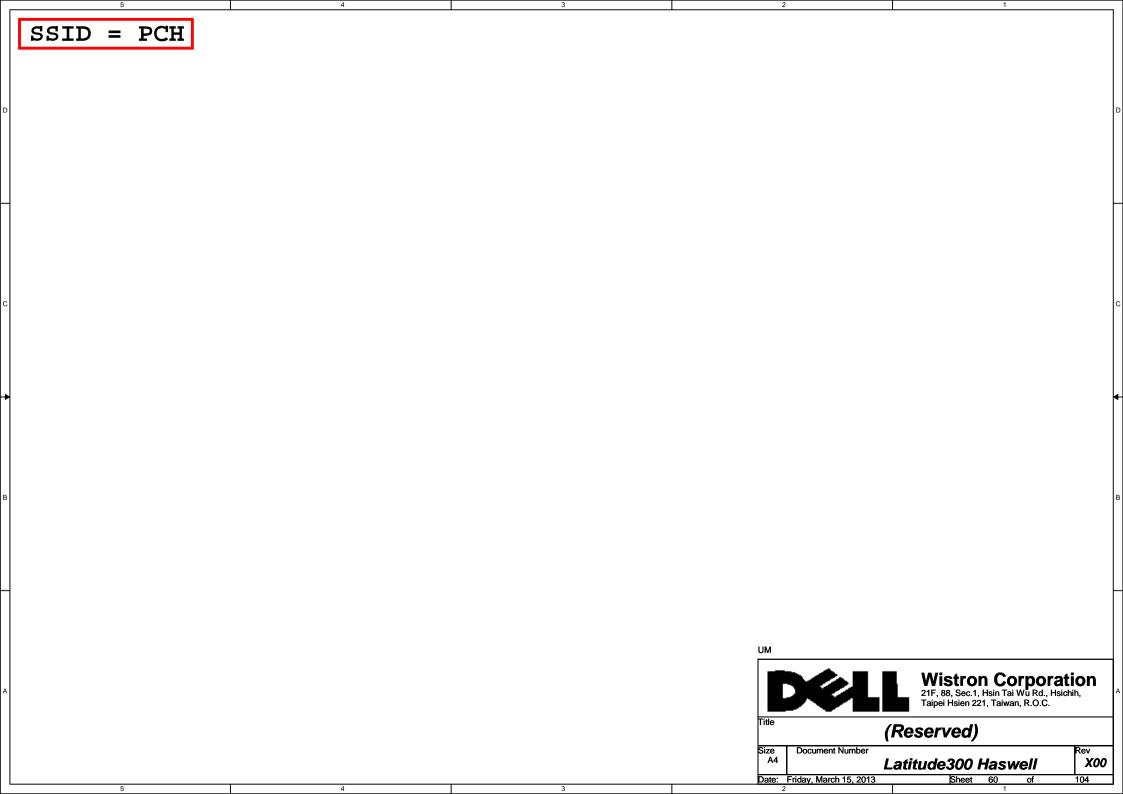
Latitude300 Haswell X00

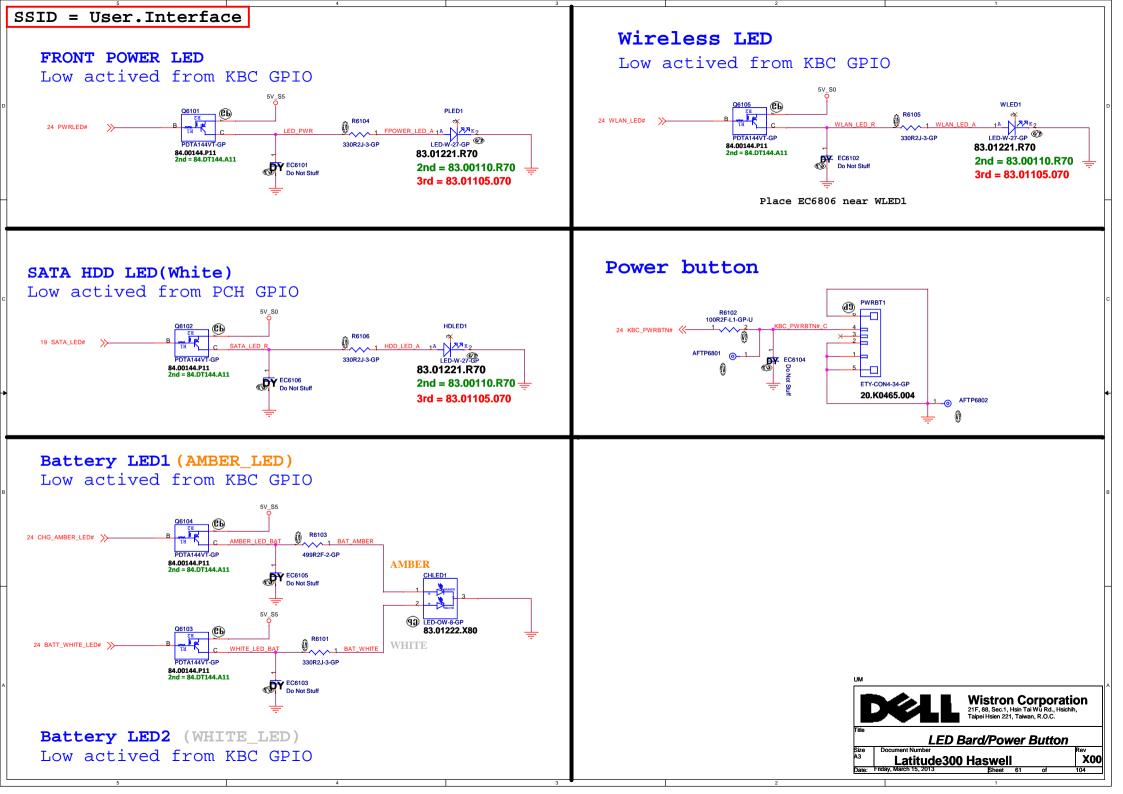
-nday, March 15, 2013 Sheet 56 of 104

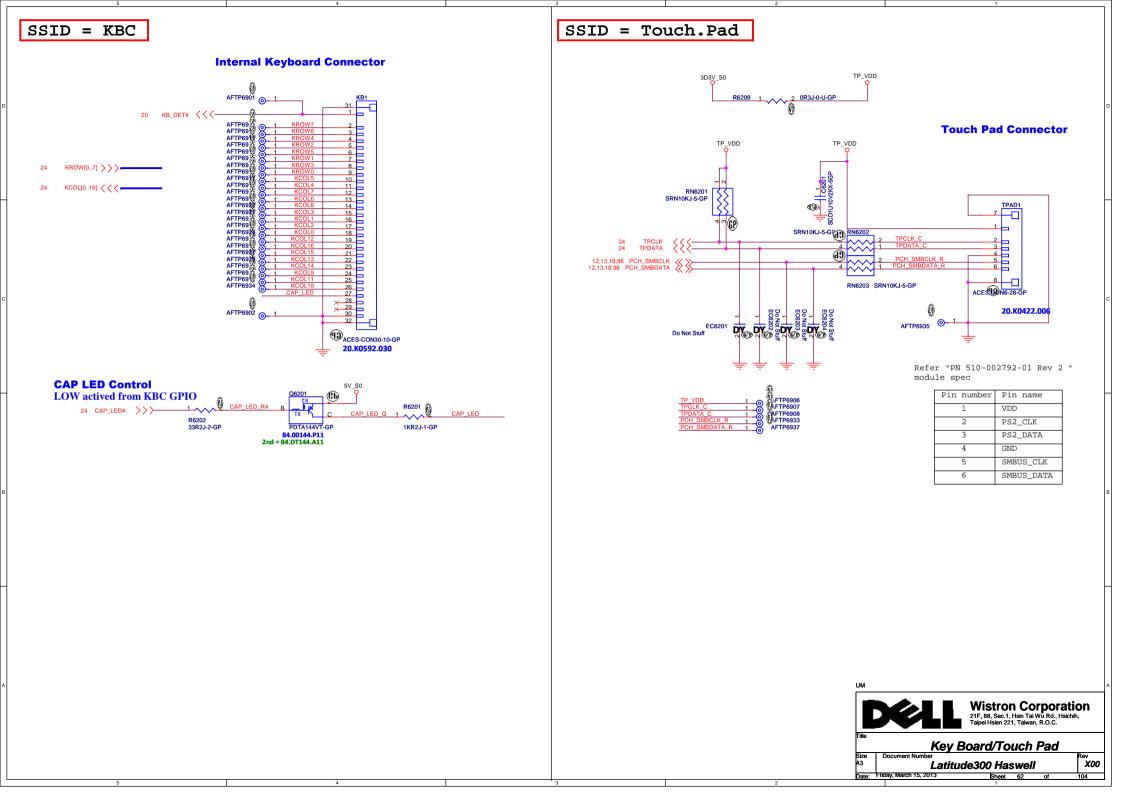
SSID = ESATA (Blanking) Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C. **ESATA** Rev **X00** 104 Latitude300 Haswell

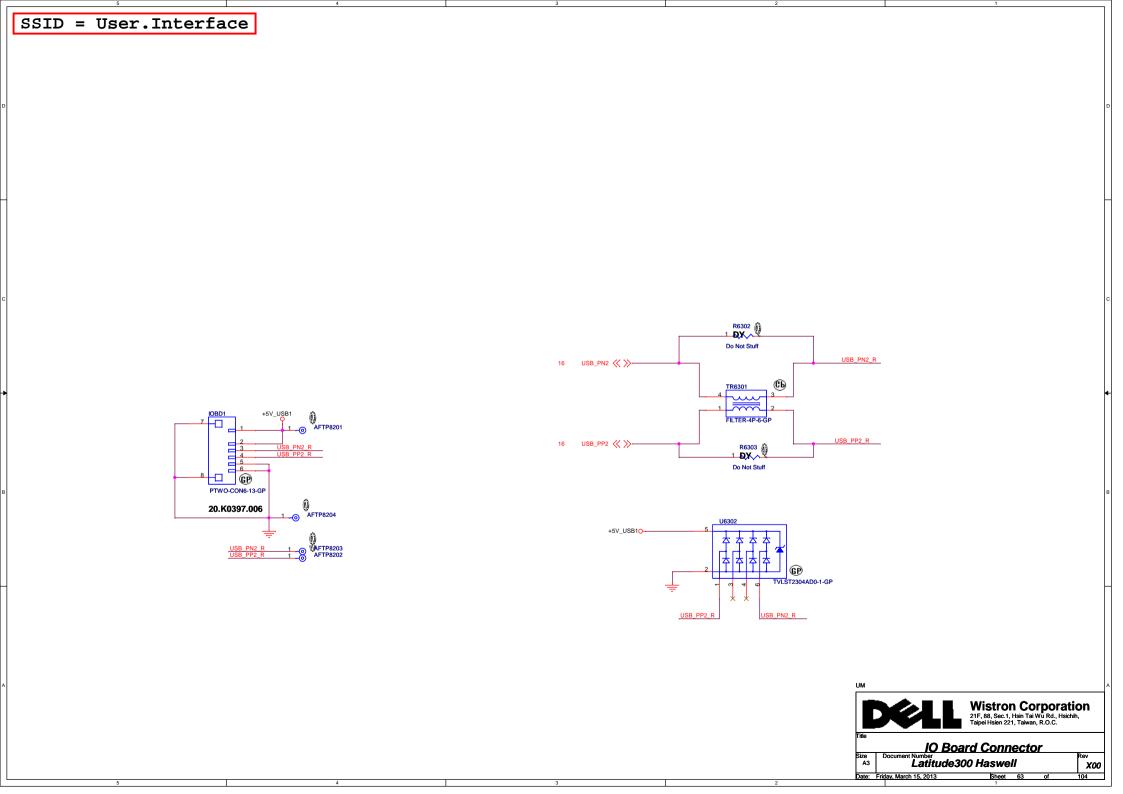


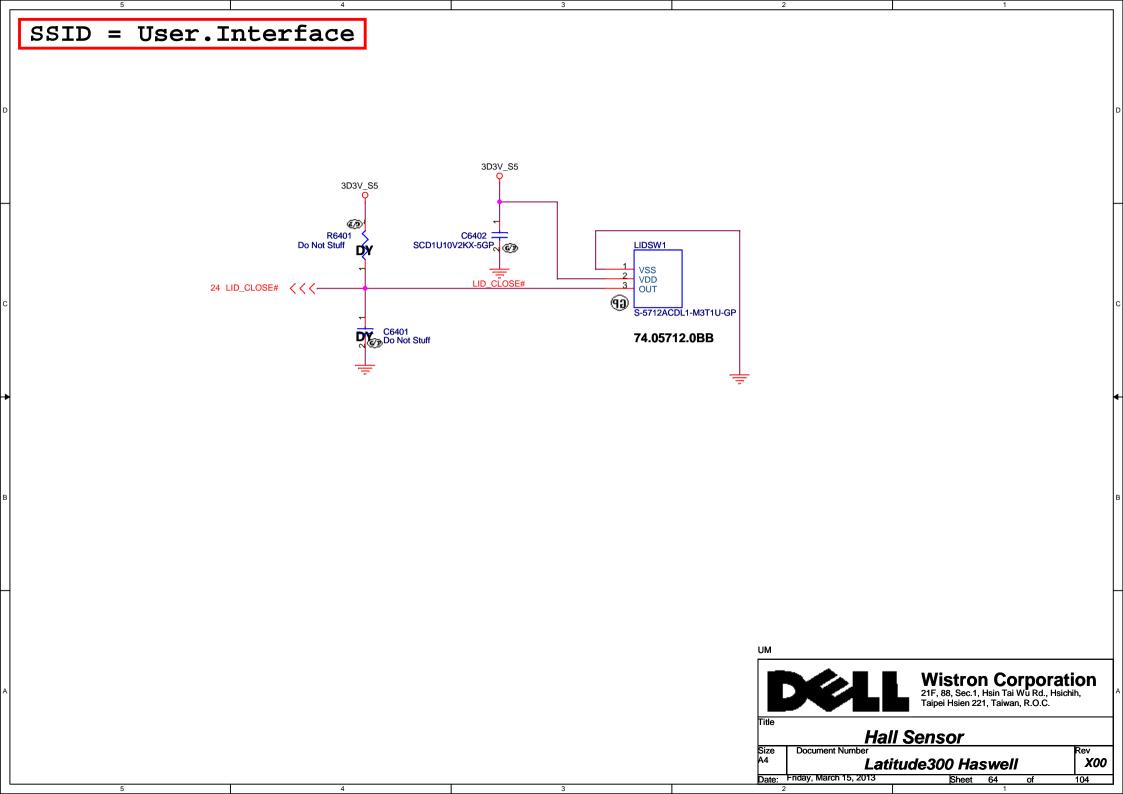


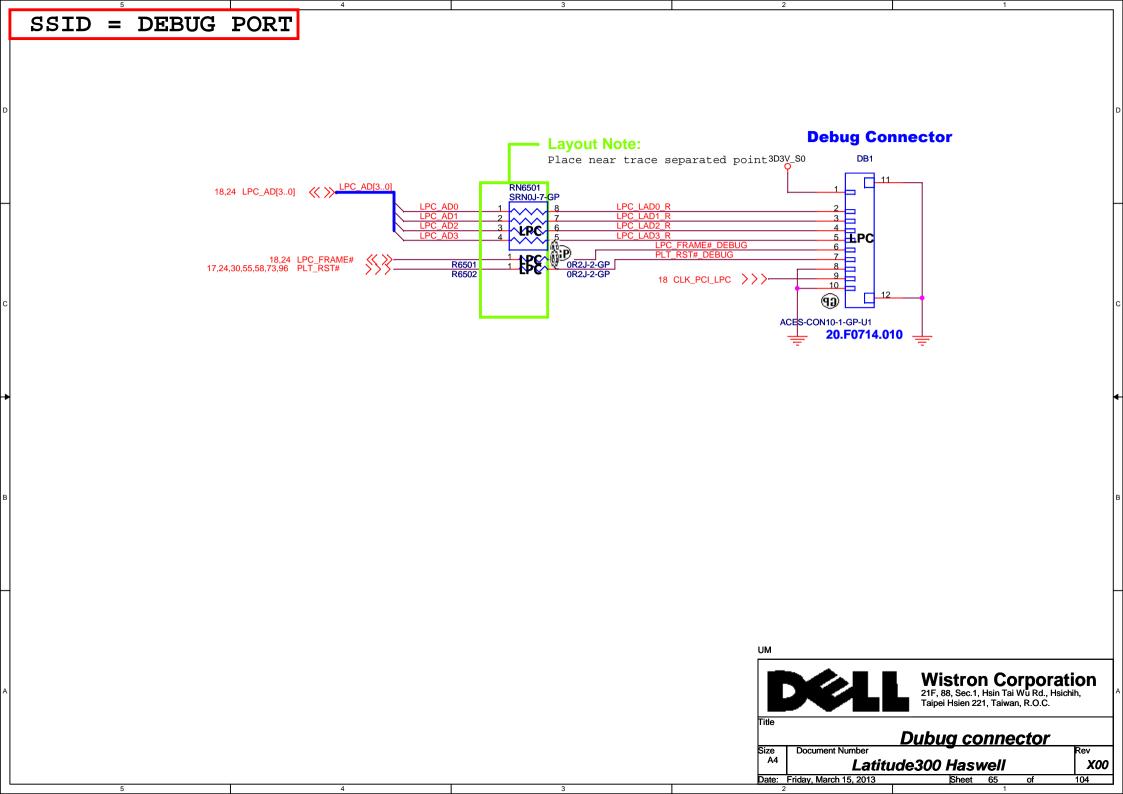


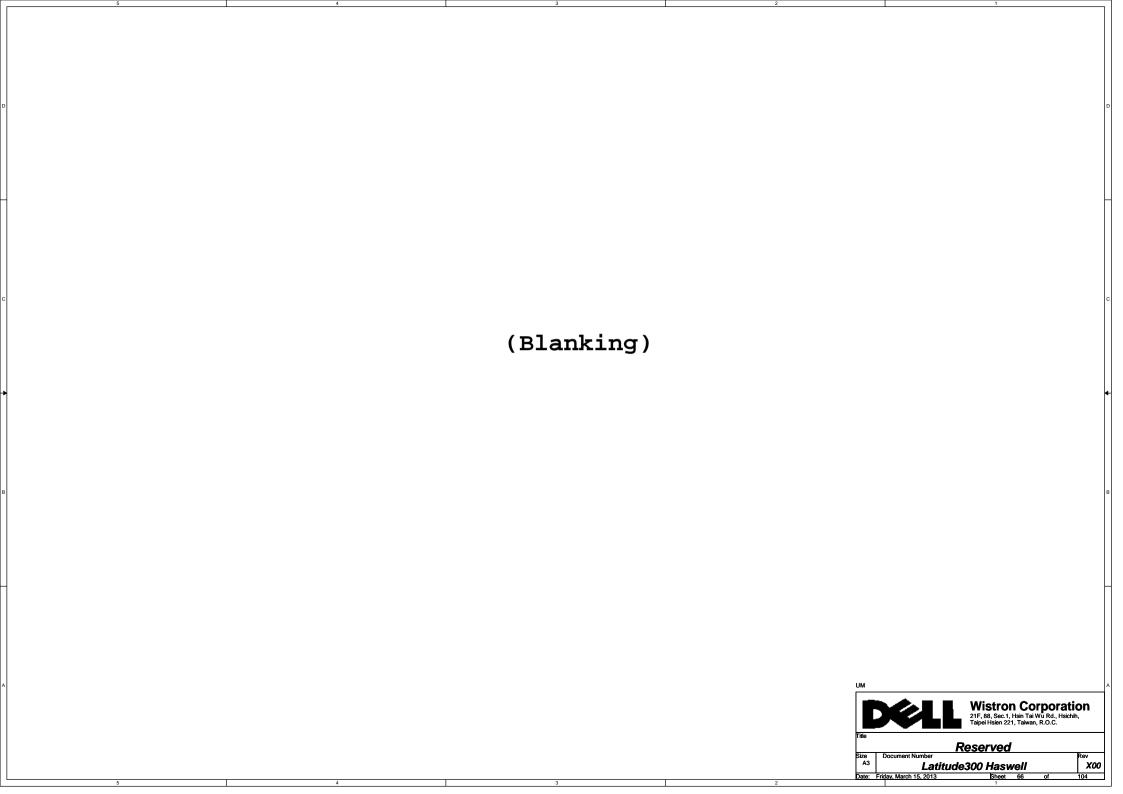


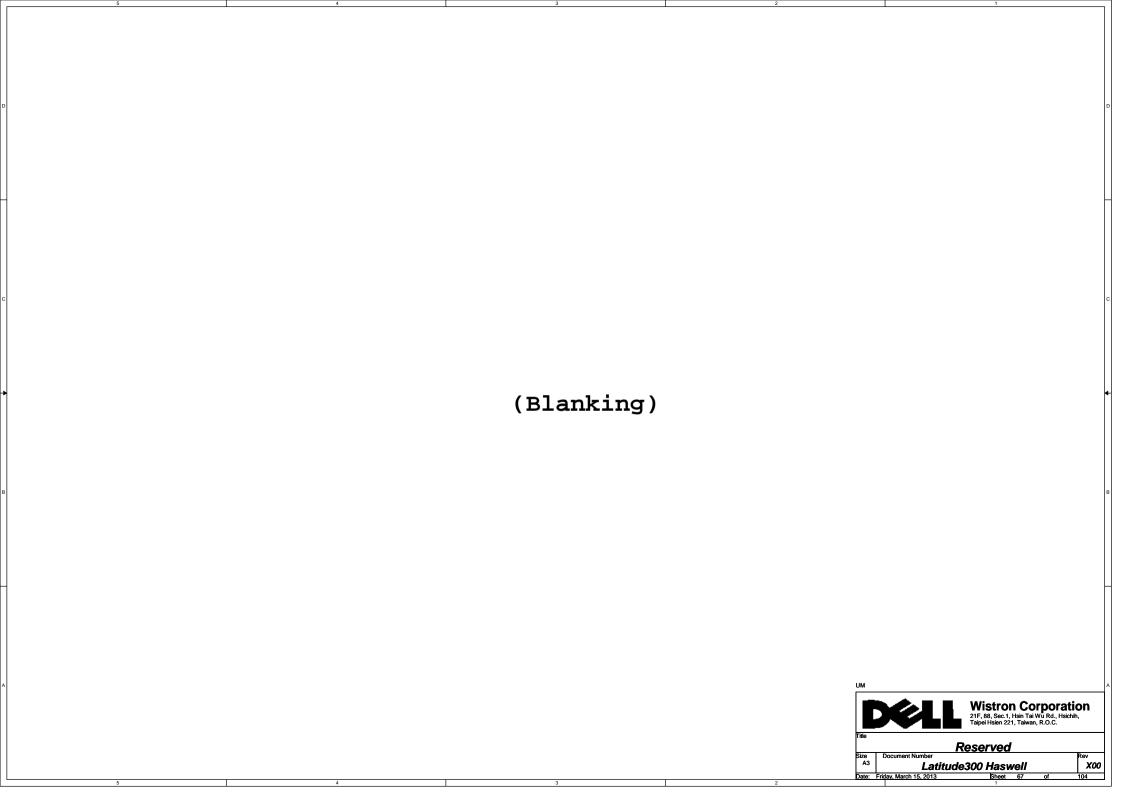




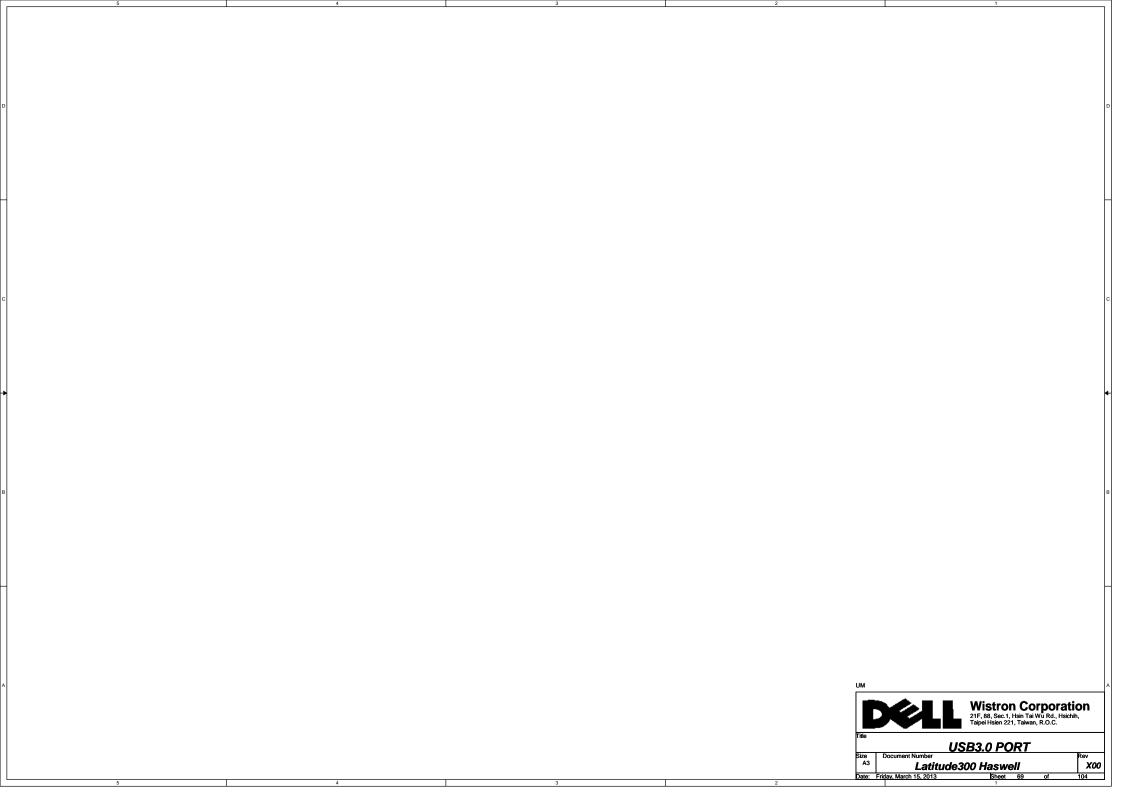


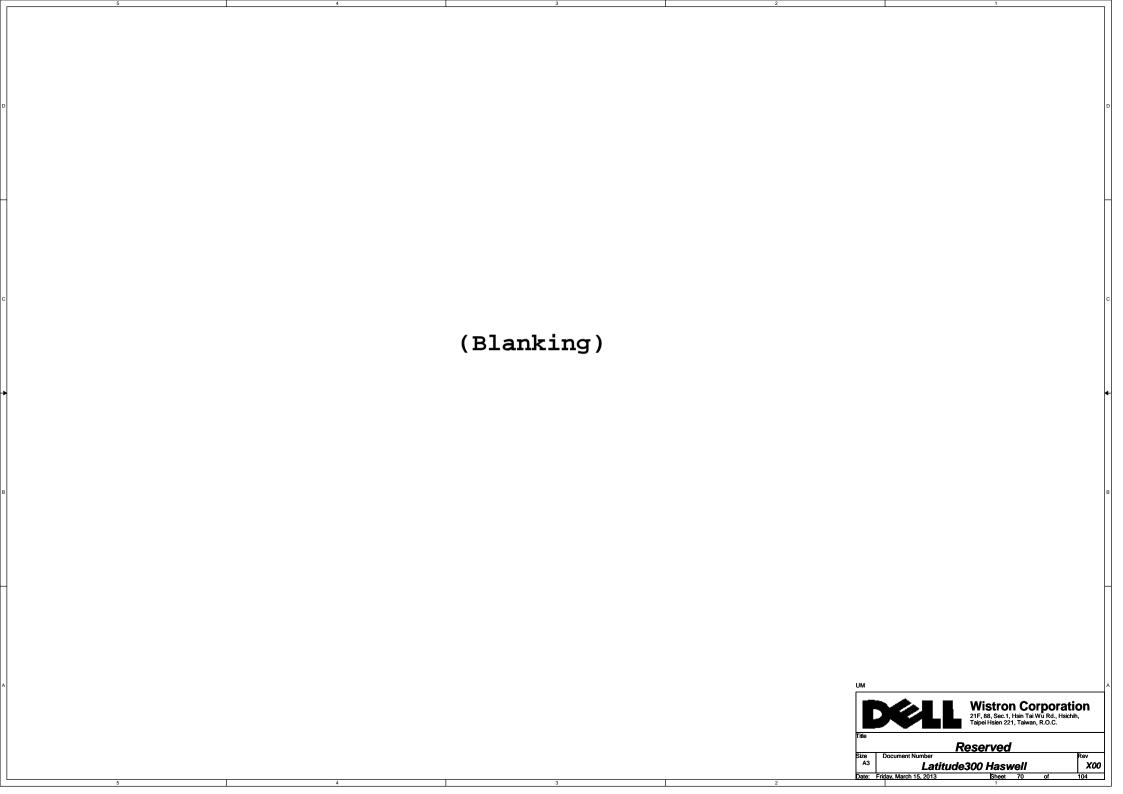


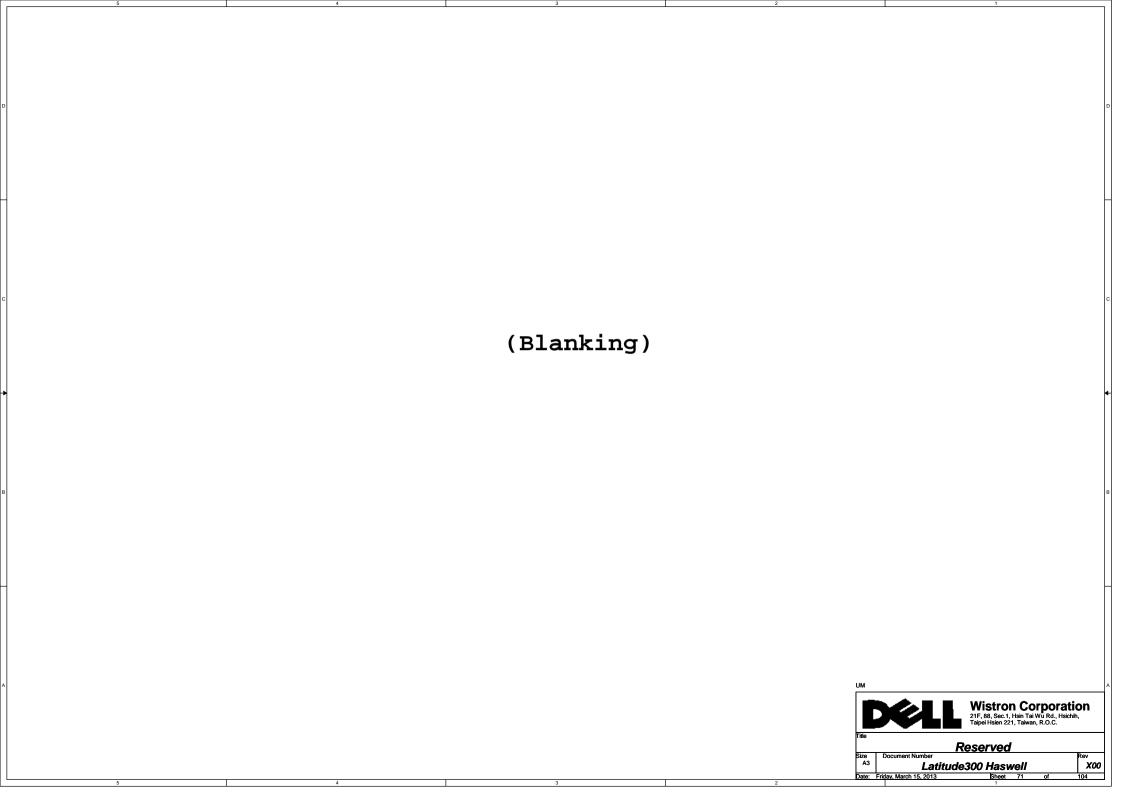


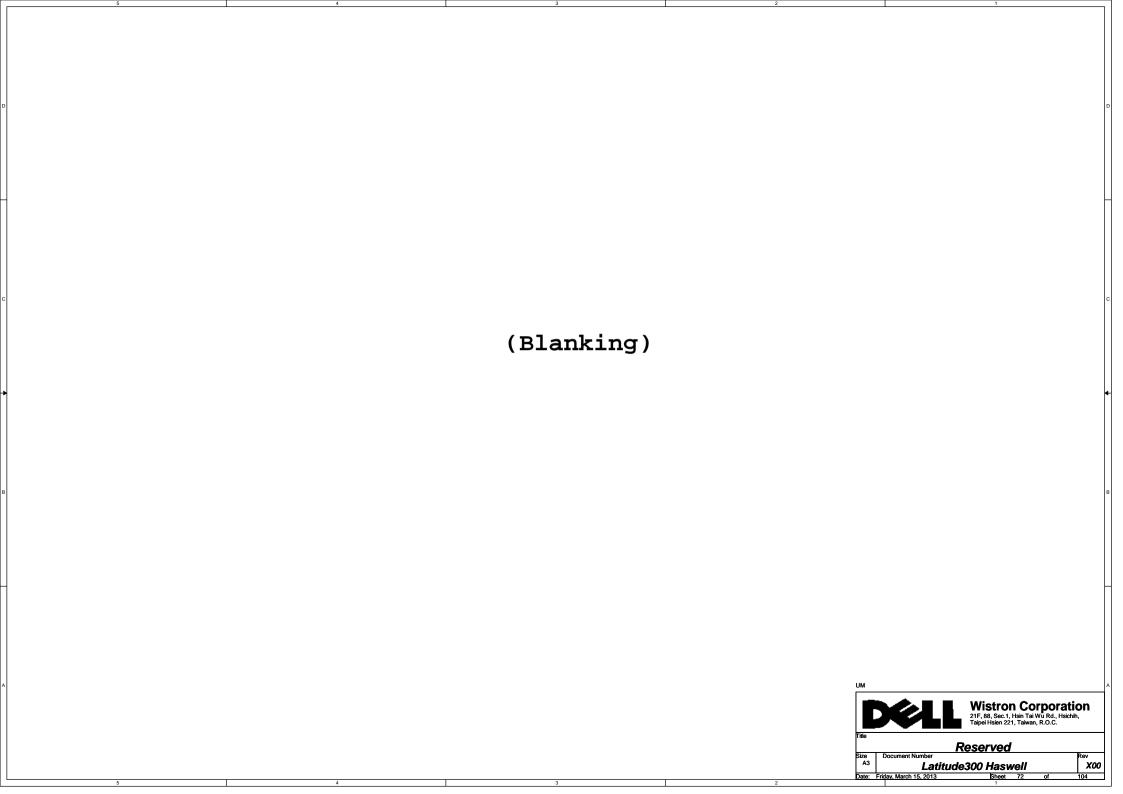


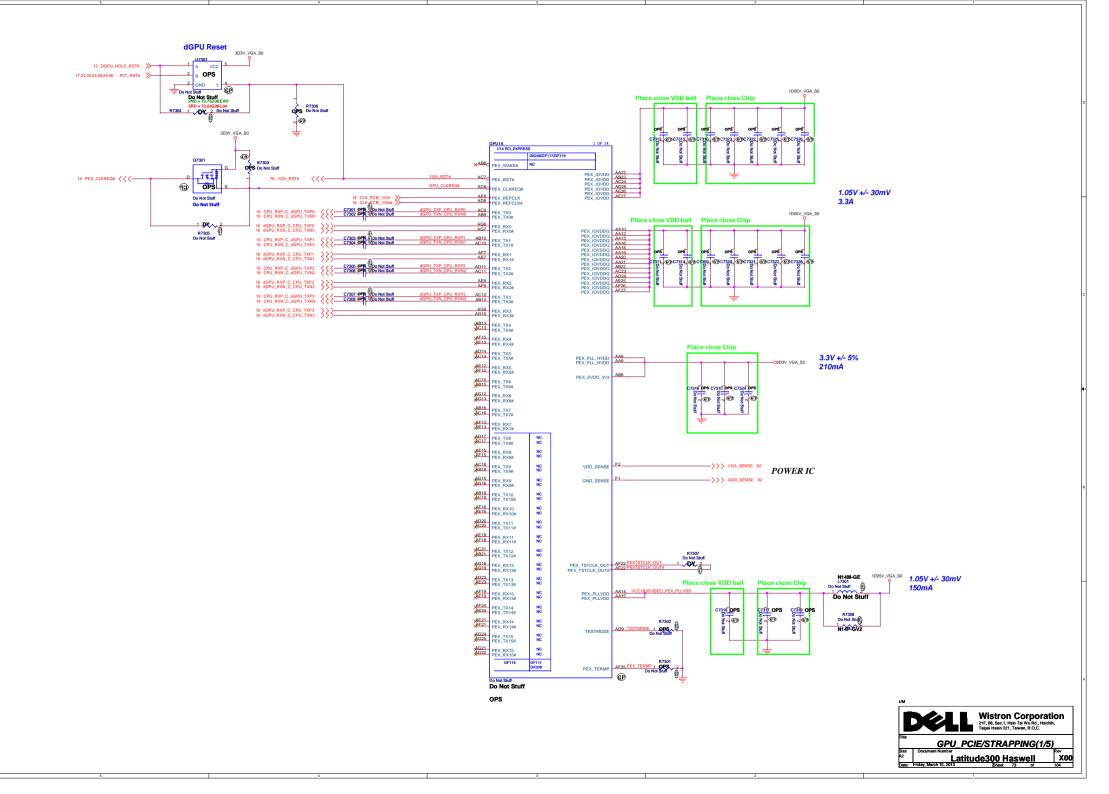
(Blanking) Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C. RESERVED t Number Latitude300 Haswell XOO



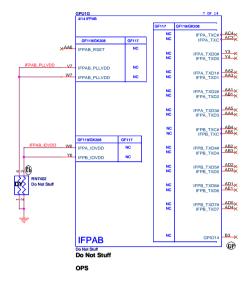




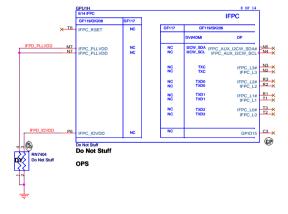


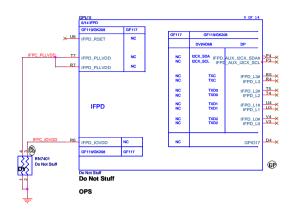


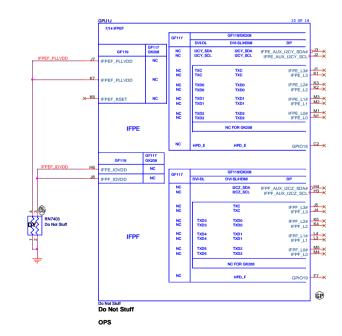
### **LVDS** Interface



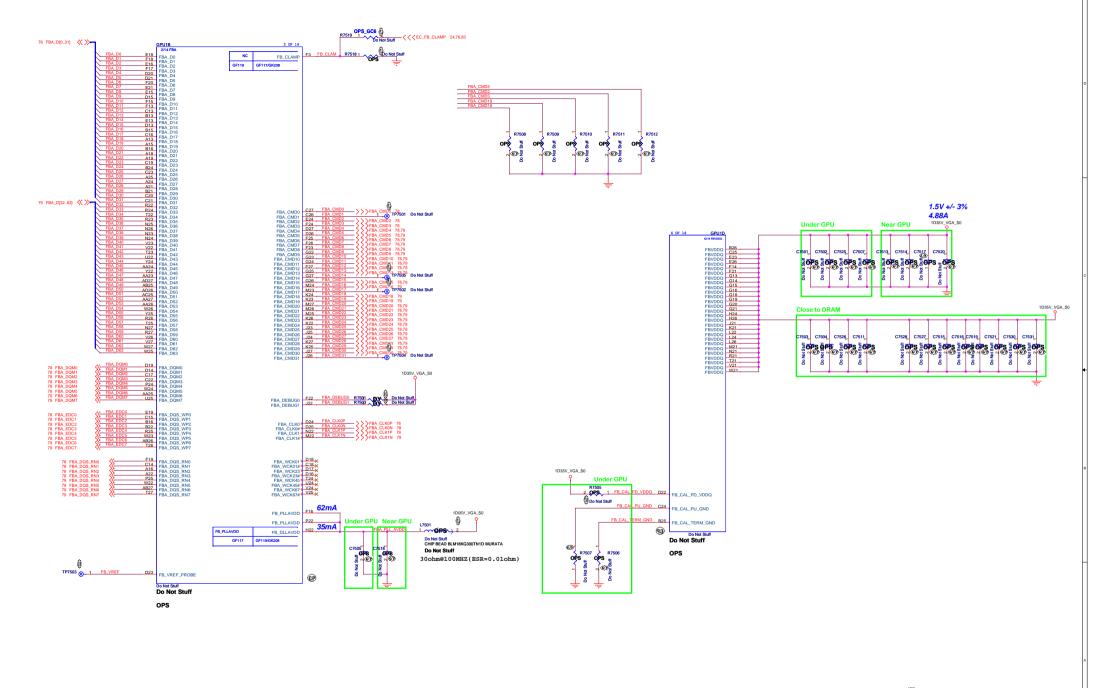
#### **HDMI** Interface













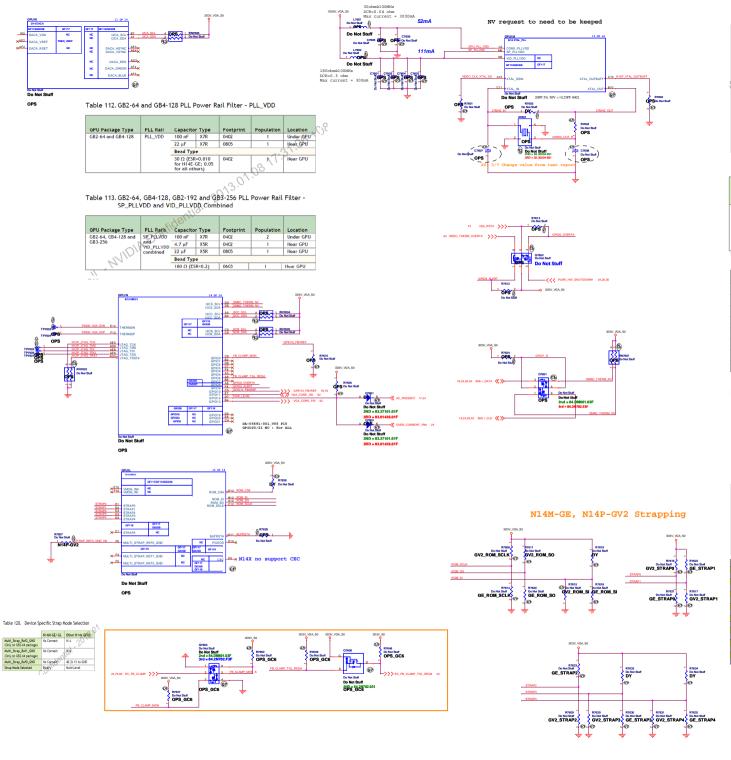


Table 1. N14M-GE/GL DDR3 Recommended Memories 128Mx16 Configuration

Con	ifiguration	Vendor	Strap	FBVDD/ FBVDDQ	Manufacturer Part Number	Max Speed CK (MHz)	Memory Date Code Minimum	Status
	M×16 DDR3	Micron	0x1	1.5 V/ 1.5 V	MT41J128M16JT- 093G:K	1000	1234	Production ready
25	Tou-Der				MT41J128M16JT- 107G:K	900	1150	Production ready
80		Samsung	0x5	1.5 V/ 1.5 V	K4W2G1646E-BC1A	1000	1204	Production ready
					K4W2G1646E-BC11	900	1204	Production ready
		Hynix	0x6	1.5V/ 1.5V	H5TQ2G63DFR-N0C	1000	N/A	Production ready
					H5TQ2G63DFR-11C	900	N/A	Production ready
			0xC	1.5V/ 1.5V	H5TC2G63FFR-11C	1000	N/A	Post-production candidate

Table 5. N14M-GS/LP and N14P-GV2 DDR3 Recommended Memories 256Mx16 Configuration

Configuration	Vendor	Strap	FBVDD/ FBVDDQ	Manufacturer Part Number	Max Speed CK (MHz)	Memory Date Code Minimum	Status
256Mx16 DDR3	Samsung	0x3	1.5 V/ 1.5 V	K4W4G1646B-HC11	900	N/A	Production ready
	Micron	0x1	1.5 V/ 1.5 V	MT41K256M16HA- 107G:E	900	N/A	Production ready
	Hynix	0x2	1.5V/ 1.5V	H5TC4G63AFR-11C	900	N/A	Production ready

Table 121. Resistance Mapping to Hex Values

Resistor Values	Pull-up to VDD33	Pull-down to GND
4.99 k	1000	0000
10.0 k	1001	0001
15.0 k	1010	0010
20.0 k	1011	0011
24.9 k	1100	0100
30.1 k	1101	0101
34.8 k	1110	0110
45.3 k	1111	0111

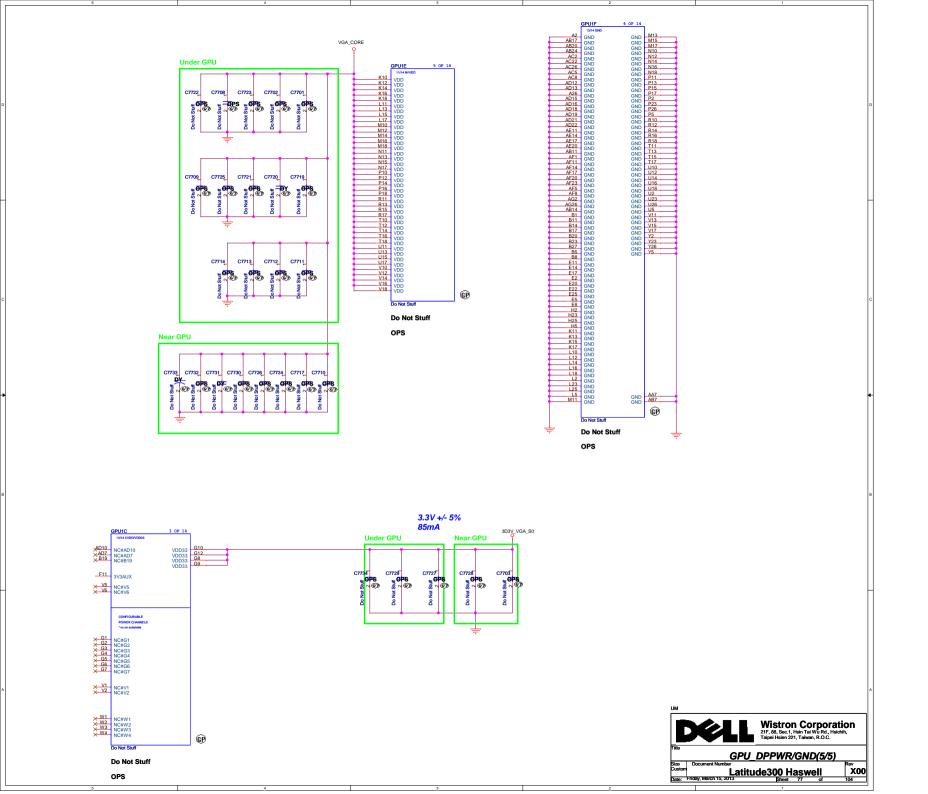
Table 122 Binary Strap Mode Mapping

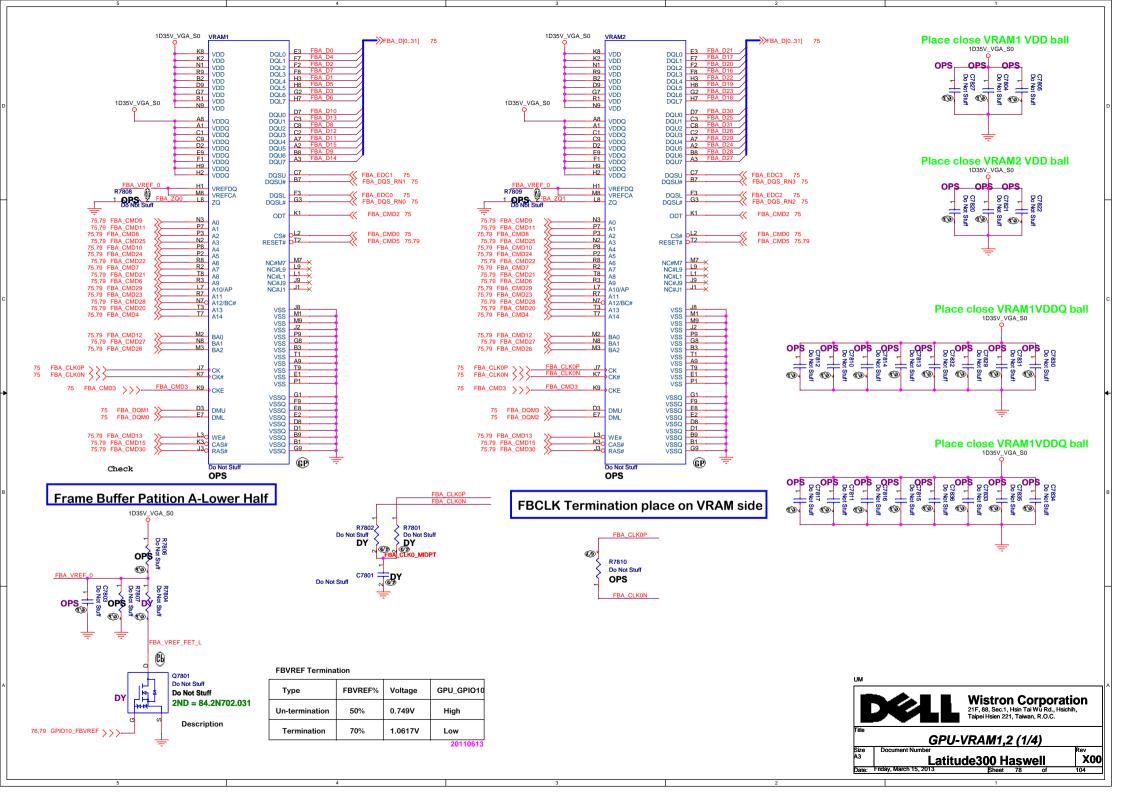
Strap Pin Name	Strap Mapping	Resistance	Polarity	
ROM_SCLK	SMB_ALT_ADDR	10k Ω	Pull-down to GND	
ROM_SI	SUB_VENDOR	10k Ω	Pull-up to 3V3 if VBIOS ROM exists Pull-down to GND if no VBIOS ROM	
ROM_SO	VGA_DEVICE	10k Ω	Pull-down to GND (no display)	
STRAP0	RAM_CFG[0]	10k Ω	See Note below	
STRAP1	RAM_CFG[1]	10k Ω	See Note below	
STRAPZ	RAM_CFG[2]	10k Ω	See Note below	
STRAP3	RAM_CFG[3]	10k Ω	See Note below	
STRAP4	PCIE_MAX_SPEED	10kΩ × 0	Pull-down to GND	

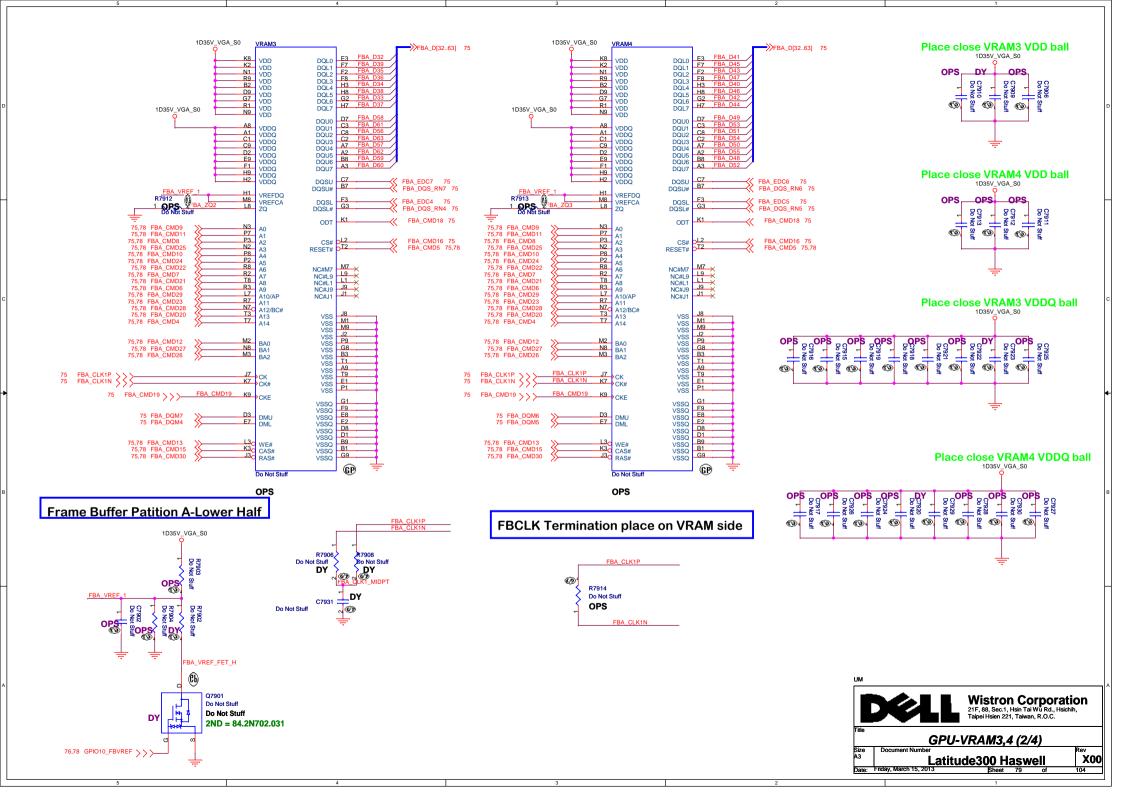
	N14M-LP	N14M-GS	N14P-GV	N14P-GV2
Chip Part #	GK208-640	GK208-630	GK208-650	GK208-632
	(Small package)	(Small package)	(Small package)	(Small package)
	GK208-740	GK208-730	GK208-750	GK208-732
	(Big package)	(Big package)	(Big package)	(Big package)
Device ID	0x1291	0x1290	0x1294	0x1292

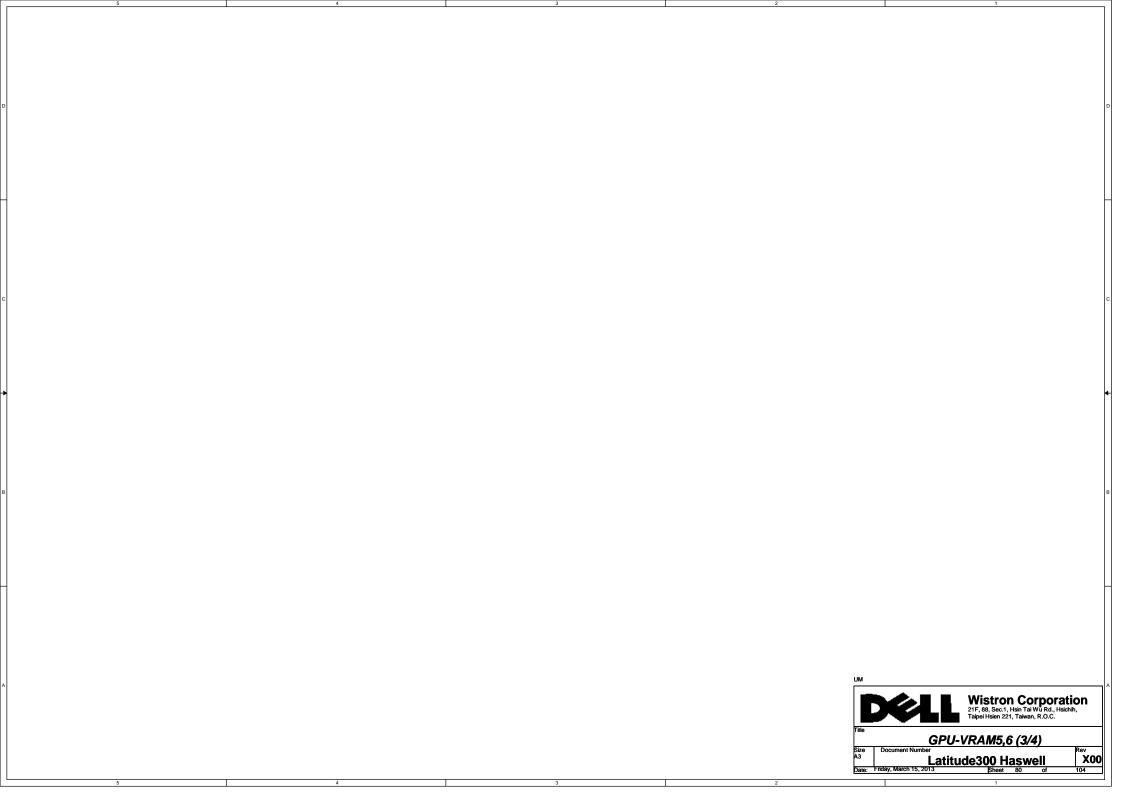
hit#2	Strap Pin Nese Logical strapping name bit(3)	ngical strapping ame bit#2	Logical strapping name bit#1	Logical strapping name bit(0)	
SUB, V	ROM_SCLK PCL_DEVID[4]	SUB_VENDOR	PCI_DEVID[6]	PEX.PLL.EN_TER.M	
	1		0		
RANG	RON_SE RANGEG(E)	RANGEG(2)	RANGEG[2]	RANGEG(8)	- I
	0	0	1	1	
FB	ROM,SO FRES	FB(0)	SMB_ALT_ADDR	VGA_DEVICE	
	1				SK ohm pull-up
USE	STRAPE USER[3]	USER[2]	USER[1]	USER(II)	The second second
	- 1		- 1		45K ohm pull-up
BGBO_PA	STRAP1 2030_PADGFG[3]	SGRO_PADOFG(2)	\$GEO_PADOFG[1]	9G30_PADGEG(8)	
- 1					SK ohm pull-down
PCI_DE	STRAP2 PCLDEVID[1]	PCI_DEVID[2]	PCI_DEVID[1]	PCI_DEV30(8)	1
- (	0	0	1	0	
SOR2_E	STRAP1 SORI_EXPOSED	SOR2_EXPOSED	SORT_EXPOSED	SORO_EXPOSED	
					SK ohm pull-down
SPEED,C	STRAP4 RESERVED	POLSPEED_CHANGE_GEN3	POSE_MAX_SPEED	DF_PLL_VDD33V	
		-	1	1	

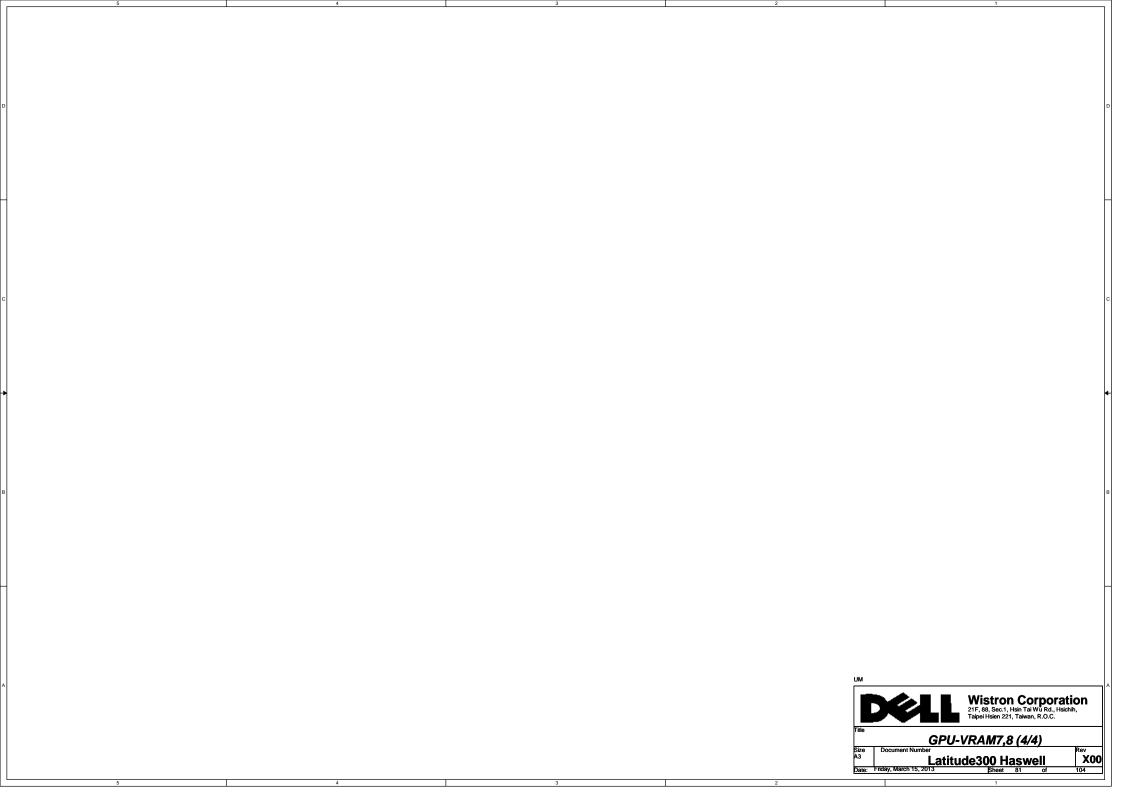


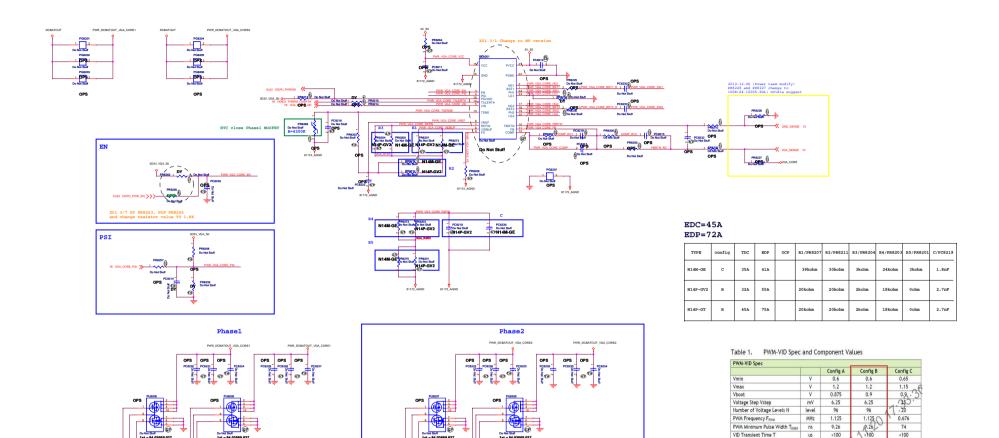












I/P cap: 10U 25V K0805 X5R/ 78:10622.51L M05: 01: Id=10A, Rdson=9.8-13.2 mohm ; 02: Id=17A, Rdson=3.6-5.2mohm 84.03669.037 Inductor: CHIP CHOKE 0.22UH PCM8063T-R22MS 2,5-3mohm Imat =34Arms 68.R2210.20C O/P cap: CHIP CAP POL 330U 2.5V M 6.3\*4.5 2.3Arms Matauti/77.53371.18L

OPS Suff

I/P cap: 10U 25V K0805 X5R/ 78.10622.51L MOS: Q1: Id=17A, Rdson=3.6-5.2mchm 84.03669.037 Inductor: CHIP CORKS 0.23MC PC086578-252802.5.5-mchm Isat =34Arms 68.82210.20C O/P cap: CHIP CAP POL 330U 2.5V M 6.3\*4.5 2.3Arms Matsuti/77.53371.18L

OPS Staff



Component Value R1 (1%)

R2 (1%)

R3 (1%) R4 (1%)

R5 (1%)

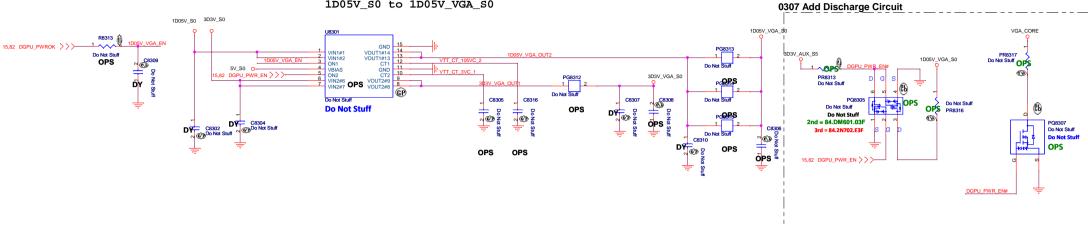
KO 1.5

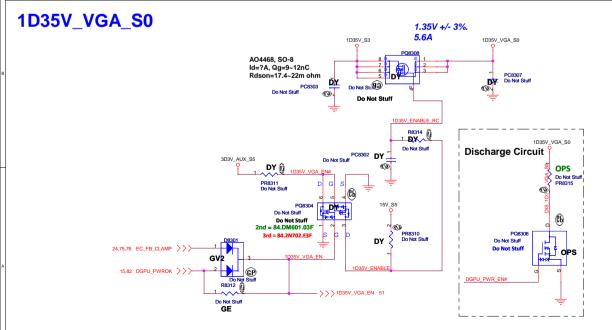
24

## 3D3V\_VGA\_S0 1D05V\_VGA\_S0

3D3V\_VGA\_S0 should ramp-up before VGA\_Core VGA\_Core should ramp-up before 1D5V\_VGA\_S0 1D35V\_VGA\_S0 should ramp-up before 1D05V\_VGA\_S0

3D3V\_S0 to 3D3V\_VGA\_S0 1D05V\_S0 to 1D05V\_VGA\_S0

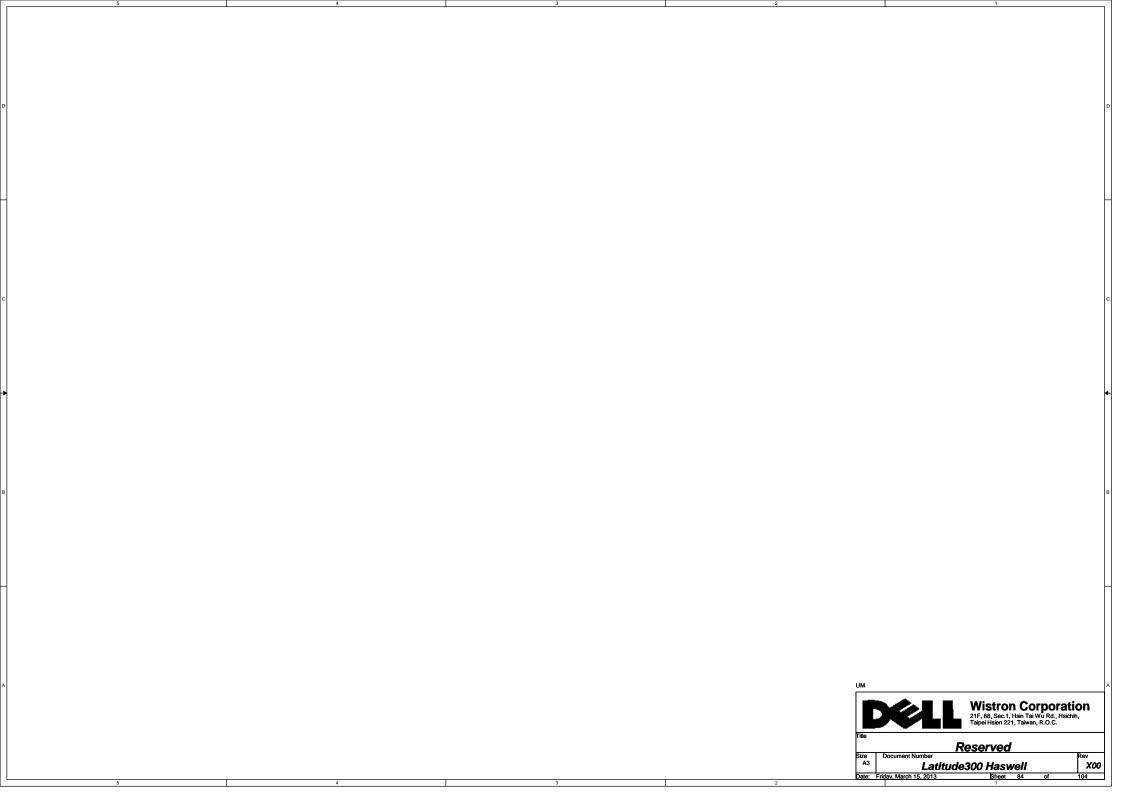


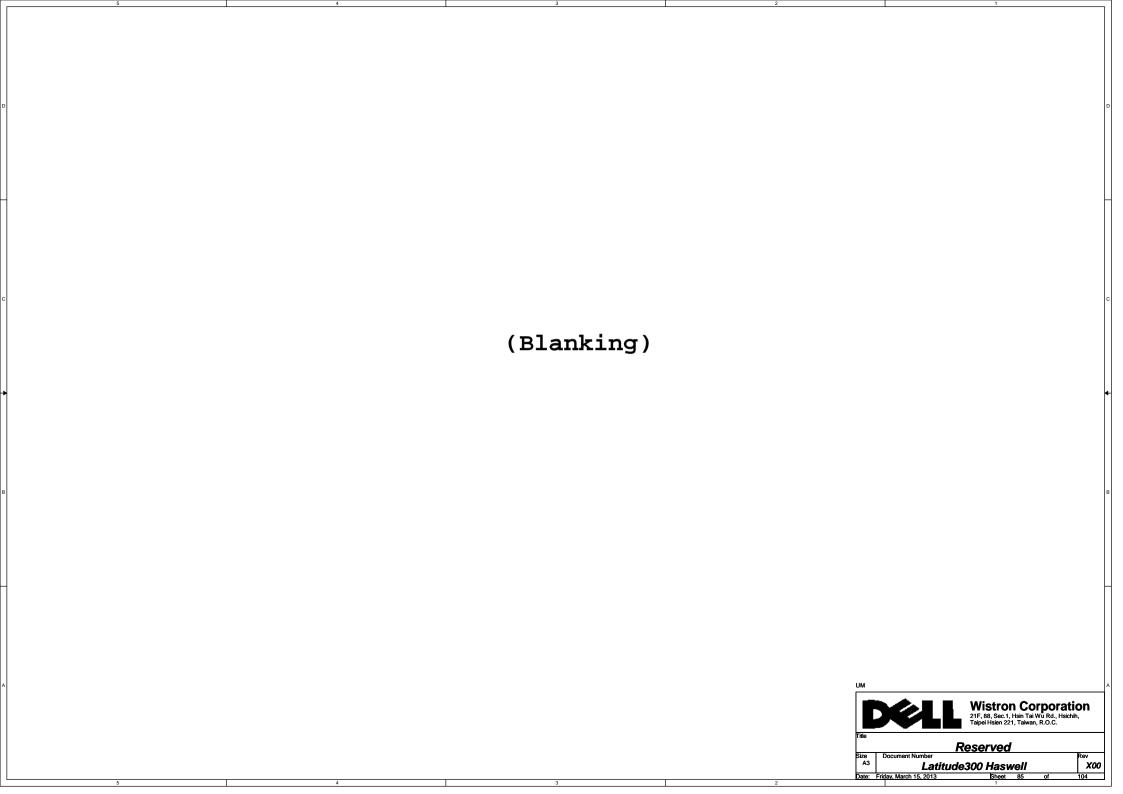


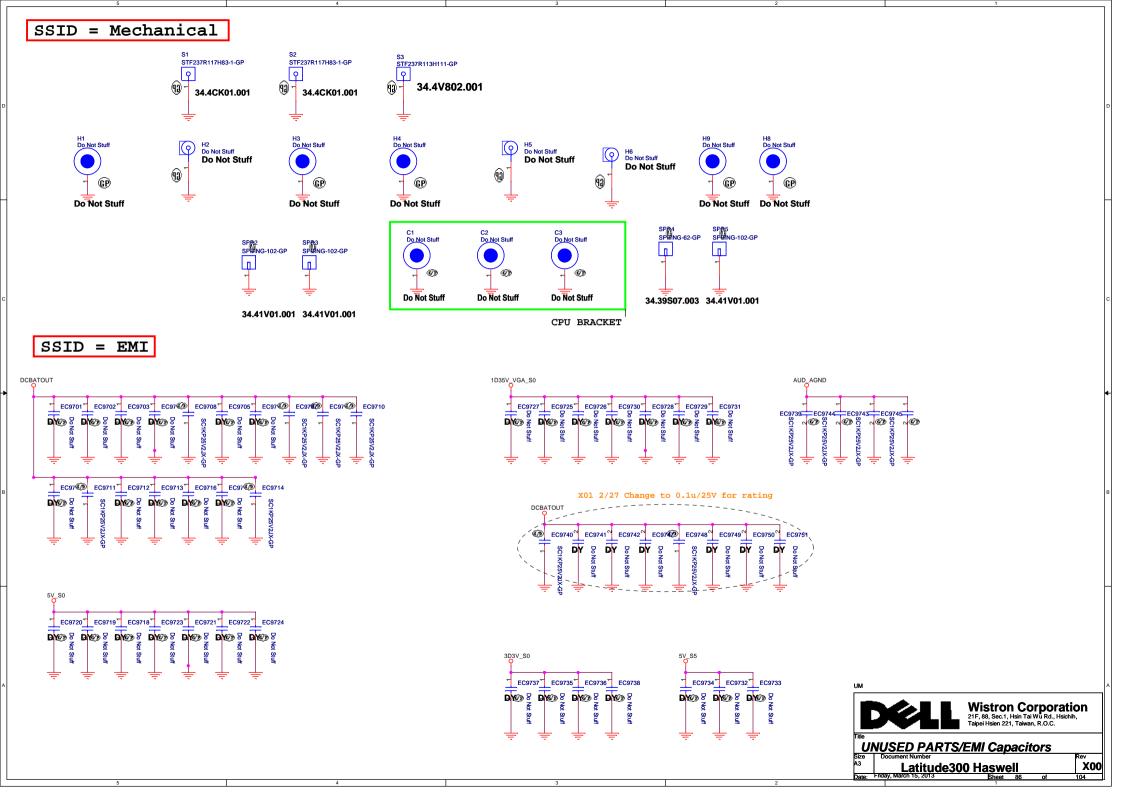
	Rise Time (μs) 10% - 90%, COUT = 0.1μF @ VIN; VOUT=0 ohm load										
	Typical values @ 25°C, 25V X7R 10% ceramic cap										
CTx (pF)	5V	3.3V	1.8V	1.5V	1.2V	1.05V	IV	0.8V			
0	107	72	46	41	36	34	33	29			
220	425	276	146	122	103	91	88	74			
270	489	316	172	139	121	107	104	84			
470	774	487	272	224	181	159	154	123			
680	1108	708	375	317	242	221	213	168			
1000	1561	1007	546	441	364	314	299	234			
2200	3600	2289	1240	1019	817	681	665	539			
4700	7757	5092	2674	2203	1808	1592	1516	1177			
10000	15700	10310	5601	4659	3674	3401	3197	2562			

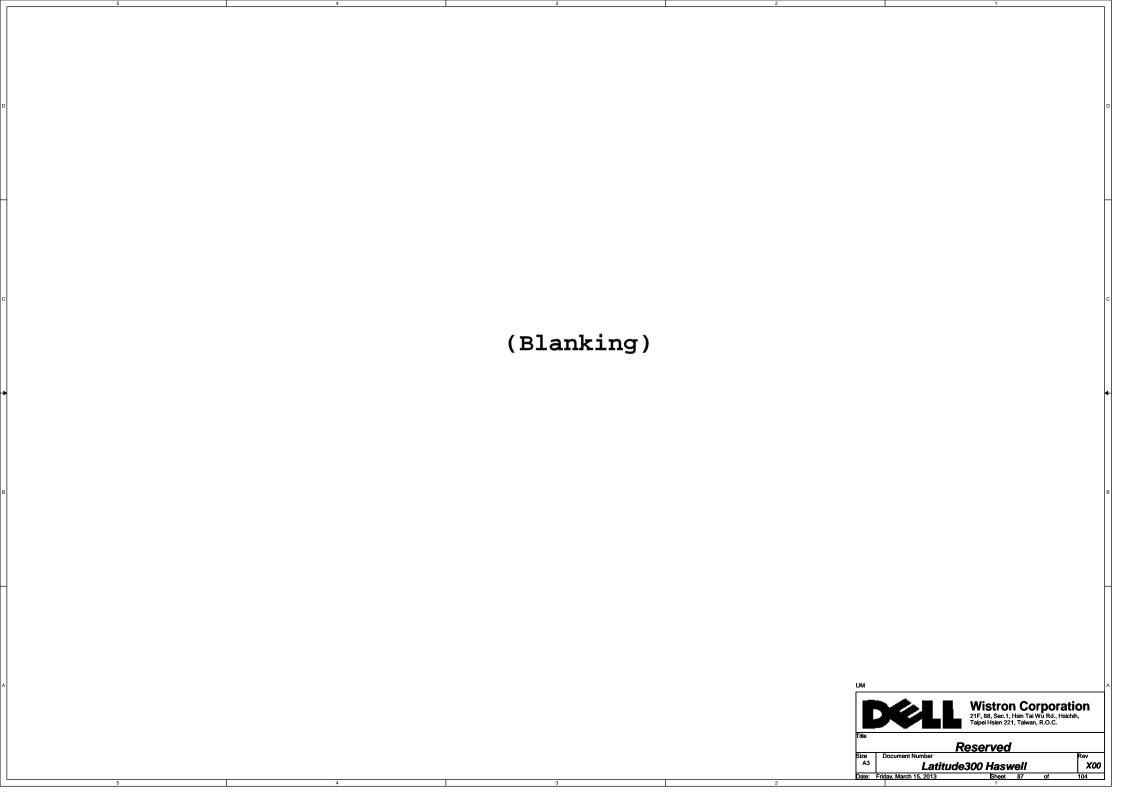
Table 1. Rise time vs. CTx value

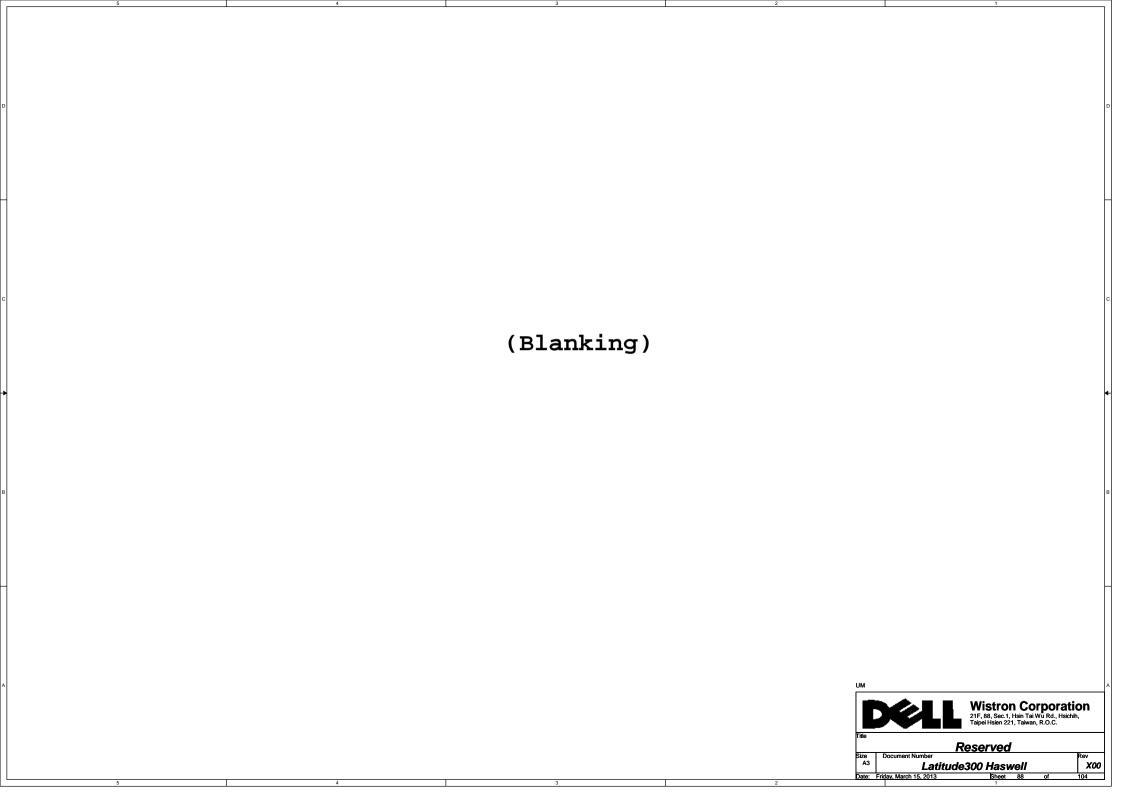


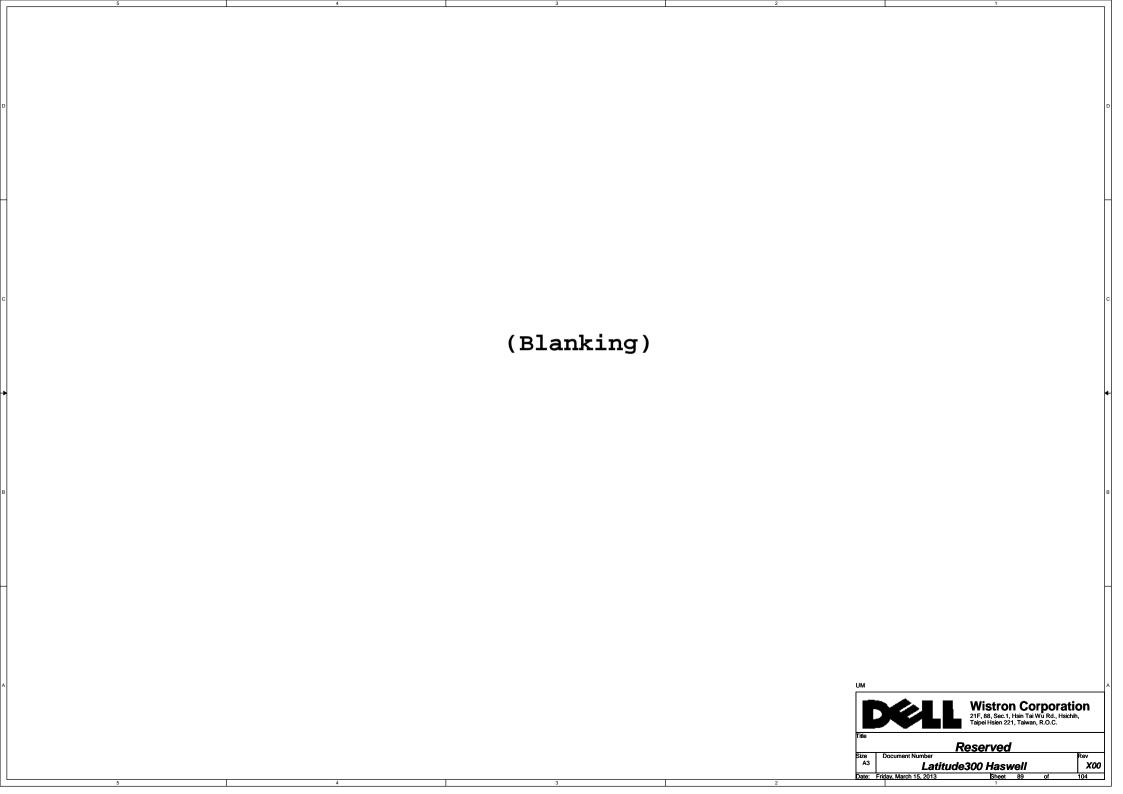




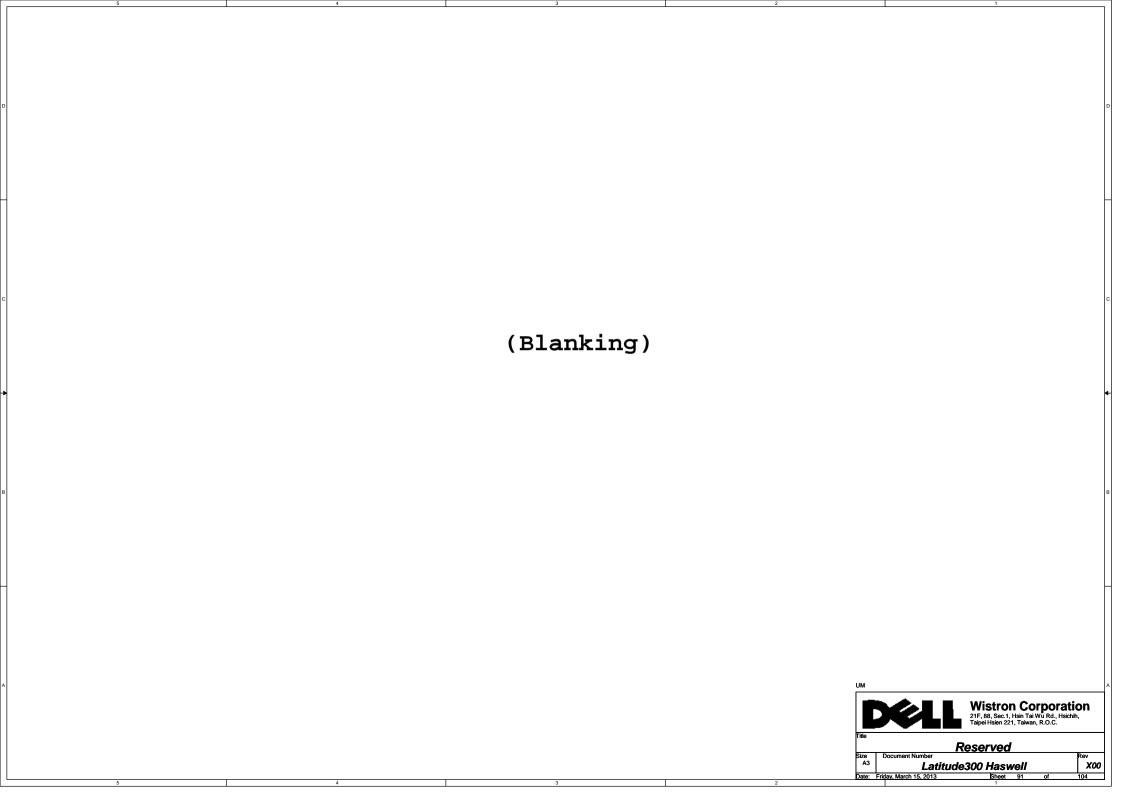


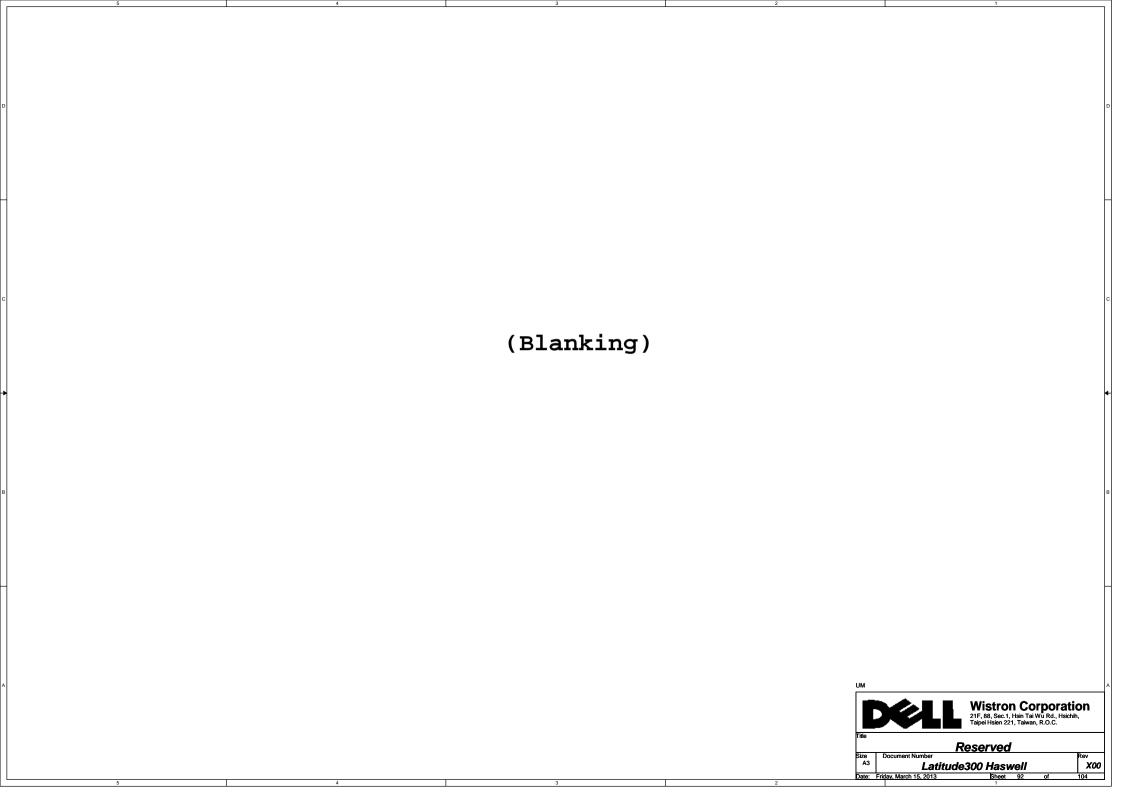


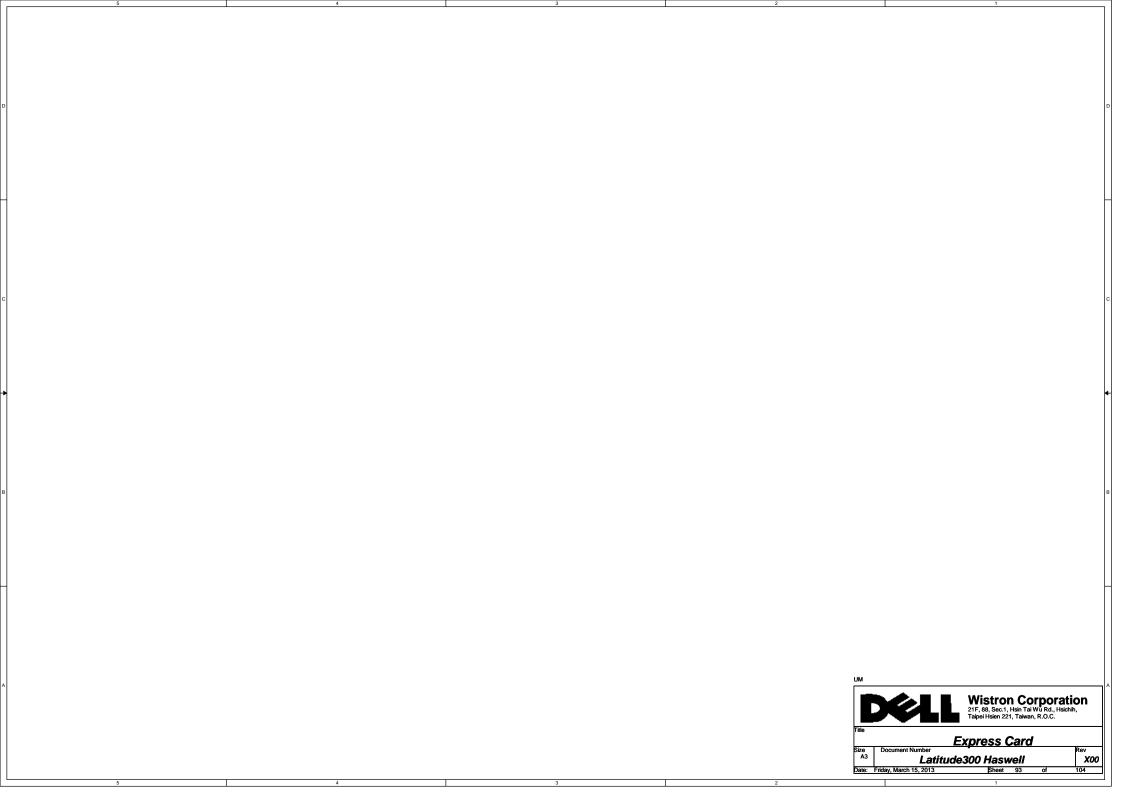




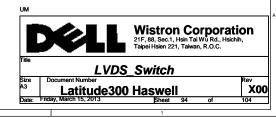
(Blanking) Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C. Free Fall Sensor A3 Latitude300 Haswell
Date: Friday, March 15, 2013 Sheet 90 XOO







(Blanking)



(Blanking)



SSID = XDP

7 H\_VCCST\_PWRGD >>

7 PWR DEBUG

17,24 SYS PWROK

18 PCIE\_CLK\_XDP\_P >> 18 PCIE\_CLK\_XDP\_N >>

17 XDP\_DBRESET# <

XDP\_TCLK >>>

Do Not Stuff

17,24,30,55,58,65,73 PLT\_RST# >>> Do Not Stuff 2 1R9602

C9602

17,24 PM PWRBTN#

R96031 XDP (II)

XDP

Do Not Stuff

XDP TCLK

2 Do Not Stuff

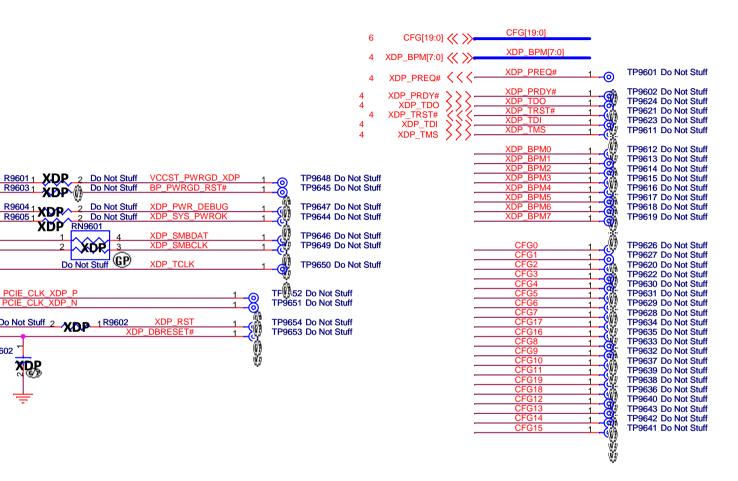
RN9601

XDR

Do Not Stuff GP

R9604 1 XDP^

### **CPU XDP**





# Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,

Taipei Hsien 221, Taiwan, R.O.C.

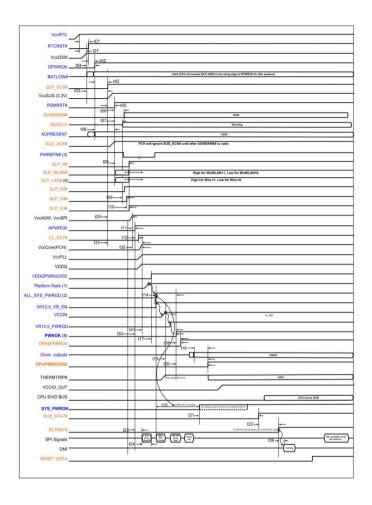
**TOUCH PANEL** 

Document Number Date: Friday, March 15, 2013 Sheet 96

Rev

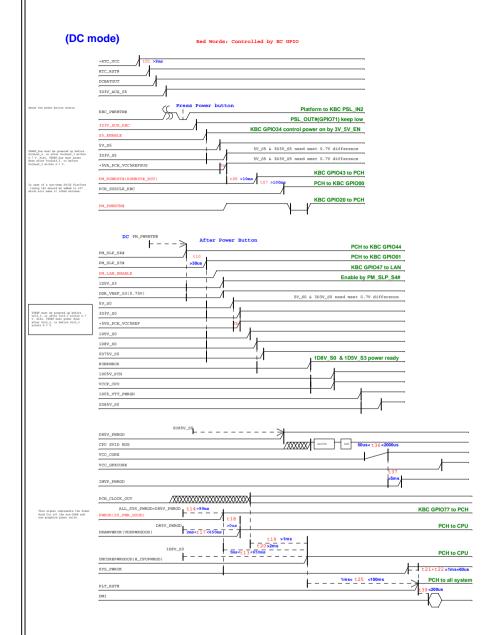
X00 104

## Shark Bay Platform Power Sequence



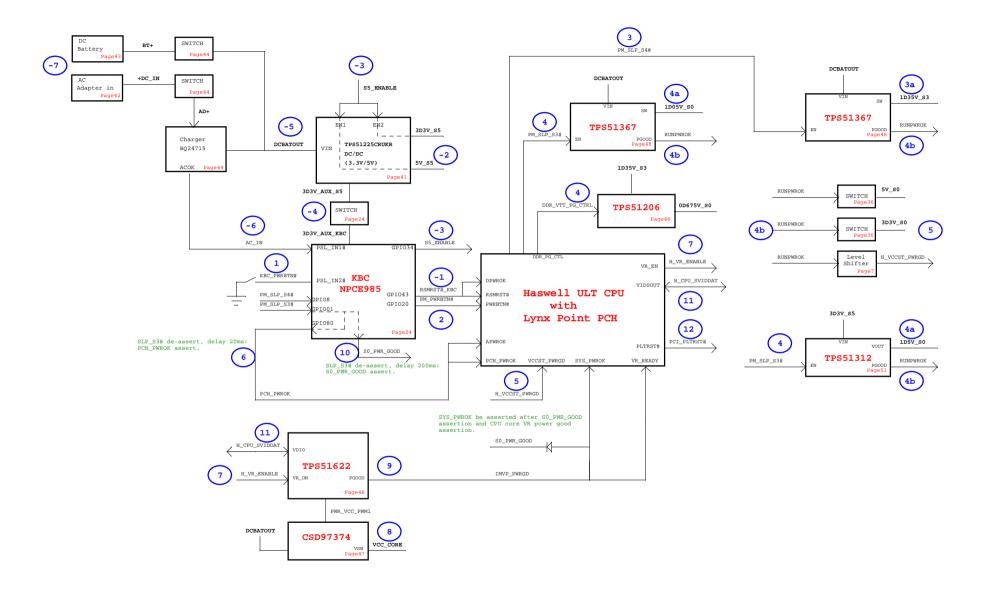
#### N14P-GT Power-Up/Down Sequence



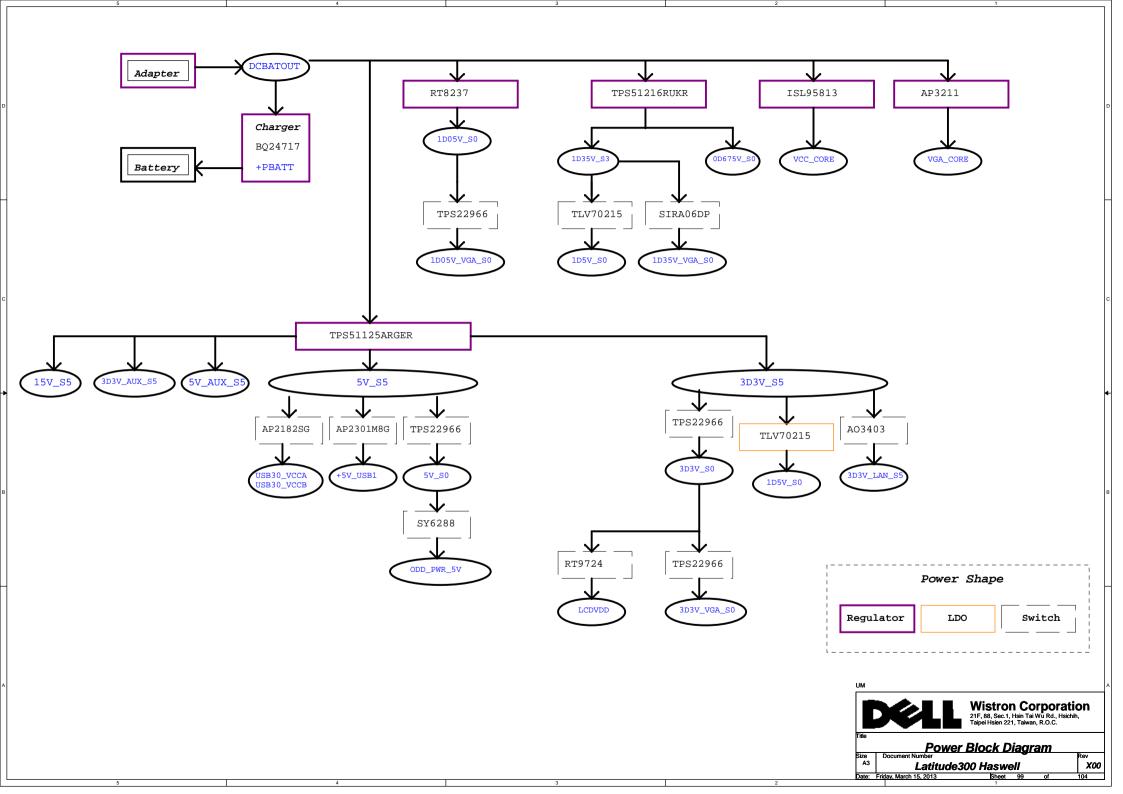


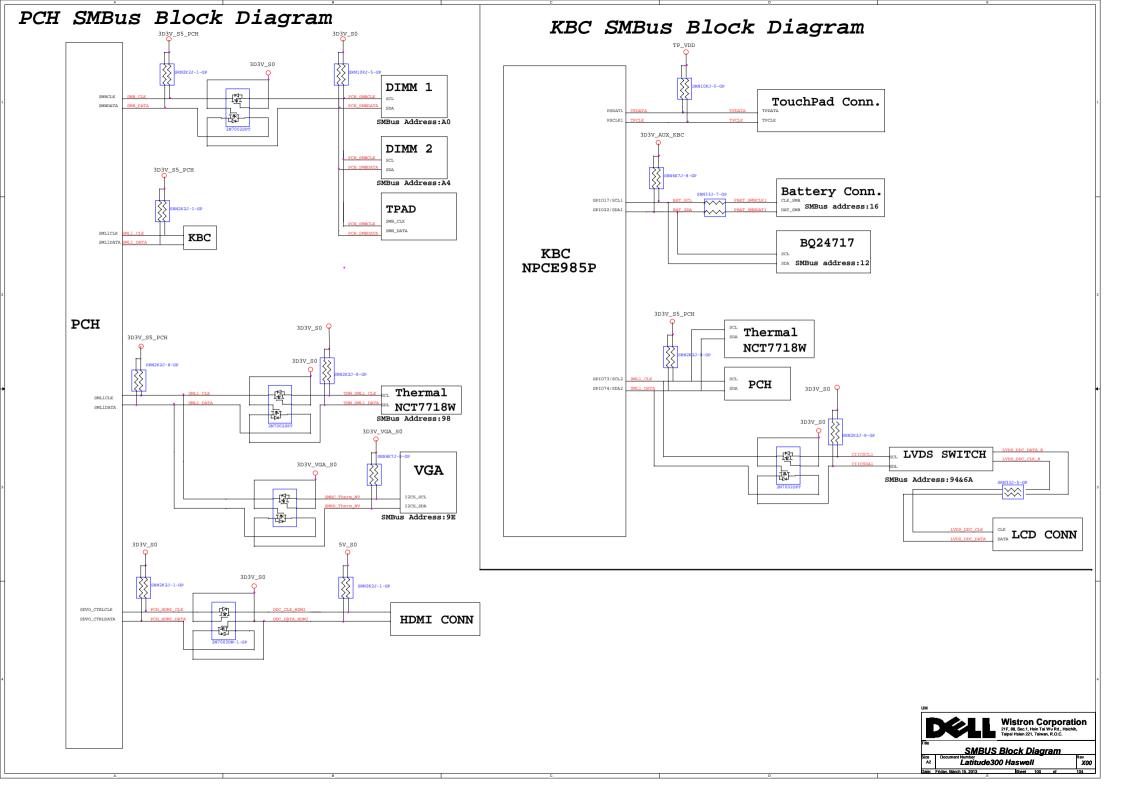


## Wistron SHARK BAY POWER UP SEQUENCE DIAGRAM

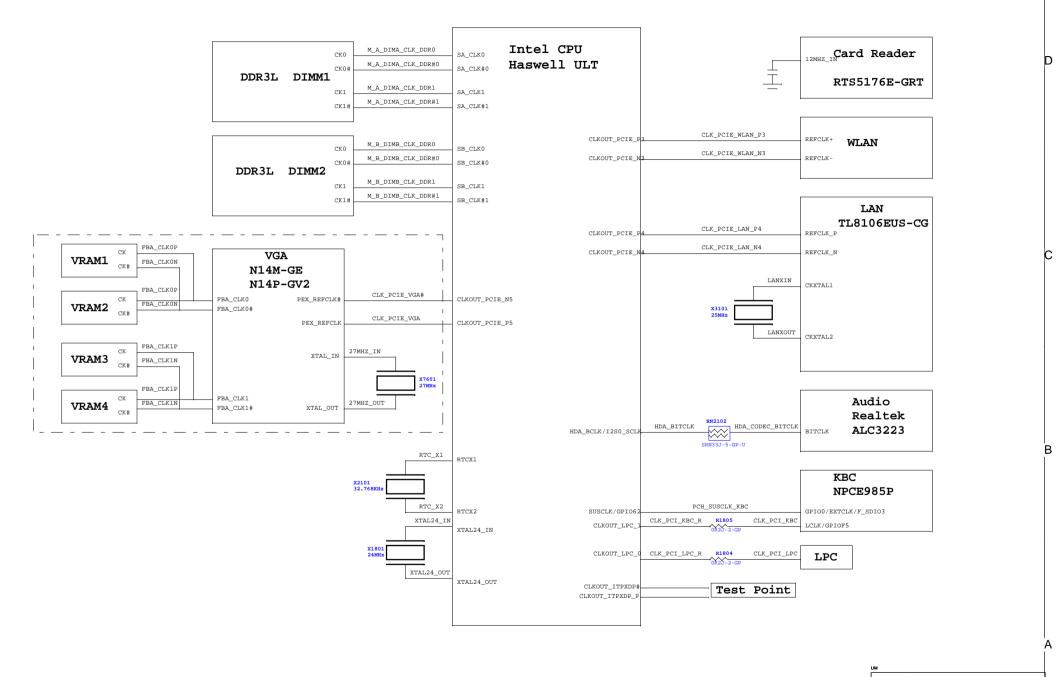






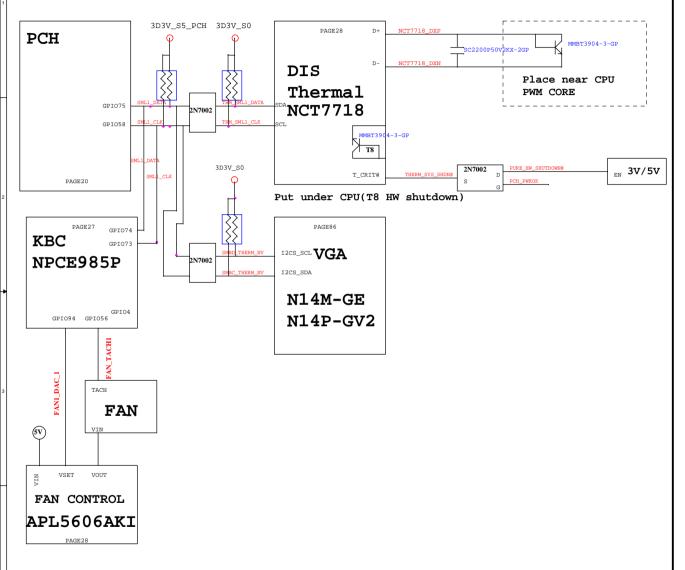


## OAK Haswell CLK Block Diagram

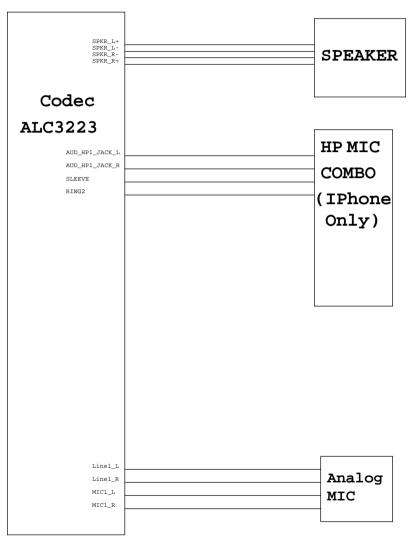


| Wistron Corporation | 21F, 88, 8e.1, 14en Tal Will MR.4, Haddin, Taipe Halen Zi, Taken, R. 10C. | | Taipe Halen Zi, Taken, R. 10C. | Taipe Halen Zi, Taipe Halen

# Thermal Block Diagram



# Audio Block Diagram





Change notes -										
IJī	DATE	VERSON	DATE	Page	Modify List	OWNER				
		X01	2/26	17	XDP_DBRESET# 10K to 3.3V	EE				
D	-		2/26	17	PCH_Wake# to 1K and DY R1705	EE	ı			
	-									
	-									
	-									
	-		,							
С	-		-							
•	-									
	-									
В	-						ı			
	-									
	-									
$\ $	}						-			
	-									
	}									
	-						UM			
А	-						·			
							Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wü Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
	-						Size Document Number Rev			
							A3			

